



# AMD A77E Fusion Controller Hub Databook

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## Revision History

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<b>Date</b>	<b>Revision</b>	<b>Change Description</b>
February 2014	3.01	Modified description in the Power and Ground Pin Descriptions table for VDDBT_RTC_G.
October 2013	3.00	Initial Release



# Chapter 1 Introduction

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The A77E FCH, code-named “Bolton-E4” is the third generation fusion controller hub (FCH) from AMD designed to deliver the quality and performance needed for ultimate high end computing, multitasking, and multimedia functionality on performance embedded platforms. The A77E FCH is referred to by its code name throughout this document.

Supporting AMD accelerated processing units (APUs), Bolton-E4 replaces the traditional two-chip approach with a new, single-chip architecture, reducing power consumption and improving system performance while reducing the overall chipset footprint. Bolton-E4 provides six SATA 6Gb/s ports and four USB 3.0 ports for expanded I/O connectivity.

## 1.1 Features of Bolton-E4

### Processors Supported

- Supports AMD Accelerated Processor Units (APUs)

### Unified Media Interface (UMI)

- 1-, 2-, or 4-lane UMI connecting the FCH with the APU
- Automatic detection of lane configuration on boot-up
- Dynamic lane width up/down configuration on detecting bandwidth requirement
- Supports transfer rate of 2.5 GT/s (2GB/s) or 5 GT/s (5GB/s) per lane
- Clock speed can be locked at 2.5 GHz for power saving

### PCI Express® 2.0 Controller

- Four-lane PCI Express (PCIe®) 2.0 interface, supporting up to four general purpose (GPP) devices. Supported configurations include:
  - 1x4
  - 2x2
  - 1x2 + 2x1
  - 4x1
- Supports L0s and L1 link power states for power saving

### USB 3.0/2.0/1.1 Host Controllers

- 2 xHCI (v.1.0), 3 OHCI, and 2 EHCI host controllers to support:
  - 4 USB 3.0 ports
  - 10 USB 2.0 ports
  - 2 dedicated USB 1.1 ports (for internal devices only)
- Supports xHCI 1.0 features + debug port
- Supports OHCI legacy keyboard/mouse

- Supports wake function in S3 and S4
- Supports USB debug port for EHCI controllers
- Supports port disable with individual control

### SMBus Controller

- Two SMBus controllers – one is multiplexed on three (3) pairs of SMBus signals while the other controller is dedicated for ASF or a Synaptics InterTouch Touchpad device
- Supports SMBALERT # signal

### Interrupt Controller

- Supports IOAPIC/X-IO APIC mode for 24 channels of interrupts
- Supports 8259 legacy mode for 15 interrupts
- Supports programmable level/edge triggering on each channels
- Supports serial interrupt on quiet and continuous mode

### DMA Controller

- Two cascaded 8237 DMA controllers
- Supports LPC DMA

### LPC Host Bus Controller

- Supports LPC-based super I/O and flash devices
- Three programmable memory windows
- Supports two master/DMA devices
- Supports TPM version 1.1/1.2 devices for enhanced security
- Supports SPI devices at speed up to 66MHz
- Supports a maximum SPI ROM size of 16MB
- Supports single, dual, and quad data SPI



**SATA Controller**

- Supports six third-generation SATA ports with transfer rates up to 6 Gbit/s
- Supports SATA first-generation (up to 1.5 Gbit/s) and second-generation (up to 3.0 Gbit/s)-compliant devices
- Complies with SATA 3.0 specification
- Supports three modes of operation:
  - IDE emulation mode
  - AHCI 1.3 mode
- Any of the ports can be configured to a lower transfer rate of 3.0 or 1.5 Gbit/s for power saving
- Any of the SATA ports can be configured to support second generation e-SATA port (compatible with devices running at 3 Gbit/s and 1.5 Gbit/s)
- AHCI Mode supporting the following features:
  - DIPM (Device Initiated Power Management)
  - HIPM (Host Initiated Power Management)
  - Hot Plug detection and notification
  - NCQ (Native Command Queue) mode
  - FIS Based Switching Mode

**High Definition Audio**

- Four independent output streams (DMA)
- Four independent input streams (DMA)
- Multiple channels of audio output per stream
- Supports up to 4 codecs
- Up to 192kHz sample rate and 32-bit audio
- 64-bit addressing capability for DMA bus master and MSI
- Unified Audio Architecture (UAA) compatible
- HD Audio registers can be located anywhere in the 64-bit address space
- Supports 3.3V/1.5V dual-voltage interface for power saving

**Timers**

- 8254-compatible timer
- Microsoft® High Precision Event Timer (HPET)
- ACPI power management timer
- Watchdog timer
- AMD boot timer

**Real Time Clock (RTC)**

- 272-byte battery-backed CMOS RAM
- Hardware-supported century rollover
- Hardware-supported day-light saving feature
- RTC battery monitoring feature

**Power Management**

- ACPI specification 3.0 compliant power management schemes
- Supports processor C states
- Supports system S0, S3, S4, and S5 states
- Supports the S5 Plus power saving mode.
- Wakeup events for S3, S4, and S5 generated by:
  - Any GEVENT pins that are on the S5 domain
  - Any GPM pins that are on the S5 domain
  - USB (Note: Remote wake from S5 for USB is not supported by the operating systems' USB driver stacks)
  - HD modem
  - Power Button
  - Internal RTC wakeup
  - SMI Event

**Consumer IR**

- SMM support: generating SMI by power management events, bus transaction (IO, memory, or PCI configuration cycle) trapping, internal controllers, GPIO, timer, management message

- CLKRUN# support for PCI power management
- Low idle power
- Supports STPCLK# control
- ALPM (HIPM) on SATA
- DIPM on SATA

### Integrated Micro-Controller (IMC)

- 8051 microcontroller:
  - 4 Kbytes of data memory
  - 64 Kbytes base instruction plus expanded instruction (beyond 64 KB) support
  - Thirteen interrupts, 50 interrupt sources, 4 interrupt priority levels
- 33 MHz operation in S0 state, 16 MHz operation in system sleep state; option to stop clock when idle
- JTAG-based In-Circuit Emulator (ICE) or debugger
- Host I/O interface
- Four general purpose timers/counters
- Hibernation, Watchdog, and RTC timers
- Access to all FCH MMIO resources (e.g. PMIO, RTC, BIOS\_RAM registers)

### Consumer IR

- Media center infrared with wake from all states
- Two transmitters
- IR receiver and wideband learning receiver
- Fully compatible with Microsoft Windows® Vista® and Windows 7 Media Center

### Hardware Monitoring

- Fan control: IMC-based APU fan control via SB-TSI

### Integrated Clock Generator

- Provides 25 MHz, 14.3 MHz (frequency is 14.318 MHz on average; cycle-to-cycle variation can be between 14.2857 and 14.8148 MHz), and 48 MHz clocks
- Provides clocks for APU, external graphics, UMI, and nine general purpose PCIe devices

### VGA Translator

- Provides VGA translation function. Supports a maximum resolution of 1920x1600 at a refresh rate of 60 Hz.
- Auto monitor detection
- Automatic power down for VGA DAC when there is no monitor attached
- Driver can put the VGA DAC into low power mode when a VGA monitor is attached but inactive.

### SD Flash Controller

- Clock speed up to 50 MHz (high-speed mode)
- Supports both standard (SD) and high-capacity (SDHC) formats
- Supports 1 and 4-bit modes
- For the SDHC format:
  - Supports capacity range of 4 to 32 GB, 4 pins @ 50 MHz. **Note:** With Windows 7 (32 or 64 bit) and MS Hotfix KB976422, up to 2 TB is supported.
  - Supports speed classes of up to Class 10
- For the SD format:
  - Supports capacities of up to 2 GB

### Miscellaneous

- Access to ACPI features through:
  - SMBus
  - ASFBus
  - GPIO

## 1.2 Branding and Part Numbers



**Figure 1. Bolton-E4 Branding and Part Number**

Notes on branding diagram:

- Branding can be in laser, ink, or mixed laser-and-ink-marking.
- AMD logo image may be in hollow/outline form.
- For the ASIC Name, FCH is used for production parts, while the engineering codename is used for engineering samples.
- For the Date Code, ENG designates engineering sample (it does not appear for production parts).

Figure legends:

ASIC NAME = See table below.

DATE CODE = YYWW (YY = assembly start year, WW = assembly start week)

COO = Country of origin (assembly site)

XXXXXX.XX = Wafer foundry lot number.wafer ID (wafer ID may not appear sometimes)

ZZZ-ZZZZZZZ = AMD part number (see table below)

**Table 1. Bolton-E4 Part Numbers**

<b>ASIC Name</b>	<b>ASIC Revision</b>	<b>Date Code</b>	<b>AMD Part Number</b>
Bolton-E4 Parts			
FCH	A1	YYWW	218-0844020-00

### 1.3 Bolton-E4 Block Diagrams

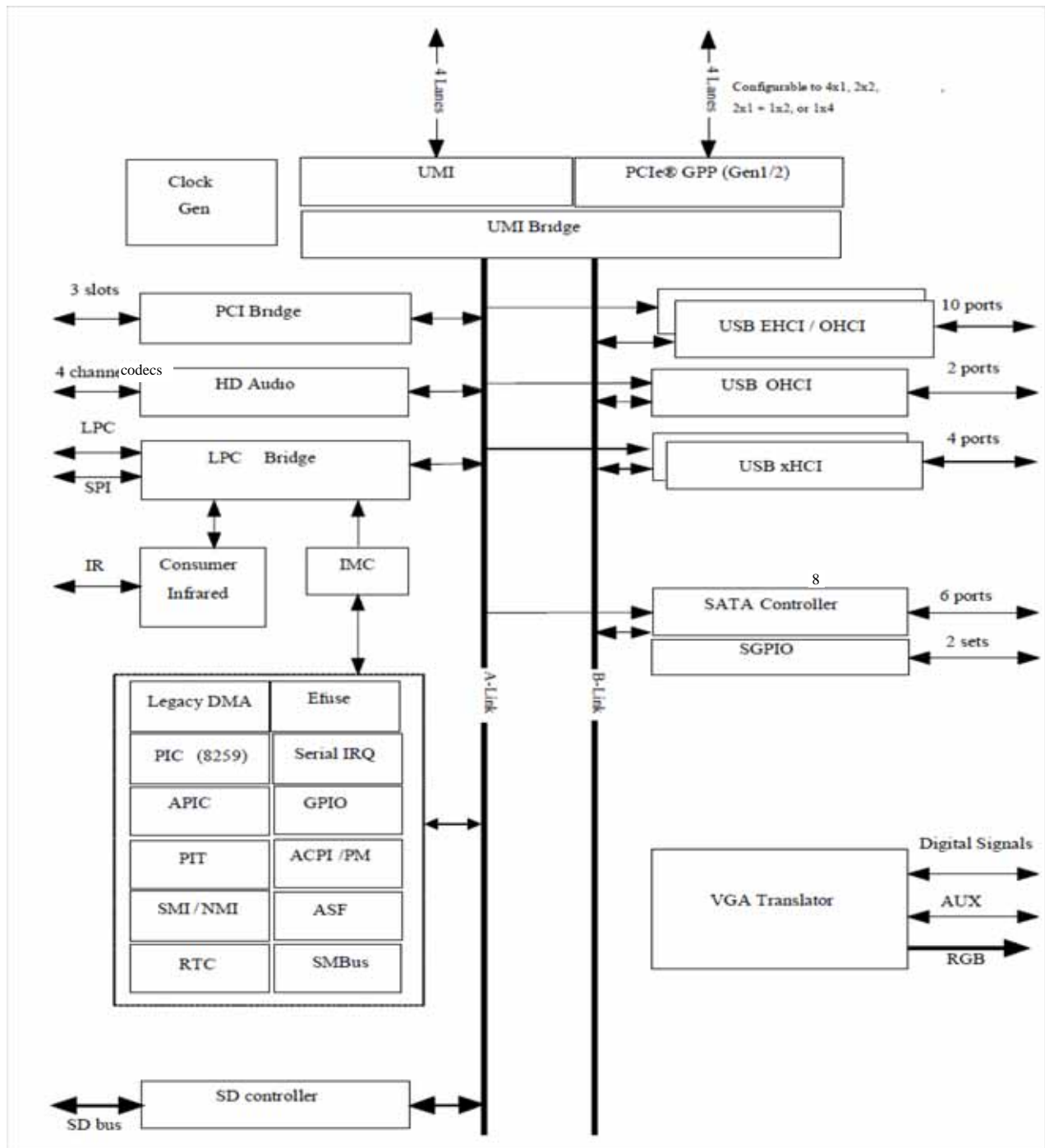


Figure 2. Bolton-E4 Block Diagram

## 1.4 Conventions and Notations

The following conventions are used throughout this manual.

### 1.4.1 Pin Names

Pins are identified by their pin names or ball references. All active-low signals are identified by the suffix ‘#’ in their names (e.g., GNT0#).

### 1.4.2 Pin Types

The pins are assigned different codes according to their operational characteristics. These codes are listed below.

**Table 2. Pin Type Codes**

Code	Pin Type
I	Digital Input
O	Digital Output
OD	Open Drain
I/O	Bi-Directional Digital Input or Output
I/OD	Digital Input or Open Drain
M	Multifunctional
PWR	Power
GND	Ground
A-O	Analog Output
A-I	Analog Input
A-I/O	Analog Bi-Directional Input/Output
A-PWR	Analog Power
A-GND	Analog Ground
Other	Pin types not included in any of the categories above

### 1.4.3 Numeric Representation

Hexadecimal numbers are appended with “h” whenever there is a risk of ambiguity. Other numbers are in decimal.

Pins of identical functions but different running integers (e.g., “LAD3,” “LAD2,” “LAD3”) are referred to collectively by specifying their integers in square brackets and with colons (i.e., “LAD[3:0]”). A similar short-hand notation is used to indicate bit occupation in a register. For example, Command[15:10] refers to the bit positions 10 through 15 of the Command register.

## 1.4.4 Register Field

A field of a register is referred to by the format of [Register Name].[Register Field]. For example, “Commad.Memory Space” is the “Memory Space” field of the register “Command.”

## 1.4.5 Acronyms and Abbreviations

The following is a list of the acronyms and abbreviations used in this manual.

**Table 3. Acronyms and Abbreviations**

Acronym	Full Expression
ACPI	Advanced Configuration and Power Interface
AHCI	Advanced Host Controller Interface
AOAC	Always On Always Connected
APU	Accelerated Processor Unit
BGA	Ball Grid Array
BIOS	Basic Input Output System. Initialization code stored in a ROM or Flash RAM used to start up a system or expansion card.
DAC	Digital to Analog Converter
DIPM	Device Initiated Interface Power Management
DMA	Direct Memory Access
EHCI	Enhanced Host Controller Interface
EPROM	Erasable Programmable Read Only Memory
FCH	Fusion Controller Hub
GND	Ground
GPIO	General Purpose Input/Output
GPM	General Power Management
HD	High Definition Audio
HIPM	Host Initiated Interface Power Management
HPET	High Precision Event Timer
I <sup>2</sup> C	Inter-Integrated Circuit
IDE	Integrated Drive Electronics
IMC	Integrated Micro-Controller
IR	Infrared
ISA	Industry Standard Architecture
JTAG	Joint Test Access Group. An IEEE standard.
LPC	Low Pin Count

**Table 3. Acronyms and Abbreviations (Continued)**

NC	No Connect
NCQ	Native Command Queuing
OHCI	Open Host Controller Interface
PCI	Peripheral Component Interface
PCIe®	PCI Express®
PLL	Phase Locked Loop
POST	Power On Self Test
PD	Pull-down Resistor
PU	Pull-up Resistor
RAID	Redundant Array of Inexpensive Disks
RTC	Real Time Clock
SATA	Serial ATA
SCI	System Controller Interrupt
SGPIO	Serial General Purpose Input/Output
SMBus	System Management Bus
SMI	System Management Interrupt
SPI	Serial Peripheral Interface
TBA	To Be Added (the information is not yet available)
TPM	Trusted Platform Module
UMI	Unified Media Interface
USB	Universal Serial Bus
xHCI	Extensible Host Controller Interface



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## Chapter 2 Functional Description

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### 2.1 USB Controllers

Figure 3 is an internal block diagram for Bolton-E4's USB controllers showing the use of two xHCI, three OHCI and two EHCI controllers to control four USB 3.0, ten USB 2.0, and two dedicated USB 1.1 ports.

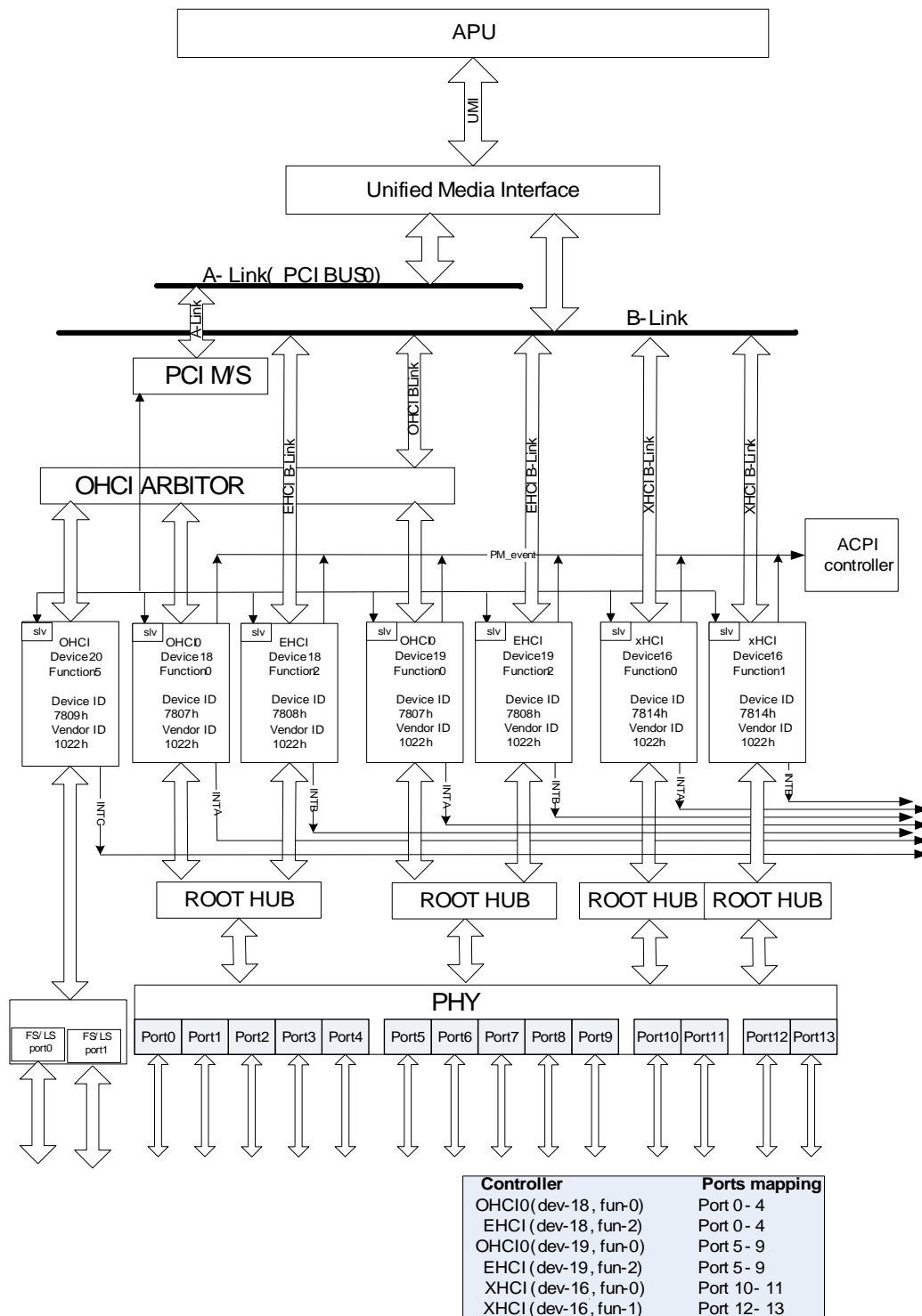


Figure 3. USB Controller Block Diagram for Bolton-E4

## 2.1.1 USB Power Management

An advanced power management capability interface compliant with *PCI Bus Power Management Interface Specification Revision 1.1* is incorporated into the EHCI and xHCI controllers. This interface allows the EHCI/xHCI to be placed in various power management states, offering a variety of power savings for a host system.

Table 4 highlights the EHCI/xHCI support for power management states and features supported for each of the power management states. An EHCI/xHCI implementation may internally gate-off USB clocks and suspend the USB transceivers (low power consumption mode) to provide these power savings.

**Table 4. EHCI/xHCI Support for Power Management States**

PCI Power Management State	State Required / Optional in Specification	Comments
D0	Required	Supported. Fully awake backward compatible state. All logic in full power mode.
D1	Optional	<b>Not supported.</b> USB Sleep state with EHCI/xHCI bus master capabilities disabled. All USB ports in suspended state. All logic in low latency power savings mode because of low latency returning to D0 state.
D2	Optional	<b>Not supported.</b> USB Sleep state with EHCI/xHCI bus master capabilities disabled. All USB ports in suspended state.
D3hot	Required	<b>Supported.</b> Deep USB Sleep state with EHCI/xHCI bus master capabilities disabled. All USB ports in suspended state.
D3cold	Required	<b>Supported.</b> Fully asleep backward compatible state. All downstream devices are either suspended or disconnected based on the implementation's capability to supply downstream port power within the power budget.

The functional and wake-up characteristics for the EHCI/xHCI power states are summarized below.

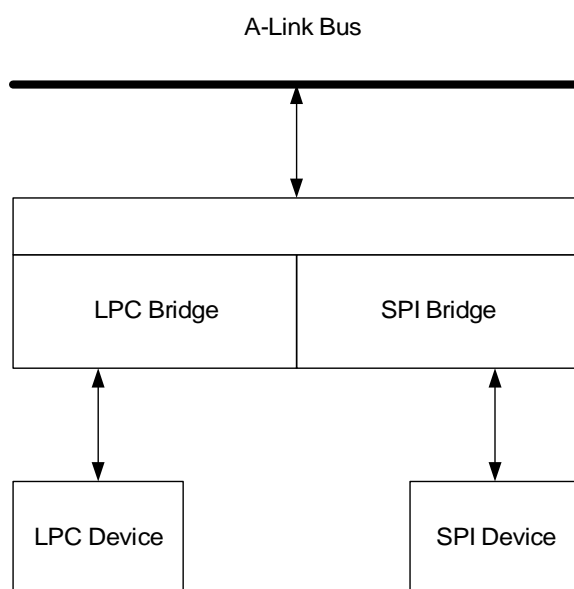
**Table 5. EHCI/xHCI Power State Summary**

Power State	Functional Characteristics	Wake-up Characteristics*
D0	<ul style="list-style-type: none"> <li>Fully functional EHCI/xHCI device state</li> <li>Unmasked interrupts are fully functional</li> </ul>	<ul style="list-style-type: none"> <li>Resume detected on suspended port</li> <li>Connect or Disconnect detected on port</li> <li>Over Current detected on port</li> </ul>
D1	<ul style="list-style-type: none"> <li>EHCI/xHCI preserves PCI configuration</li> <li>EHCI/xHCI preserves USB configuration</li> <li>Hardware masks functional interrupts</li> <li>All ports are disabled or suspended</li> </ul>	<ul style="list-style-type: none"> <li>Resume detected on suspended port</li> <li>Connect or Disconnect detected on port</li> <li>Over Current detected on port</li> </ul>
D2	<ul style="list-style-type: none"> <li>EHCI/xHCI preserves PCI configuration</li> <li>EHCI/xHCI preserves USB configuration</li> <li>Hardware masks functional interrupts</li> <li>All ports are disabled or suspended</li> </ul>	<ul style="list-style-type: none"> <li>Resume detected on suspended port</li> <li>Connect or Disconnect detected on port</li> <li>Over Current detected on port</li> </ul>
D3hot	<ul style="list-style-type: none"> <li>EHCI/xHCI preserves PCI configuration</li> <li>EHCI/xHCI preserves USB configuration</li> <li>Hardware masks functional interrupts</li> <li>All ports are disabled or suspended</li> </ul>	<ul style="list-style-type: none"> <li>Resume detected on suspended port</li> <li>Connect or Disconnect detected on port</li> <li>Over Current detected on port</li> </ul>
D3cold	<ul style="list-style-type: none"> <li>PME Context in PCI Configuration space is preserved</li> <li>Wake Context in EHCI/xHCI MemorySpace is preserved</li> <li>All ports are disabled or suspended</li> </ul>	<ul style="list-style-type: none"> <li>Resume detected on suspended port</li> <li>Connect or Disconnect detected on port</li> <li>Over Current detected on port</li> </ul>
<p><b>Note:</b> *Associated enables must be set.</p>		

## 2.2 LPC ISA Bridge

### 2.2.1 LPC Interface Overview

The Low Pin Count (LPC) bus interface is a cost-efficient, low-speed interface designed to support low bandwidth and legacy devices. The LPC interface essentially eliminates the need of ISA and X-bus in the system. A typical setup of the system with LPC interface is shown in Figure 4. The LPC host controller contains both LPC and Serial Peripheral Interface (SPI) bridge functions. It connects to the internal A-Link bus on one side and the LPC and SPI buses on the other side.



**Figure 4. A Typical LPC Bus System**

Examples of LPC devices include Super I/O, BIOS ROM, audio, Trusted Platform Module (TPM), and system management controller. A BIOS ROM can also be populated on the SPI interface. The FCH can support an LPC or SPI type BIOS ROM. The ROM selection is determined by a strap pin (refer to Table 32 on page 81) during RSMRST# assertion. In addition to the straps, software can change the ROM selection through programming in the PMIO registers.

The host controller supports memory and I/O read/write, Direct Memory Access (DMA) read/write, bus master memory I/O read/write, and TPM read/write. It supports up to two bus masters and seven DMA channels. A bus master or DMA agent uses the LDRQ pin to assert bus master or DMA requests. The host controller uses LFRAME# to indicate the start or termination of a cycle. Table 6 on page 30 shows a list of cycles supported by the host controller, their initiators, data flow directions, and their PCI counterparts.

**Table 6. LPC Cycle List and Data Direction**

Cycle	Size (bytes)	Initiator	Data Direction	PCI Counterpart
Memory read	1	Host	P-2-Host	MemRead to LPC range
Memory write	1	Host	Host-2-P	MemWrit to LPC range
I/O read	1	Host	P-2-Host	IORead to LPC range
I/O write	1	Host	Host-2-P	IOWrit to LPC range
DMA read	1, 2, 4	Peripheral	Host-2-P	DMA control setup; DMA data fetch
DMA write	1, 2, 4	Peripheral	P-2-Host	DMA control setup; DMA data store
BM Memory read	1, 2, 4	Peripheral	Host-2-P	DMA control setup; DMA data fetch
BM Memory write	1, 2, 4	Peripheral	P-2-Host	DMA control setup; DMA data store
BM I/O read	1, 2, 4	Peripheral	Host-2-P	DMA control setup; I/O data fetch
BM I/O write	1, 2, 4	Peripheral	P-2-Host	DMA control setup; I/O data store
TPM read	1,2,4	Host	P-2-Host	TPM read
TPM write	1,2,4	Host	Host-2-P	TPM write

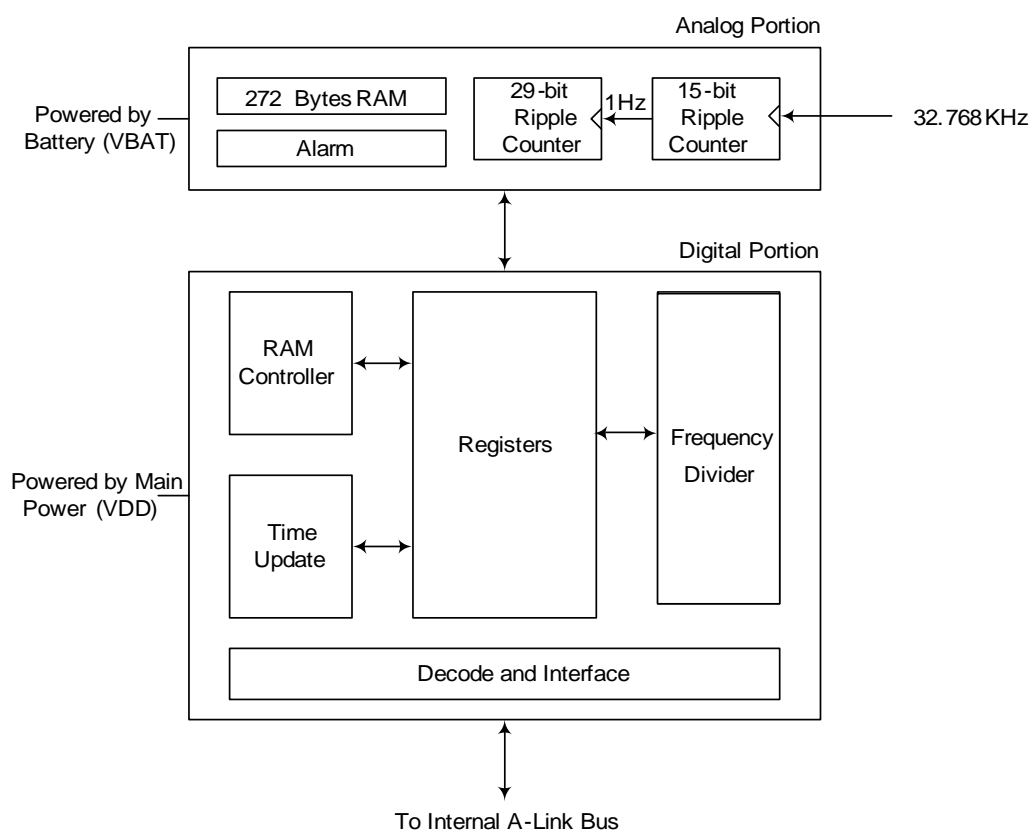
The host controller has a SERIRQ (Serial IRQ) pin, which is used by peripherals that require interrupt support. All legacy interrupts are serialized on this pin, decoded by the host controller, and sent to the interrupt controller for processing. Refer to the *Serial IRQ Specification, Version 5.4*, for a detailed description of the Serial IRQ protocol.

## 2.3 Real Time Clock

The Real Time Clock (RTC) updates the computer's time and generates interrupts for periodic events and pre-set alarm. The RTC also makes hardware leap year corrections. The FCH's RTC includes a 272-byte (256 standard bytes plus 16 additional bytes) CMOS RAM, which is used to store the configuration of a computer such as the number and type of disk drive, graphics adapter, base memory, checksum value, etc.

### 2.3.1 Functional Blocks of RTC

The internal RTC is made of two parts—one part is an analog circuit, powered by a battery (VBAT), and the other is a digital circuit, powered by the main power (VDD). Figure 5 shows the block diagram of the internal RTC. The FCH has a hardware-based daylight saving feature, which makes clock adjustments (spring forward or fall back) at the designated dates/times. Both the date and hour for the daylight and standard time are fully programmable, allowing for different daylight saving dates and hours for different parts of the world.



**Figure 5. Block Diagram of Internal RTC**

## 2.4 Serial ATA Controller

The integrated Serial ATA controller processes host commands and transfers data between the host and Serial ATA devices. It supports six independent Serial ATA channels. Each channel has its own Serial ATA bus and supports one Serial ATA device. The SATA controller supports Serial ATA first, second, and third generation transfer rates (up to 1.5 Gbit/s, 3.0 Gbit/s, and 6.0 Gbit/s respectively).

Figure 6 on page 33, and Figure 7 on page 35, are diagrams for the SATA block. The SATA controller can operate in three modes:

- All six channels configured to SATA AHCI mode.
- All six channels configured to IDE mode. In this configuration, the SATA controller is configured into two IDE controllers, with the programming interface of channel 0 to 3 under the first IDE controller, and that of channel 4 to 5/7 under the second IDE controller.
- Four channels (channel 0 to 3) configured as SATA AHCI and four channels (channel 4 to 5/7) configured as IDE mode. In this configuration, the programming interface of channel 4 to 5/7 is under the IDE controller.



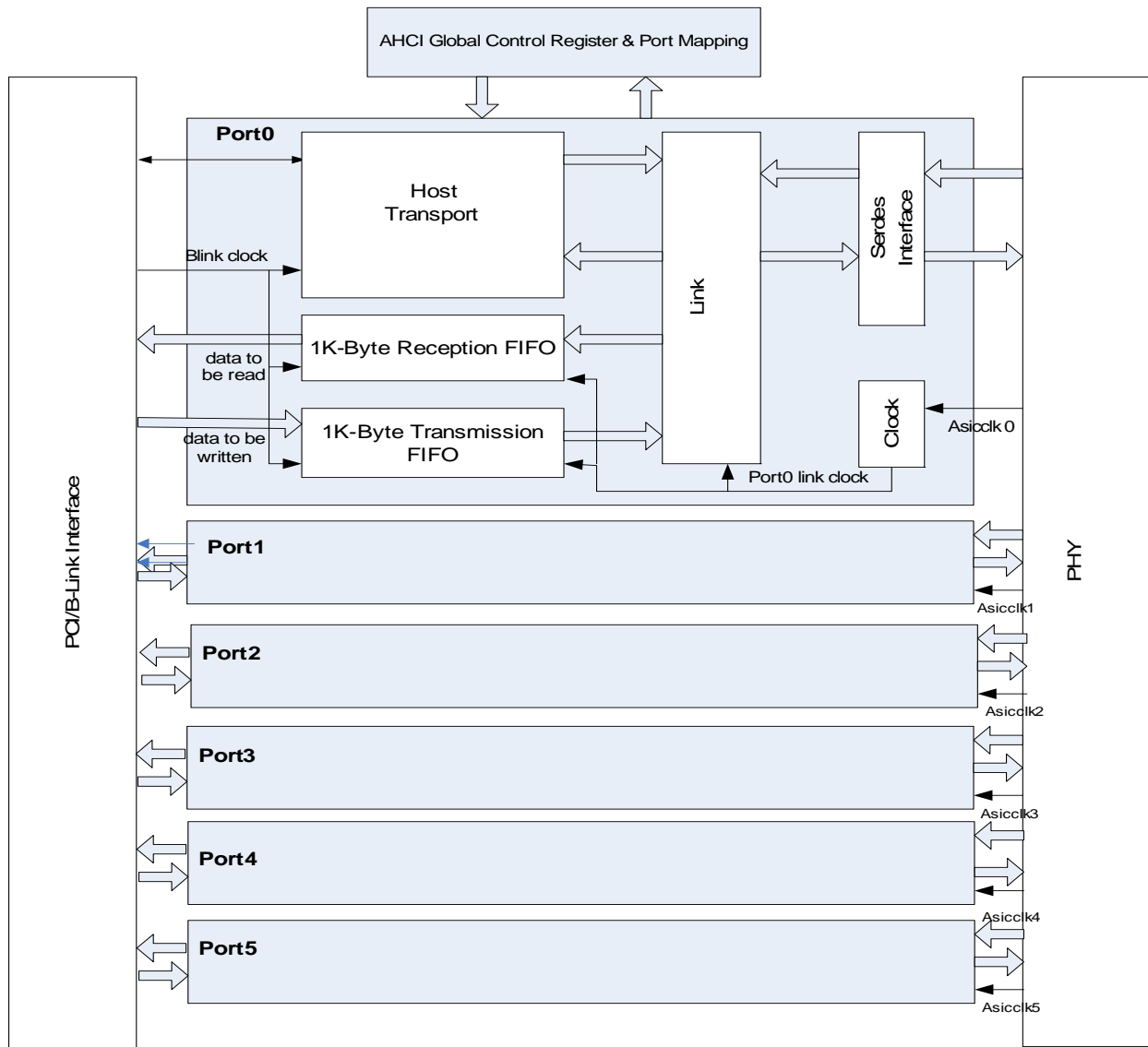


Figure 6. Block Diagram of the SATA Module of Bolton-E4

## **2.5 PCI Bridge**

The PCI Bridge supports up to three PCI slots. The PCI bridge runs at 33 MHz and can support the CLKRUN# function with individual clock override (option for not stopping specific PCICLK). In addition, it has the capability to hide individual PCI devices.

## 2.6 High Definition Audio

The High Definition (HD) audio controller communicates with external HD audio codec(s) over the HD audio link. The HD audio controller consists of four independent output DMA engines and four independent input DMA engines that are used to move data between system memory and the external codec(s). The controller can support up to four audio or modem codecs in any combinations.

### 2.6.1 HD Audio Codec Connections

Figure 7 shows the HD Audio interface connections to the HD Audio codecs. The FCH can support up to four HD Audio codecs. Each codec has its own AZ\_SDIN (data input) for the HD Audio interface. Figure 7 shows the connection for a two-codec configuration.

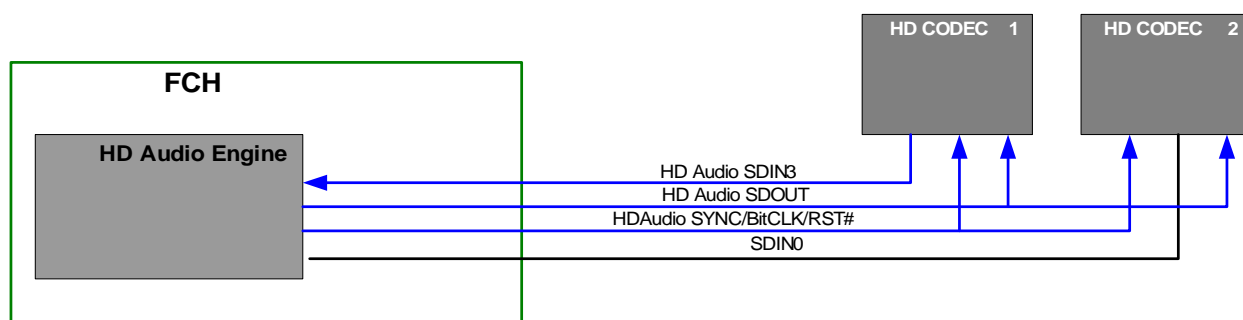


Figure 7. HD Audio Codec Connections

## 2.7 Clock Generation

Bolton-E4 has two clock configurations: (1) external clock mode, and (2) integrated clock mode. These are shown in Figure 8 and Figure 9 on page 37, respectively.

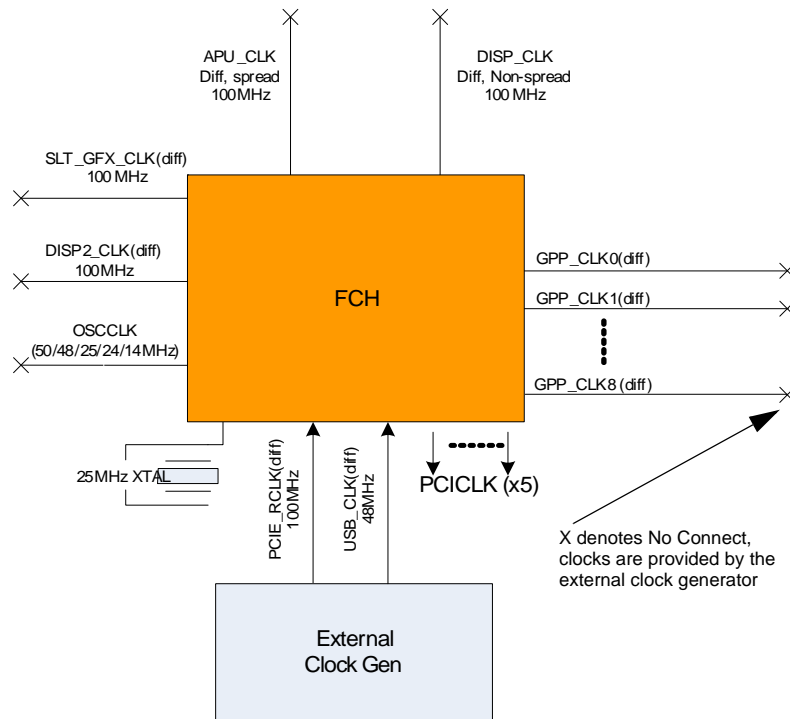
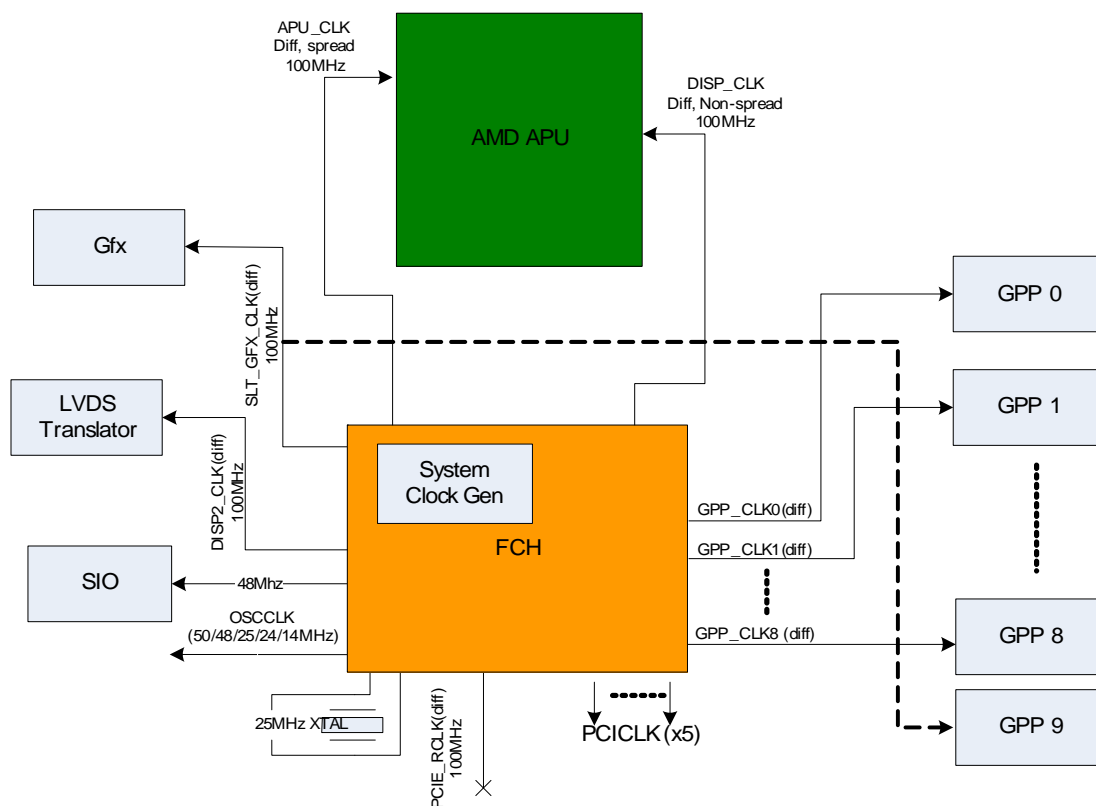


Figure 8. Bolton-E4 Clock Signals for External Clock Mode



**Figure 9. Bolton-E4 Clock Signals for Internal Clock Mode**

The clock mode is selected by a strap pin. If the FCH is in external clock mode, the clock sources required include a 14.318 MHz source for the timers, a 25MHz clock source for the VGA translator, a 32-KHz crystal for the RTC, a 100 MHz differential clock pair for the PCIe reference clocks, a 48-MHz clock source for USB, and a 25 MHz single ended or 100 MHz differential pair clock for SATA. In addition to the PCIe® clocks, the FCH also uses the 100 MHz clock to generate various internal clocks, including the PCI 33-MHz clocks.

If integrated clock mode is selected, only a 25 MHz crystal for master reference and a 32 KHz crystal for the RTC are required. The FCH will then generate all of the system clocks needed, including the APU clocks, the external graphics clock, the 25 MHz clock for SATA, and the 48 MHz clocks for USB, and so on.

## 2.8 SMI/SCI Generation

There are a total of 160 sources of events. The first 64 can be mapped to the 32 standard ACPI EVENT bits, which can be used to generate SCI or PME. All of the 160 events can be configured to generate SMI/NMI.

When an event is routed to SMI, an SMI assertion message will be sent by the FCH to the APU. The SMI status remains active until the EOS bit is set and the status bit is cleared. When the EOS is set, an SMI de-assertion message will be sent to the APU. If the event is routed to SCI, BIOS can then route it to any of the legacy interrupts (except IRQ8) or INT21 in the case of IOAPIC.

### 2.8.1 Event Sources for SCI

Table 7 below shows the 160 sources of SCI events, the first 64 of which can be mapped to the 32 event resources of the ACPI EventStatus. The SCI event mapping are controlled through the SciMap\* registers in SMI\_Reg space. And the SCI Event enable/status is accessed through the EventEnable/EventStatus registers in SMI\_reg space. Refer to the *AMD Bolton Fusion Controller Hub Register Reference Guide* for more details.

**Table 7. SCI Event Sources and Mapping onto ACPI EventStatus**

Event Number	Event Source
0 ~ 23	Gevent0 ~ 23 (GEVENT pins)
24	PME from USB device 18
25	PME from USB device 19
26	PME from USB device 20
27	PME from USB device 22
28	PME from GPP device 21, function 0
29	PME from GPP device 21, function 1
30	PME from GPP device 21, function 2
31	PME from GPP device 21, function 3
32	Hot plug event from GPP device 21, function 0
33	Hot plug event from GPP device 21, function 1
34	Hot plug event from GPP device 21, function 2
35	Hot plug event from GPP device 21, function 3
36	PME from HD Audio device
37	SATA Gevent 0
38	SATA Gevent 1
39	PME from Gec
40	IMC Gevent

**Table 7. SCI Event Sources and Mapping onto ACPI EventStatus (Continued)**

41	Reserved
42	PME from CIR
43	WAKE# pin
44	FanThermal Gevent
45	ASF Master Interrupt event
46	ASF Slave interrupt event
47	SMBUS0 interrupt
48	TWARN event
49	Traffic Monitor Gevent
50	iLLB_event50
51	PwrButton_event
52	ProcHot_event
53	NBHWAssertionMsg
54	NBSciAssertionMsg
55	RAS_event
56	XHC0PME
57	XHC1PME
57: 63	Reserved
64	Reserved
65	Slp_En_Write
66	GecRomSmi
67	SATA_AHCI_Smi
68	NbGppPme
69	NbGppHotPlug
70	RtcIrqEvent
71	ACPI_Timer_Event
72	GBL_RLS
73	BIOS_RLS
74	PWRBTN
75	SmiCmdPort
76	UsiSmi (OHCI legacy support)
77	SerIrqSmi
78	SMBus0Intr

**Table 7. SCI Event Sources and Mapping onto ACPI EventStatus (Continued)**

79	EcSmi
80	xHCErr
81	IntruderAlert
82	VBATLow
83	ProcHot
84	PCI_Serr
85	SB_Gpp0Serr
86	SB_Gpp1Serr
87	SB_Gpp2Serr
88	SB_Gpp3Serr
89	ThermalTrip
90	Emulate64_event90
91	Usb_FLR_event91
92	Sata_FLR_event92
93	Az_FLR_event93
94	Gec_FLR_event94
95	CmosEraseSts_event95
96	IRQ0Trapping_event96
97	IRQ1Trapping_event97
98	IRQ2Trapping_event98
99	IRQ3Trapping_event99
100	IRQ4Trapping_event100
101	IRQ5Trapping_event101
102	IRQ6Trapping_event102
103	IRQ7Trapping_event103
104	IRQ8Trapping_event104
105	IRQ9Trapping_event105
106	IRQ10Trapping_event106
107	IRQ11Trapping_event107
108	IRQ12Trapping_event108
109	IRQ13Trapping_event109
110	IRQ14Trapping_event110
111	IRQ15Trapping_event111



**Table 7. SCI Event Sources and Mapping onto ACPI EventStatus (Continued)**

112	IRQ16Trapping_event112
113	IRQ17Trapping_event113
114	IRQ18Trapping_event114
115	IRQ19Trapping_event115
116	IRQ20Trapping_event116
117	IRQ21Trapping_event117
118	IRQ22Trapping_event118
119	IRQ23Trapping_event119
120	VIn0Sts_event120
121	VIn1Sts_event121
122	VIn2Sts_event122
123	VIn3Sts_event123
124	VIn4Sts_event124
125	VIn5Sts_event125
126	VIn6Sts_event126
127	VIn7Sts_event127
128	Temp0Sts_event128
129	Temp1Sts_event129
130	Temp2Sts_event130
131	Temp3Sts_event131
132	Temp4Sts_event132
133	FanIn0Sts_event133
134	FanIn1Sts_event134
135	FanIn2Sts_event135
136	FanIn3Sts_event136
137	FanIn4Sts_event137
138	Fake0Sts_event138
139	Fake1Sts_event139
140	Fake2Sts_event140
141	CStateMsg_event141
142	ShortTimer_event142
143	LongTimer_event143
144	AbSmiTrap_event144

**Table 7. SCI Event Sources and Mapping onto ACPI EventStatus (Continued)**

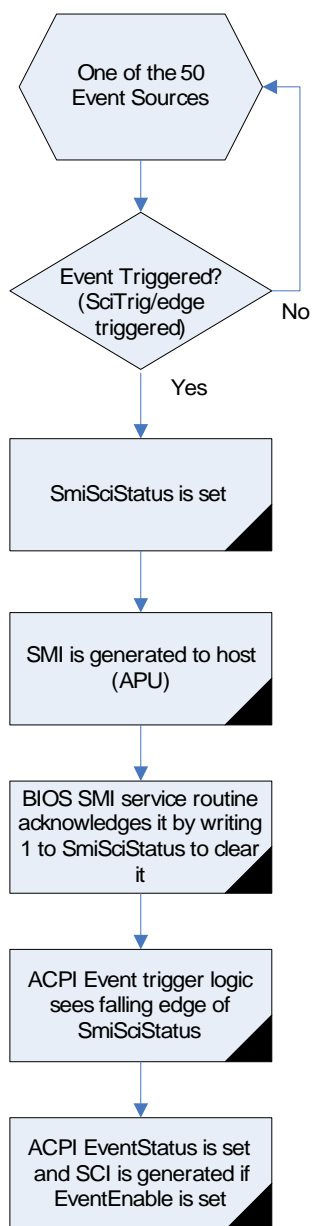
145	SoftReset_event145
146	PStateChange_event146
147	PStateChange_event147
148	IoTrapping0_event148
149	IoTrapping1_event149
150	IoTrapping2_event150
151	IoTrapping3_event151
152	MemTrapping0_event152
153	MemTrapping1_event153
154	MemTrapping2_event154
155	MemTrapping3_event155
156	CfgTrapping0_event156
157	CfgTrapping1_event157
158	CfgTrapping2_event158
159	CfgTrapping3_event159

## 2.8.2 SMI Events

Bolton-E4 supports up to 160 sources to generate SMI. The SMI control/status is accessed through the registers defined in the SMI\_Reg space. Refer to the *AMD Bolton Fusion Controller Hub Register Reference Guide, order# 51192* for more details.

## 2.8.3 SMI/SCI Work Flow

Figure 10 on page 43, shows how the SMI/SCI logic works (SmiSciEn bit set to 1).



**Figure 10. SMI/SCI Logic of Bolton-E4**

## **2.9 Power Management/ACPI**

The Bolton-E4 power management/ACPI logic supports both hardware and message-based C1e, stutter mode, and S states.

# Chapter 3 Ballout Assignment

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
A			VSS		USB_HSD2N	USB_HSD2N		USB_HSD6P		USB_HSD7N		USB_S5_RX1N	USB_S5_TX1P		USBS5_CALR N			
B							VSS		USB_RCOMP		USB_HSD9P		VSS		USB_S5_TX2N		KSO_16/XDB17 GPIO224	
C	USB_HSD1P		USB_HSD1N		USB_HSD2P	USB_HSD3P		USB_HSD5N		USB_HSD7P		USB_S5_RX1P	USB_S5_TX1N		USBS5_CALR P			
D							VDDPL_33_US B_S		VSS		USB_HSD9N		VSS		USB_S5_TX2P		KSO_17/XDB18 GPIO228	
E	USB_HSD0P		USB_HSD0N		VSS	VDDBT_RTC_G		USB_HSD4N		USB_HSD8P		VSS		USB_S5_RX1P		VSS		
F	RTCLK		INTRUDER_A LERT#		USB_OC2# AC_PRES/ TDO		VSS	USB_HSD4P	VSS	USB_HSD5N	VSS	USB_HSD11N	VSS	USB_S5_RX2N	USB_S5_TX1P	VSS	VSS	
G		32K_X1		32K_X2		VSS	VDDAN_33_U SB_S_1	USBCLK/ 14M_25M_48M OSC	USB_HSD6N	USB_HSD13N		USB_HSD11P	USB_S5_TX1N	USB_S5_TX1N		VSS		
H	USB_FSD1P/ GPIO186		USB_FSD1N		USB_FSD0N	USB_FSD0P/ GPIO185		S5_CORE_EN	VDDAN_33_U SB_S_2	USB_HSD6P	USB_HSD13P		VSS	USB_S5_RX1P		USB_S5_TX0N		
J		IR_LED# LLB#GPIO184		PWR_BT#		VSS	USB_OC1# TDO/ GEVENT13#		VDDAN_33_U SB_S_3	VSS	VSS		USB_HSD12N	VSS	USB_S5_RX0P	USB_S5_TX0P		
K	WAKE#/ GEVENT1#		TEMPIN1/ GPIO173		TEMPIN1/ GPIO172	TEMPIN0/ GPIO171		VSS	VDDAN_33_U SB_S_4	VDDAN_33_U SB_S_5	USB_HSD12P		USB_HSD10P	USB_HSD10N	USB_S5_RX0N	VSS		
L		VIN2/SDATL_1/ GPIO177		NC5		VSS						VSS	VSS		VSS	VSS		
M	VIN2/ GBE_STAT2/ GPIO181		VIN1/GPIO176		VIN7/ GBE_LED3/ GPIO182	TEMPIN3/ TALERT#/ GPIO174		BLIN#/ USB_OC7#/ GEVENT18#	VDDAN_33_H WM_S	VDDAN_33_U SB_S_6	VDDAN_33_U SB_S_7	VDDAN_33_U SB_S_10	VDDAN_33_U SB_S_12	VSS	VDDAN_11_S SUBS_2	VSS	VDDCR_11_S SUBS_4	
N		VIN0/GPIO175		VIN3/ SDATO_1/ GPIO178		VSS	PWR_GOOD	VSSAN_HWM	VDDAN_33_U SB_S_8	VDDAN_33_U SB_S_9	VSS	VDDAN_33_U SB_S_11	VSS	VDDAN_11_S SUBS_3	VDDCR_11_S SUBS_3	VDDCR_11_S SUBS_2	VDDCR_11_S SUBS_5	
P	VIN4/ SLOAD_1/ GPIO179		VIN5/SDATO_1/ GPIO180		USB_OC2# TCK/ GEVENT14#	USB_OC4#/ IR_RX0/ GEVENT16#						VSS	VDDAN_11_5 SUBS_4	VDDAN_11_5 SUBS_5	VSS	VDDCR_11_S SUBS_3	VDDCR_11_S SUBS_3	
R		RIS#/ GEVENT2#		VSS		VSS	SDA1/ GPIO228	USB_OC6#/ IR_TX1/ GEVENT16#	PHE#/ GEVENT3#	THRMTRP#/ SMBALERT#/ GEVENT2#	VSS							
T	USB_OC5#/ IR_TX0/ GEVENT17#		SLP_S3#		LPC_PD#/ GEVENT5#	SPL_CS1#/ GPIO165		SCL1/ GPIO227	VBE_OC0#/ GEVENT12#/ TR#7	TEST0	TEST1/TMS	VSS	VDDCR_11_U SB_S_1	VDDCR_11_U SB_S_2	VDDCR_11_1	VSS	VDDCR_11_2	
U		RSMRST#		SYS_RESET#/ GEVENT19#		VSS						VDDAN_11_U SB_S_1	VDDAN_11_U SB_S_2	VSS		VDDCR_11_4	VSS	
V	ROM_RST#/ SPL_WP#/ GPIO161		SPL_CLK/ GPIO162		SPL_DO/ GPIO163	SPL_DI/ GPIO164		IR_RX1/ GEVENT20#	DDR3_RST#/ GEVENT7#/ VQ_PA	TEST2	GBE_LED2/ GEVENT10#	VSS	VDDIO_33_S_4	VDDIO_33_S_5	VDDCR_11_6	VSS	VDDCR_11_7	
W		SLP_S5#		VSS		VSS		SPL_CS3#/ GBE_STAT1/ GEVENT21#	GBE_LED0/ GPIO183	GBE_PHY_INT R	GBE_MDIO	VDDIO_33_S_8						
Y	AZ_SDIN0/ GPIO170		AZ_SDIN2/ GPIO169		AZ_SDIN1/ GPIO168	SPI_TCLK#/ GBE_LED1/ GEVENT19#		GBE_PHY_RS T#	GBE_STAT0/ GEVENT11#	VDDIO_33_S_1	VDDIO_33_S_2	VDDCR_11_G BE_S_2	VSS	VSS	VSS	VSS	VSS	
AA		AZ_SDIN0/ GPIO167		VDDIO_AZ_S		VSS		GBE_PHY_RS T#	GBE_STAT0/ GEVENT11#	VDDIO_33_S_1	VDDIO_33_S_2	VDDCR_11_G BE_S_2	VSS	VSS	VSS	VSS	VSS	
AB	AZ_SDOUT		AZ_BITCLK		PCIRST#	PCIE_RST2#/ GEVENT4#		GBE_TXCLK	GBE_RXCLK	GBE_TXCTL/ TXEN	VDDIO_33_GB E_S	VDDCR_11_G BE_S_1	VDDIO_33_PC IGP_7	VDDIO_33_PC IGP_8	VDDIO_33_PC IGP_9	VDDIO_33_PC IGP_10	VDDIO_33_PC IGP_1	
AC		GBE_PHY_PD		GBE_COL		VSS						AD24/GPIO24	VDDIO_33_PC IGP_8		AD30/GPIO30	INTG#/GPIO34		
AD	GBE_RXERR		GBE_CRS		A_RST#	AZ_SYNC		GBE_RXD0	GBE_TXD0	GBE_MDCK	VDDIO_33_PC IGP_4		CBE3#	GNT1#/GPIO44	AD29/GPIO29	GNT#		
AE		PCIE_RST#		AZ_RST#		VSS		GBE_RXD1	GBE_TXD1	VDDIO_33_PC IGP_3	PAR		AD23/GPIO23	AD25/GPIO25	VSS	AD31/GPIO31		
AF	PCICLK1/ GPIO36		PCICLK0		PCICLK2/ GPIO37	PCICLK4/ 14M_OSV/ GPIO39		GBE_RXD2	VSS	GBE_TXD3	TRDY#		VSS	AD26/GPIO26	REQ2# CLK_REQ#/ GPIO41	VSS		
AG		PCICLK3/ GPIO38		AD2/GPIO2		GBE_TXD2		VDDIO_33_PC IGP_5	GBE_RXCTL/ RXDV	AD16/GPIO16	FRAME#		AD22/GPIO22	REQ1#/ GPIO40	REQ0#	NC1		
AH	STOP#		AD4/GPIO4		VSS			GBE_RXD3	SERR#	LOCK#	NC2	VSS	SD_WP#/ GPIO76	AD27/GPIO27	AD28/GPIO28	SD_DATA2/ GPIO79	FANOUT0/ GPIO52	SATA_IS4#/ FANOUT0/ GPIO55
AJ	AD9/GPIO9		AD0/GPIO0		AD5/GPIO5	AD13/GPIO13			CBE1#		AD18/GPIO18		SD_CSN#/ GPIO75		SD_DATA3/ GPIO80		FANOUT2/ GPIO54	
AK								AD14/GPIO14		DEVSEL#		AD20/GPIO20		SD_DATA0/ SDATL_0/ GPIO77	FANIN0/ GPIO56		FANIN2/ GPIO58	GNT3#/CLK_ REQ7#/SATA_ IS7#/GPIO58
AL	AD6/GPIO6		AD11/GPIO11		AD1/GPIO1	AD3/GPIO3			AD10/GPIO10		IRDY#		AD19/GPIO19		SD_CLK/ SCLK_0/ GPIO73		FANIN0/ GPIO58	
AM								AD12/GPIO12		PERR#		AD17/GPIO17		SD_DATA1/ SDATO_0/ GPIO75	FANOUT1/ GPIO53		FANIN1/ GPIO57	REQ3#/CLK_ REQ5#/SATA_ IS6#/GPIO42
AN	VSS		CBE#		AD7/GPIO7	AD8/GPIO8			AD15/GPIO15		CBE2#		AD21/GPIO21		SD_CMD/ SLOAD_0/ GPIO74		FANIN1/ GPIO57	

Figure 11. Bolton-E4 Ballout Assignment (Left)

18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	
KSO_12/ GPIO221		KSO_5/ GPIO214		KSO_3/ GPIO212		KSO_16/ XDR2/		LAD2		NC3	LAD3		LFRAME#		VSS	A
	KSO_14/ XDB9/		KSO_9/ GPIO218		KSI_5/ GPIO206		LPCLK0		LDR00#							B
KSO_13/ GPIO222		PS2KB_CLK /GPIO190		PS2M_CLK/ GPIO183		PS2M_CLK/ GPIO183		KSI_6/ GPIO207		LPC_SMI#/ GEVENT23#	LAD1	ML_VGA_H PD/GPIO229	25M_X1		25M_X2	C
	KSO_11/ GPIO220		PS2KB_DAT# /GPIO189		PS2M_DAT# /GPIO191		LPCLK1		LAD0							D
KSO_4/ GPIO213		KSO_1/ GPIO210		EC_PWM0/ EC_TIMER0/		KSI_4/ GPIO205		APU_PG		PROCHOT#	VSS		GPP_CLKIN		GPP_CLK3P	E
KSI_7/ GPIO208	VSS		KSO_2/ GPIO211	KSO_0/ GPIO209	KSI_2/ GPIO203	VSS	KSI_3/ GPIO204	VSS	APU_RST#	CLK_CALRN			GPP_CLK2N		GPP_CLK2P	F
KSO_8/ GPIO217	SDAP# /GPIO194		SDA3_LV# /GPIO196	SCL3_LV# /GPIO195		VDDXL_33_ S	DMA_ACTIV E#	LDT_STP#		NC4	PCIE_RCLK N		PCIE_RCLK P		VSS	G
KSO_7/ GPIO216	SCL2# /GPIO193		EC_PWM3/ EC_TIMER3/	EC_PWM1/ EC_TIMER1/		VDDPL_33_ SYS	VSSPL_SYS	VDDAN_11 CLK_1	GPP_CLK0P	GPP_CLK0N	VSS		DISP2_CLK N		DISP2_CLK P	H
KSO_6/ GPIO215	PS2L_CLK# /SCL4/		SPI_CS2#/ CBE_STAT2	EC_PWM2/ EC_TIMER2/		VDDPL_11_ SYS_S	VDDAN_11_ CLK_2	14M_25M_4 8M_OSC	GPP_CLK1P	VSS		SLT_GFX_C LKP		VSS		J
KSO_10/ GPIO219	PS2_DAT# /SD4V/		KSI_0/ GPIO201	KSI_1/ GPIO202		VDDAN_11_ CLK_3	VSSXL	GPP_CLK1N	VSS	VSS		SLT_GFX_C LKN	VGA_DAC_ RSET		VSSANO_D AC	K
VDDPL_33_ SSUBS_5	VDDIO_33_ S_2		VSS	VDDAN_11_ CLK_4						VSSAN_DAC		VGA_RED		VGA_GREE N		L
VDDIO_33_ S_3		VDDCR_11_ S_2	VSS	VDDAN_11_ CLK_5	GPP_CLK4P	GPP_CLK4N	VSS	GPP_CLK5N	GPP_CLK5P	VGA_HSYN C/GPO68	VGA_BLUE		LDO_CAP		VGA_BDC_ SDA/GPO70	M
VDDIO_33_ S_1		VDDCR_11_ S_1	VDDAN_11_ CLK_6	VDDAN_11_ CLK_7	VSS	VSS	GPP_CLK6P	GPP_CLK6N	GPP_CLK8P	VSSIO_DAC		VGA_VSYN C/GPO69		VGA_DDC_ SCL/GPO71		N
VSS		VSS	VSS	VDDAN_11_ CLK_8						ML_VGA_L3 N	ML_VGA_L3 P		VSS		VSS	P
					GPP_CLK7P	GPP_CLK7N	VSS	DISP_CLKP	GPP_CLK8N	VSS		ML_VGA_L2 N		ML_VGA_L2 P		R
VSS		VDDCR_11_ S	VSSPL_DAC	VDDAN_11_ DAC	APU_CLKN	APU_CLKP	VSS	DISP_CLKN	VSS	ML_VGA_L1 N	ML_VGA_L1 P		ML_VGA_L0 P		ML_VGA_L0 N	T
VDDCR_11_ S		VSS	VSS	VDDPL_33_ ML						AUXCAL		VSS		VSS		U
VSS		VDDCR_11_ S	VDDPL_11_ DAC	VDDPL_33_ DAC	VDDAN_11_ ML_2	VDDAN_11_ ML_3	VDDAN_11_ ML_4	GPP_RX2P	GPP_RX1N	AUX_VGA_ CH_P	AUX_VGA_ CH_N		GPP_TX0N		GPP_TX0P	V
					GPP_RX3N	GPP_RX3P	VSS	GPP_RX2N	GPP_RX1P	VSS		GPP_TX1P		GPP_TX1N		W
VSS		VDDAN_11_ SATA_4	VDDAN_11_ PCIE_2	VDDAN_11_ ML_1					UMI_RX3P	UMI_RX3N		UMI_RX2N		UMI_RX2P		Y
VDDAN_11_ SATA_8		VDDAN_11_ SATA_7	VDDAN_11_ SATA_1	VDDAN_11_ SATA_3	GPP_TX3N	GPP_TX3P	VSS	GPP_RX0N	GPP_RX0P	VSS		VSS		VSS		AA
VDDIO_33_ PCIP_2		VDDAN_11_ SATA_9	VDDAN_11_ SATA_2	VDDAN_11_ SATA_5	VDDAN_11_ PCIE_5	VDDAN_11_ PCIE_1	VSS	GPP_TX2P	GPP_TX2N	UMI_RX1P	UMI_RX1N		UMI_RX0N		UMI_RX0P	AB
VSS	VDDAN_11_ SATA_10		VDDAN_11_ SATA_6	VDDAN_11_ SATA_5						VSS		UMI_TX3P		UMI_TX3N		AC
INTH#/ GPIO35	CLKRUN#		GN12#/ SD_LED/	SATA_ACT# /GPIO67		VDDAN_11_ PCIE_4	SDA0/ GPIO47	SCL0/ GPIO43	VSS	UMI_TX2P	UMI_TX2N		UMI_TX1N		UMI_TX1P	AD
INTF#/ GPIO33	SERIRQ/ GPIO48		VSS	GA20IN/ GEVENT0#		CLK_REQ3# /SATA_IS1#	VDDAN_11_ PCIE_3	SMARTVOL TI/	LDRQ1#/ CLK_REQ6#	VSS		UMI_TX0P		UMI_TX0N		AE
INTE#/ GPIO32	WD_PWRG D		SATA_X1			SPKR/ GPIO66	CLK_REQ3# /GPIO65/	VDDAN_11_ PCIE_7	SATA_CALR N	SATA_CALR P	PCIE_CALR P		PCIE_CALR N		VSS	AF
SATA_JSS#/ FANN3/	KBRST#/ GEVENT1#		SATA_X2	CLK_REQ1# /FANOUT4/		CLK_REQ4# /SATA_IS0#	CLK_REQ2# /FANN4/	SMARTVOL T2/	VDDAN_11_ PCIE_8	VDDPL_33_ SATA		VSS		VSS		AG
VSS	VSS	SATA_RX1N	VSS	SATA_TX2N	VSS	SATA_TX3P	VSS	SATA_RX4P	VSS		VDDPL_33_ PCIE		SATA_TX0N		SATA_TX0P	AH
VSS		SATA_RX1P		SATA_TX2P		SATA_TX3N		SATA_RX4N		VSS	VSS		SATA_RX7P		SATA_RX7N	AJ
	SATA_TX0P		VSS		SATA_RX2P		VSS		SATA_RX5N							AK
VSS		SATA_RX0N		SATA_TX1N		SATA_RX3P		SATA_TX4P		SATA_TX5N	SATA_TX6P		SATA_RX6N		SATA_RX6P	AL
	SATA_TX0N		VSS		SATA_RX2N		VSS		SATA_RX5P							AM
VSS		SATA_RX0P		SATA_TX1P		SATA_RX3N		SATA_TX4N		VSS	SATA_TX5P		SATA_TX6N		VSS	AN

Figure 12. Bolton-E4 Ballout Assignment (Right)

## Chapter 4 Pin Descriptions

### Notes:

For multi-functional pins, please refer to the relevant section for description of a specific function (e.g., for USB\_FSD1P/GPIO186, the USB\_FSD1P function is described in Section 4.6 “USB Interface” on page 51, and the GPIO186 function is described in Section 4.21 “General Purpose I/O and General Event Pins” on page 67).

### 4.1 APU Interface

**Table 8. APU Interface Pin Descriptions**

Pin name	Type	Voltage	Functional Description
DMA_ACTIVE#	In/OD	VDDIO_33_S (0.8V threshold)	DMA_ACTIVE#. See Section 4.14 “Power Management Interface” on page 57 for description.
APU_PG	OD	VDDIO_33_S	APU Power Good
APU_RST#	OD	VDDIO_33_S	APU Reset. See Section 4.16 “Reset Pins” on page 60 for description.
LDT_STP#	OD	VDDIO_33_S	Not used. Leave unconnected.
PROCHOT#	I	VDDIO_33_S (0.8V threshold)	Processor Hot: Similar to TALERT#. When it is asserted, it can generate SCI or SMI to OS/BIOS

### 4.2 LPC Interface

**Table 9. LPC Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
CLKRUN#	I/O	VDDIO_33_PCIGP (5V tolerance)	See Section 4.17 “Clock Interface” on page 62 for description.
GA20IN/GEVENT0#	I	VDDIO_33_PCIGP (5V tolerance)	A20 Gate Input from SIO / General Event 0
KBRST#/ GEVENT1#	I	VDDIO_33_PCIGP (5V tolerance)	Keyboard reset# / General Event 1
LAD[3:0]	I/O	VDDIO_33_S	Multiplexed Command / Address/Data [3:0]
LDRQ0#	I	VDDIO_33_S	Encoded DMA Bus Master Request 0
LDRQ1#/ CLK_REQ6#/ GPIO49	I/O	VDDIO_33_PCIGP (5V tolerance)	Encoded DMA Bus Master Request 1 / Clock Request 6 / GPIO 49
LFRAME#	O	VDDIO_33_S	LPC Bus Frame. Indicates start of a new cycle or termination of a broken cycle.
LPCCLK0	O	VDDIO_33_S	33MHz LPCCLK for LPC device such as flash ROM

**Table 9. LPC Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
LPCCLK1	O	VDDIO_33_S	33MHz LPCCLK for LPC device such as SIO device
LPC_SMI#/ GEVENT23#	I	VDDIO_33_S	LPC SMI / General Event 23
SERIRQ/GPIO48	I/O	VDDIO_33_PCIGP (5V tolerance)	Serial IRQ / GPIO 48

*Note: LPCCLK0 can be assigned to any LPC device. This clock can be active during sleep state during initial G3->S5 or when IMC is enabled. LPCCLK1 and PCI clock can be used for additional LPC devices that do not require a clock in S3-S5 states.*

### 4.3 Unified Media Interface (UMI)

**Table 10. UMI Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
UMI_TX[3:0]P	O	VDDAN_11_ PCIE	SCL Lane 3-0 Transmit Positive
UMI_TX[3:0]N	O		SCL Lane 3-0 Transmit Negative
UMI_RX[3:0]P	I		SCL Lane 3-0 Receive Positive
UMI_RX[3:0]N	I		SCL Lane 3-0 Receive Negative
PCIE_CALRP	I/O		Pad connection to an external resistor to VSS on board required for TX impedance calibration.
PCIE_CALRN	I/O		Pad connection to an external resistor to VDDAN_11_PCIE on board required for RX impedance calibration.

### 4.4 General Purpose PCI Express® Ports Interface

**Table 11. General Purpose PCI Express® Ports Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
GPP_TX[3:0]P	O	VDDAN_11_ PCIE	General purpose PCIe® ports Lane 3 to 0 Transmit Positive
GPP_TX[3:0]N	O		General purpose PCIe ports Lane 3 to 0 Transmit Negative
GPP_RX[3:0]P	I		General purpose PCIe ports Lane 3 to 0 Receive Positive
GPP_RX[3:0]N	I		General purpose PCIe ports Lane 3 to 0 Receive Negative



## 4.5 PCI Interface (PCI Host Bus and Internal PCI/PCI Bridge)

**Table 12. PCI Interface (PCI Host Bus and Internal PCI/PCI Bridge) Pin Description**

Pin Name	Type	Voltage	Functional Description
AD[31:0]/ GPIO[31:0]	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Address/Data [31:0] / GPIO[31:0]
CBE[3:0]#	I/O	VDDIO_33_PCIGP (5V tolerance)	Command/Byte Enable[3:0]
CLKRUN#	I/O	VDDIO_33_PCIGP (5V tolerance)	See Section 4.17 “Clock Interface” on page 62 for description.
DEVSEL#	I/O	VDDIO_33_PCIGP (5V tolerance)	Device Select. Driven by target to indicate it has decoded its address as the target of the current access.
FRAME#	I/O	VDDIO_33_PCIGP (5V tolerance)	Cycle Frame. Driven by the current master to indicate the beginning and duration of an access.
GNT0#	O	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Grant 0 from the FCH. Indicates to the agent that access to the bus has been granted.
GNT1#/GPO44	O	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Grant 1 from the FCH. Indicates to the agent that access to the bus has been granted. Pin muxed with GPIO44
GNT2#/SD_LED/ GPO45	O	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Grant 2 from the FCH. Indicates to the agent that access to the bus has been granted. Pin muxed with GPIO45
GNT3#/ CLK_REQ7#/ GPIO46	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Grant 3 from the FCH. Indicates to the agent that access to the bus has been granted. Pin muxed with GPIO46
INTH#/GPIO35	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Interrupt H / GPIO 35
INTG#/ GPIO34	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Interrupt G / GPIO 33
INTF#/GPIO33	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Interrupt F / GPIO 33
INTE#/GPIO32	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Interrupt E / GPIO 32
IRDY#	I/O	VDDIO_33_PCIGP (5V tolerance)	Initiator Ready: Indicates the initiating agent’s ability to complete the current data phase of the transaction
LOCK#	I/OD	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Lock
PAR	I/O	VDDIO_33_PCIGP (5V tolerance)	PCI Bus Parity
PCICLK0	O	VDDIO_33_PCIGP (5V tolerance)	33 MHz PCI clock 0

**Table 12. PCI Interface (PCI Host Bus and Internal PCI/PCI Bridge) Pin Description**

Pin Name	Type	Voltage	Functional Description
PCICLK[3:1]/ GPO[38:36]	O	VDDIO_33_PCIGP (5V tolerance)	33 MHz PCI clock [3:1]
PCICLK4/ 14M_OSC/GPO39	O	VDDIO_33_PCIGP (5V tolerance)	33 MHz PCI clock 4. See Section 4.17 “Clock Interface” on page 62 for description.
PCIRST#	O	VDDIO_33_PCIGP (5V tolerance)	Hardware Reset for PCI Slots. See Section 4.16 “Reset Pins” on page 60 for description.
A_RST#	O	VDDIO_33_S (5V tolerance)	PCI Host Bus Reset. See Section 4.16 “Reset Pins” on page 60 for description.
PERR#	I/O	VDDIO_33_PCIGP (5V tolerance)	Parity Error. Reports data parity errors during all PCI transactions, except in a special cycle.
REQ0#	I	VDDIO_33_PCIGP (5V tolerance)	PCI Request 0 Input. Indicates that the agent desires use of the bus.
REQ1#/GPIO40	I	VDDIO_33_PCIGP (5V tolerance)	PCI Request 1 Input. Indicates that the agent desires use of the bus.
REQ2#/ CLK_REQ8#/ GPIO41	I	VDDIO_33_PCIGP (5V tolerance)	Request 2 Input. Indicates that the agent desires use of the bus
REQ3#/ CLK_REQ5#/ GPIO42	I	VDDIO_33_PCIGP (5V tolerance)	Request 3 Input. Indicates that the agent desires use of the bus.
SERR#	I/OD	VDDIO_33_PCIGP (5V tolerance)	System Error. For reporting address parity errors and data parity errors on the special cycle command, or any other system error where the result will be catastrophic.
STOP#	I/O	VDDIO_33_PCIGP (5V tolerance)	Stop. Indicates the current target is requesting the master to stop the current transaction
TRDY#	I/O	VDDIO_33_PCIGP (5V tolerance)	Target Ready. Indicates the target agent’s ability to complete the current data phase of the transaction.

## 4.6 USB Interface

**Table 13. USB Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
USB_SS_TX[3:0]P	I/O	VDDAN_11_SSUSB	USB Super Speed port 3:0 Transmit Positive
USB_SS_TX[3:0]N	I/O	VDDAN_11_SSUSB	USB Super Speed port 3:0 Transmit Negative
USB_SS_RX[3:0]P	I/O	VDDAN_11_SSUSB	USB Super Speed port 3:0 Receive Positive
USB_SS_RX[3:0]N	I/O	VDDAN_11_SSUSB	USB Super Speed port 3:0 Receive Negative
USB_HSD[13:0]P	I/O	VDDAN_33_USB	USB Port 13:0 Positive I/O
USB_HSD[13:0]N	I/O	VDDAN_33_USB	USB Port 13:0 Negative I/O
USB_FSD1P/ GPIO186	I/O	VDDIO_33_S	USB port 1 (full/low speed) Positive I/O
USB_FSD0P/ GPIO185	I/O	VDDIO_33_S	USB port 0 (full/low speed) Positive I/O
USB_FSD[1:0]N	I/O	VDDIO_33_S	USB port 1:0 (full/low speed) Negative I/O
USBCLK/ 14M_25M_48M_O SC	I/O	VDDPL_33_USB	See Section 4.16 “Reset Pins” on page 60; Section 4.17 “Clock Interface” on page 62; and Section 4.18 “ATE/JTAG Interface” on page 65
USB_RCOMP	I	VDDPL_33_USB	Compensating resistors input.
USB_OC0#/ GEVENT12#/TRST	I/O	VDDIO_33_S	USB Over Current 0#
USB_OC1#/TDI/ GEVENT13#	I/O	VDDIO_33_S	USB Over Current 1#
USB_OC2#/TCK/ GEVENT14#	I/O	VDDIO_33_S	USB Over Current 2#
USB_OC3#/ AC_PRES/TDO/ GEVENT15#	I/O	VDDIO_33_S	USB Over Current 3#
USB_OC4#/ IR_RX0/ GEVENT16#	I/O	VDDIO_33_S	USB Over Current 4#
USB_OC5#/ IR_TX0/ GEVENT17#	I/O	VDDIO_33_S	USB Over Current 5#
USB_OC6#/ IR_TX1/ GEVENT6#	I/O	VDDIO_33_S	USB Over Current 6#
BLINK/ USB_OC7#/ GEVENT18#	I/O	VDDIO_33_S	USB Over Current 7#
USBSS_CALRP	I	VDDAN_11_SSUSB	Pad connection to an external resistor to VSS (close to USBSS interface) on the motherboard, for TX impedance calibration

**Table 13. USB Interface Pin Descriptions (Continued)**

Pin Name	Type	Voltage	Functional Description
USBSS_CALRN	I	VDDAN_11_SSUSB	Pad connection to an external resistor to VDDAN_11_SSUSB on the motherboard, for RX impedance calibration

**Note:**

1. The USB\_HSD[13:0]P and USB\_HSD[13:0]N signals are used for connecting internal or external USB devices through the USB Port connectors. These ports are handled by users and are subject directly to ESD events to either the connector, the device, or to the pins themselves. The USB\_HSDP and USB\_HSDN signals that may be exposed to the user through an USB port connection must have ESD protection.
2. The USB\_FSD[1:0]P and USB\_FSD[1:0]N signals are used only for connecting to internal devices. They support only full or low, but not high speed devices.
3. The USBCK/14M\_25M\_48M\_OSC pin (G8) as well as the 14M\_25M\_48M\_OSC pin (J26) output a 14.318MHz clock on the first power up if the internal system clock generator mode strap is selected.

## 4.7 SD Card Interface

**Table 14. SD Card Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
SD_CLK/SCLK_0/GPIO73	O	VDDIO_33_PCIGP	SD Clock
SD_CMD/SLOAD_0/GPIO74	O		SD Command
SD_CD#/GPIO75	I		SD Card Detect
SD_WP/GPIO76	O		SD Write Protect
SD_DATA0/SDATI_0/GPIO77	I/O		SD Data
SD_DATA1/SDATO_0/GPIO78	I/O		SD Data 1
SD_DATA2/GPIO79	I/O		SD Data 2
SD_DATA3/GPIO80	I/O		SD Data 3
GNT2#/SD_LED/GPO45	O		SD LED

## 4.8 Serial ATA Interface

**Table 15. Serial ATA Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
SATA_ACT#/GPIO67	OD	VDDIO_33_PCIGP	SATA Channel Active
SATA_CALRP	I	VDDAN_11_SATA	Pad connection to an external resistor to VSS close to the SATA interface on the motherboard, for TX impedance calibration
SATA_CALRN	I	VDDAN_11_SATA	Pad connection to an external resistor to VDDAN_11_SATA on the motherboard, for RX impedance calibration
SATA_RX[57:0]N	I	VDDAN_11_SATA	SATA Channel[57:0] Receive Negative
SATA_RX[57:0]P	I	VDDAN_11_SATA	SATA Channel[57:0] Receive Positive

**Table 15. Serial ATA Interface Pin Descriptions (Continued)**

Pin Name	Type	Voltage	Functional Description
SATA_TX[57:0]N	O	VDDAN_11_SATA	SATA Channel[57:0] Transmit Negative
SATA_TX[57:0]P	O	VDDAN_11_SATA	SATA Channel[57:0] Transmit Positive
SATA_X1	I	VDDPL_33_SATA	SATA 25MHz crystal clock input (external clock mode)
SATA_X2	O	VDDPL_33_SATA	SATA 25MHz crystal clock input (external clock mode)
CLK_REQ4#/ SATA_IS0#/GPIO64	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 0 (Input) *
CLKREQ3#/ SATA_IS1#/GPIO63	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 1 (Input) *
SMARTVOLT1/ SATA_IS2#/GPIO50	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 2 (input) *
CLKREQ0#/ SATA_IS3#/GPIO60	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 3 (input) *
SATA_IS4#/ FANOUT3/GPIO55	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 4 (input) *
SATA_IS5#/FANIN3/ GPIO59	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 5 (input) *
REQ3#/CLK_REQ5#/ SATA_IS6#/GPIO42	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 6 (input) *
GNT3#/CLK_REQ7#/ SATA_IS7#/GPIO46	I/O	VDDIO_33_PCIGP	SATA Interlock Switch Port 7 (input) *
VIN2/SDATI_1/ GPIO177	I/O	VDDIO_33_S	SGPIO Data In (set 1) **
VIN3/SDATO_1/ GPIO178	I/O	VDDIO_33_S	SGPIO Data Out (set 1) **
VIN4/SLOAD_1/ GPIO179	I/O	VDDIO_33_S	SGPIO Load (set 1) **
VIN5/SCLK_1/ GPIO180	I/O	VDDIO_33_S	SGPIO Clock (set 1) **
SD_CLK/SCLK_0/ GPIO73	I/O	VDDIO_33_PCIGP	SGPIO Clock (set 0) **
SD_CMD/SLOAD_0/ GPIO74	I/O	VDDIO_33_PCIGP	SGPIO Load (set 0) **
SD_DATA0/ SDATI_0/GPIO77	I/O	VDDIO_33_PCIGP	SGPIO Data In (set 0) **
SD_DATA1/ SDATO_0/GPIO78	I/O	VDDIO_33_PCIGP	SGPIO Data Out (set 0) **
<b>Notes:</b>			
1. * SATA_ISx#: These are Hot Plug external interlock switches (one for each SATA port). The SATA Hot Plug function support with AMD drivers does not require the use of these signals. Please refer to the Bolton Motherboard Design Guide on how to terminate these signals.			
2. ** Bolton-E4 supports up to two sets of SGPIO.			

## 4.9 HD Audio Interface

**Table 16. HD Audio Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional description
AZ_BITCLK	O	VDDIO_33_S/VDDIO_AZ_S (1.5V)	HD Audio Interface Bit Clock
AZ_RST#	O	VDDIO_33_S/VDDIO_AZ_S (1.5V)	HD Audio Interface Reset
AZ_SDIN[3:0]/ GPIO[170:167]	I/O	VDDIO_33_S/VDDIO_AZ_S (1.5V)	HD Audio Serial Data Input from Codec [3:0]/ GPIO [170:167]
AZ_SDOUT	O	VDDIO_33_S/VDDIO_AZ_S (1.5V)	HD Audio Serial Data Output to Codec
AZ_SYNC	O	VDDIO_33_S/VDDIO_AZ_S (1.5V)	HD Audio Sync signal to Codec

## 4.10 Real Time Clock Interface

**Table 17. Real Time Clock Interface**

Pin Name	Type	Voltage	Functional Description
32K_X1	I	VDDIO_33_S/ VDDBT_RTC_G	RTC crystal oscillator input 1 (internal RTC). See Section 4.17 “Clock Interface” on page 62 for description.
32K_X2	O	VDDIO_33_S/ VDDBT_RTC_G	RTC crystal oscillator input 2 (internal RTC). See Section 4.17 “Clock Interface” on page 62 for description.
RTCCLK	I/O	VDDIO_33_S	32 kHz output for internal RTC.
INTRUDER_ALER T#	I	VDDBT_RTC_G	Intruder alert sense input
S5_CORE_EN	O	VDDIO_33_S	S5 Core Enable. See Section 4.14 “Power Management Interface” on page 57 for description.
USB_OC3#/ AC_PRESENT/ TDO/ GEVENT15#	I/O	VDDIO_33_S	AC Power Present. See Section 4.14 “Power Management Interface” on page 57 for description.
WAKE#/ GEVENT8#	I/O	VDDIO_33_S	PCIe <sup>®</sup> Wake. See Section 4.14 “Power Management Interface” on page 57 for description.
IR_LED#/LLB#/ GPIO184	I/O	VDDIO_33_S	Low Low Battery. Connected to the battery circuit signal output that indicates a battery low condition. When the function is enabled, an assertion of this pin will prevent the system from waking up by any wake event .

**Table 17. Real Time Clock Interface (Continued)**

Pin Name	Type	Voltage	Functional Description
SLP_S3#	O	VDDIO_33_S	S3 Sleep Power plane control. See Section 4.14 “Power Management Interface” on page 57 for description.
SLP_S5#	O	VDDIO_33_S	S5 Sleep Power plane control. See Section 4.14 “Power Management Interface” on page 57 for description.
PWR_BTN#	I	VDDIO_33_S	Power Button. See Section 4.14 “Power Management Interface” on page 57 for description.

## 4.11 Hardware Monitor Interface

**Table 18. Hardware Monitor Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
CLK_REQ1#/ FANOUT4/GPIO61	I/O	VDD_IO_33_PCIG P (5V tolerance)	Fan PWM Output 4
CLK_REQ2#/ FANIN4/GPIO62	I/O	VDD_IO_33_PCIG P (5V tolerance)	Fan Input 4
FANIN[2:0]/ GPIO[58:56]	I/O	VDD_IO_33_PCIG P (5V tolerance)	Fan Tachometer Input [2:0]
FANOUT[2:0]/ GPIO[54:52]	I/O	VDD_IO_33_PCIG P (5V tolerance)	Fan PWM Output [2:0]
SATA_IS4#/ FANOUT3/GPIO55	I/O	VDD_IO_33_PCIG P (5V tolerance)	Fan Control Output 3
SATA_IS5#/ FANIN3/GPIO59	I/O	VDD_IO_33_PCIG P (5V tolerance)	Fan Input 3
TEMPIN[2:0]/ GPIO[173:171]	I/O	VDDIO_33_S	Temperature Monitor Input [2:0] (not supported)
TEMPIN3/ TALERT#/GPIO174	I/O	VDDIO_33_S	Temperature Monitor Input 3 (not supported) / Temperature has reached cautionary state
VIN0/GPIO175	I/O	VDDIO_33_S	Voltage Monitor Input 0 (not supported)
VIN1/GPIO176	I/O	VDDIO_33_S	Voltage Monitor Input 1 (not supported)
VIN2/SDATI_1/ GPIO177	I/O	VDDIO_33_S	Voltage Monitor Input 2 (not supported)
VIN3/SDATO_1/ GPIO178	I/O	VDDIO_33_S	Voltage Monitor Input 3 (not supported)
VIN4/SLOAD_1/ GPIO179	I/O	VDDIO_33_S	Voltage Monitor Input 4 (not supported)
VIN5/SCLK_1/ GPIO180	I/O	VDDIO_33_S	Voltage Monitor Input 5 (not supported)
VIN6/GBE_STAT3/ GPIO181	I/O	VDDIO_33_S	Voltage Monitor Input 6 (not supported)

**Table 18. Hardware Monitor Interface Pin Descriptions**

VIN7/GBE_LED3/ GPIO182	I/O	VDDIO_33_S	Voltage Monitor Input 7 (not supported)
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## 4.12 VGA Translator Interface

**Table 19. VGA Translator Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
ML_VGA_L[3:0]P	I	VDDAN_11_ML	Translator Input [3:0] Positive
ML_VGA_L[3:0]N	I	VDDAN_11_ML	Translator Input [3:0] Negative
ML_VGA_HPD/ GPIO229	I/O*	VDDIO_33_S	VGA Hot Plug Detect * Programmed by software to output as required, see Table 28 on page 67, for default I/O state.
AUXCAL	I/O	VDDIO_33_PCIGP	AUX Port Calibration
AUX_VGA_CH_P	I/O	VDDIO_33_PCIGP	AUX Port Positive
AUX_VGA_CH_N	I/O	VDDIO_33_PCIGP	AUX Port Negative
VGA_RED	O	LDO_CAP (internally-generated supply)	VGA Red Output
VGA_BLUE	O	LDO_CAP	VGA Blue Output
VGA_GREEN	O	LDO_CAP	VGA Green Output
VGA_HSYNC/ GPO68	O	VDDIO_33_PCIGP	VGA Horizontal SYNC
VGA_VSYNC/ GPO69	O	VDDIO_33_PCIGP	VGA Vertical SYNC
VGA_DAC_RSET	O	VDDIO_33_PCIGP	DAC Reset
VGA_DDC_SDA/ GPO70	I/O	VDDIO_33_PCIGP (5V tolerance)	VGA DDC Data
VGA_DDC_SCL/ GPO71	I/O	VDDIO_33_PCIGP (5V tolerance)	VGA DDC Clock
DDR3_RST#/ GEVENT7#/ VGA_PD	O*	VDDIO_33_S	VGA Power Down. This pin is used to power down the VGA DAC regulators when no display is connected. * <i>Note:</i> Pin type is OD for DDR_RST#, and I/O for GEVENT7#

## 4.13 SPI ROM Interface

SPI ROM is supported up to 66 MHz. The burst read and fast read cycles are not supported. Refer to Section 6.5.3.3 “SPI AC Specifications” on page 107 for timing information.



**Table 20. SPI ROM Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
SPI_CS1#/GPIO165	I/O	VDDIO_33_S	SPI Chip Select1#
SPI_CS2#/GBE_STAT2/ GPIO166	I/O	VDDIO_33_S	SPI Chip Select2#
SPI_CS3#/GBE_STAT1/ GEVENT21#	I/O	VDDIO_33_S	SPI Chip Select3#
SPI_CLK/GPIO162	I/O	VDDIO_33_S	SPI Clock
SPI_DI/GPIO164	I/O	VDDIO_33_S	SPI Data In
SPI_DO/GPIO163	I/O	VDDIO_33_S	SPI Data Output
SPI_HOLD#/ GBE_LED1/GEVENT9#	I/O	VDDIO_33_S	SPI HOLD#. Assert low to hold the SPI transaction.
ROM_RST#/SPI_WP#/ GPIO161	I/O	VDDIO_33_S	ROM reset (LPC flash) or SPI write protect (active low)
LPC_PD#/GEVENT5#	I/O	VDDIO_33_S	LPC power down (negative logic)

## 4.14 Power Management Interface

**Table 21. Power Management Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
DMA_ACTIVE#	In/OD	VDDIO_33_S (0.8V threshold)	DMA active. Bolton-E4 drives the DMA_ACTIVE# to APU to notify DMA activity. This will cause the APU to re-establish the SCL link quicker.
PME#/GEVENT3#	I/O	VDDIO_33_S	LPC/PCI PME# Power management signal for LPC/PCI interface.
LPC_SMI#/ GEVENT23#	I/O	VDDIO_33_S	LPC SMI Input
PWR_BTN#	I	VDDIO_33_S	Power Button. The Power Button causes an SMI or SCI to indicate a system request to go to a sleep state. If the system is already in a sleep state, this signal will cause a wake event. If PWRBTN# is pressed for more than 4 seconds, it will cause an unconditional transition (power button override) to the S5 state with only the PWRBTN# available as a wake event. This signal has an internal pull-up resistor.

Table 21. Power Management Interface Pin Descriptions (Continued)

Pin Name	Type	Voltage	Functional Description
PWR_GOOD	I	VDDIO_33_S	Power good input. Assertion of PWR_GOOD by the power good circuit on the motherboard indicates that power supplies to the Bolton-E4 are valid. Assertion takes place sometime after APU Power Good is asserted.  Deassertion of PWR_GOOD by the power good circuit indicates that the power supplies to the chip are NOT valid. Deassertion takes place sometime after SLP_S3# or SLP_S5#'s assertion, or after Power Supply Power Good is deasserted.
RI#/GEVENT22#	I/O	VDDIO_33_S	Ring Indicator
S5_CORE_EN	O	VDDIO_33_S	S5 Core Enable.
SMARTVOLT2/ SHUTDOWN#/ GPIO51	I/O	VDDIO_33_PCIGP (5V tolerance)	System Shutdown.  Assertion will cause the Bolton-E4 to assert SLP_S3# and SLP_S5# to force system to transition to S5 immediately, without waiting for the STPGNT message from the APU.
SLP_S3#	O	VDDIO_33_S	S3 Sleep Power plane control.  Assertion of SLP_S3# shuts off power to non-critical components when system transitions to S3, S4, or S5 states.  Deassertion of SLP_S3# turns on power to non-critical components when system transitions from S3, S4, or S5 back to S0. Deassertion takes place sometime after a wake-up event has been triggered.
SLP_S5#	O	VDDIO_33_S	S5 Sleep Power plane control.  Assertion of SLP_S5# shuts power off to non-critical components when system transitions to S4 or S5 state.  Deassertion of SLP_S5# turns on power to non-critical components when transitioning from S4/S5 back to S0 state. Deassertion takes place sometime after a wake-up event is triggered.
THRMTRIP#/ SMBALERT#/ GEVENT2#	I/O	VDDIO_33_S	Thermal Trip.  Indicates to Bolton E4 that a thermal trip has occurred. Its assertion will cause Bolton E4 to transition the system to S5 immediately, without waiting for the STPGNT message from the processor.  <i>Note: If Thermtrip function is required, the SMBAlert function can be mapped to any other available Gevent pin.</i>

**Table 21. Power Management Interface Pin Descriptions (Continued)**

Pin Name	Type	Voltage	Functional Description
TEMPIN3/ TALERT#/ GPIO174	I/O	VDDIO_33_S	Thermal Alert. The signal is a thermal alert to the FCH. The FCH can be programmed to generate an SMI, SCI, or IRQ13 through GPE, or generate an SMI without GPE in response to the signal's assertion. See the <i>AMD Bolton Fusion Controller Hub Register Reference Guide</i> for details.
USB_OC3#/ AC_PRES/TDO/ GEVENT15#	I/O	VDDIO_33_S	AC Power Present. Used by the FCH to check if AC power is present.
WAKE#/ GEVENT8#	I/O	VDDIO_33_S	PCIe Wake. WAKE# signal is required for PCIe devices. This signal is routed from the PCIe device/slot to the FCH. Note: the WAKE# is in S5 domain so it is active when the system is in S5 state. Care must be taken when plugging in the PCIe devices: the system should be transitioned into G3 state (S5 Power OFF) before a PCIe device is installed. Plugging in a PCIe device when the system is in S5 state may cause the system to wake up. That is because the WAKE# signal driven by the PCIe device may transition momentarily to active state when the device is installed but has not been initialized to drive the signal in an inactive state.
WD_PWRGD	OD	VDDIO_33_PCIGP	The pin is not used by the FCH. Refer to the <i>AMD Bolton Fusion Controller Hub Motherboard Design Guide</i> on how to handle the pin.

## 4.15 SMBus Interface

**Table 22. SMBus Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
SCL0/GPIO43	I/O	VDDIO_33_PCIGP (5V tolerance)	SMBus Clock 0
SDA0/GPIO47	I/O	VDDIO_33_PCIGP (5V tolerance)	SMBus Data 0
SCL1/GPIO227	I/O	VDDIO_33_S	SMBus Clock 1. SMBus Clock 1 supports an ASF interface or a Synaptics InterTouch Touchpad. See Note 1 below.
SDA1/GPIO228	I/O	VDDIO_33_S	SMBus Data 1. SMBus Data 1 supports an ASF interface or a Synaptics InterTouch Touchpad. See Note 1 below.

**Table 22. SMBus Interface Pin Descriptions (Continued)**

Pin Name	Type	Voltage	Functional Description
SCL2/GPIO193	I/O	VDDIO_33_S	SMBus Clock 2
SDA2/GPIO194	I/O	VDDIO_33_S	SMBus Data 2
SCL3_LV/GPIO195	I/O	VDDIO_33_S domain (0.8V threshold)	SMBus Clock 3 (typically used for TSI)
SDA3_LV/GPIO196	I/O	VDDIO_33_S domain (0.8V threshold)	SMBus Data 3 (typically used for TSI)
PS2_CLK/SCL4/ GPIO188	I/O	VDDIO_33_S	SMBus Clock 4
PS2_DAT/SDA4/ GPIO187	I/O	VDDIO_33_S	SMBus Data 4
THRMTRIP#/ SMBALERT#/ GEVENT2#	I/O	VDDIO_33_S	SMBus Alert#. This signal is used to wake the system or generate an SMI. If not used for SMBALERT#, it can be used for thermal trip or as a GEVENT.  Note: If this pin is used for Thermtrip function, the SMBAlert function can be mapped to any other available Gevent pin.
<b>Notes:</b>			
1. The SDA1 and SCL1 SMBus1 interface is dedicated for ASF devices or a Synaptics InterTouch Touchpad. This SMBus1 interface will not support a connection to both types of devices simultaneously.			
2. There are only two SMBus controllers. The SCL1/SDA1 pair is controlled by SMBus controller 1. SCL0/SDA0, SCL2/SDA2, SCL3/SDA3 and SCL4/SDA4 are multiplexed pins that are all controlled by SMBus controller 0, and only 1 pair of those pins can be active at any time.			

## 4.16 Reset Pins

**Table 23. Reset Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
A_RST#	O	VDDIO_33_S	PCI Host Bus Reset. Asserted during transition to S3/S4/S5 to reset all devices in the FCH or connected to it, except the ACPI logic in the FCH.
AZ_RST#	O	VDDIO_33_S/ VDDIO_AZ_S	HD Audio interface Reset.
DDR3_RST#/ GEVENT7#/ VGA_PD	OD	VDDIO_33_S	System Memory Reset

**Table 23. Reset Pin Descriptions (Continued)**

Pin Name	Type	Voltage	Functional Description
APU_RST#	OD	VDDIO_33_S (0.8V threshold)	APU Reset. Reset signal to the APU. Assertion of APU_RST# causes the APU to re-initialize its internal states. Assertion of APU_RST# can occur based on the following: 1) whenever there is a S3 or higher sleep state entry; 2) deassertion of FCH PWR_GOOD; 3) warm reset issued by a software command such as a write to IO 0xCF9; 4) hardware reset due to assertion of pins such as RSMRST# or KB_RST# or SYS_RESET#; 5) an internal error (sync flood); 6) expiration of the watchdog timer.  When the above conditions are no longer true, APU_RST# will deassert after a predetermined period of time (see Figure 21 Reset Timing Requirements on page 95)
PCIE_RST#	O	VDDIO_33_S	PCIe Reset. Asserted during transition to S3/S4/S5. Same function as A_RST#.
PCIE_RST2#/ GEVENT4#	I/O	VDDIO_33_S	Additional PCIe reset for GPP.
PCIRST#	O	VDDIO_33_PCI GP (5V tolerance)	Hardware Reset for PCI slots. Asserted (a) at power on, (b) after the system has transitioned into S3/S4/S5, (c) at warm reset, (d) at software initiated reset
ROM_RST#/ GPIO161	I/O	VDDIO_33_S	ROM Reset. Early version of system reset, the deassertion of which is ahead of other system reset signals such as A_RST#, PCIE_RST#, or PCIRST#. Used for resetting the system BIOS flash ROM.
RSMRST#	I	VDDIO_33_S	Resume Reset from motherboard. Assertion of RSMRST# resets all FCH registers to their default values. It also causes all reset signals originating from the FCH (A_RST#, PCIRST#, PCIE_RST#, APU_RST#, AZ_RST#, FC_RST#, GBE_PHY_RST#, ROM_RST# and, DDR3_RST#) to be issued. RSRMT# should be asserted when system power is being applied for the first time. RSMRST# should be deasserted sometime after S5 power is up, and should stay deasserted until system power is removed.
SYS_RESET#/ GEVENT19#	I/O	VDDIO_33_S	System Reset. Signal coming from the power button circuit signaling a reset for the system. On receiving the signal, the FCH asserts all reset signals that originate from the FCH (A_RST#, PCIRST#, PCIE_RST#, APU_RST#, AZ_RST#, FC_RST#, ROM_RST#, and DDR3_RST#). it also resets all FCH registers to their default values.

## 4.17 Clock Interface

**Table 24. Clock Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
25M_X1	I	3.3V (VDDXL_33_S)	25 MHz crystal clock or external reference clock. Clock source for FCH internal core PLLs.
25M_X2	O	3.3V (VDDXL_33_S)	25 MHz crystal clock output.
32K_X1	I	VDDIO_33_S/ VDDBT_RTC_G	RTC crystal oscillator input 1 (internal RTC). Must be active at all time.
32K_X2	O	VDDIO_33_S/ VDDBT_RTC_G	RTC crystal oscillator input 2 (internal RTC). Must be active at all time.
14M_25M_48M_OS C	O	VDDIO_33_S	14MHz / 24MHz / 25MHz / 48MHz /50MHz clock output. Note: This pin outputs a 14.318MHz clock on the first power up if the internal system clock generator mode strap is selected.
PCICLK0	O	3.3V (5V tolerance)	33 MHz PCI clock 0
PCICLK1/GPO36	O	3.3V (5V tolerance)	33 MHz PCI clock 1
PCICLK2/GPO37	O	3.3V (5V tolerance)	33 MHz PCI clock 2
PCICLK3/GPO38	O	3.3V (5V tolerance)	33 MHz PCI clock 3
PCICLK4/ 14M_OSC/GPO39	O	3.3V	33 MHz PCI Clock 4 / 14.318 MHz clock output. <b>For external clock generator mode:</b> 33 MHz PCI clock output. <b>For internal clock generator mode:</b> 14.318 MHz clock output for internal clock generator mode. The function is selected by the pin strap “CLKGEN” (pin LPCCLK1). Refer to Table 32 on page 81.
CLKRUN#	I/O	3.3V (5V tolerance)	Clock running is deasserted by the clock provider to indicate the system is about to shut down the PCI or LPC clock. When it is driven low by other agents, it means the agent is requesting the clock provider not to deactivate the clock.
USBCLK/ 14M_25M_48M_OS C	I/O	VDDIO_33_S	48 MHz clock input used for USB / 14.318 MHz or 25 MHz or 48 MHz output.

Table 24. Clock Interface Pin Descriptions (Continued)

Pin Name	Type	Voltage	Functional Description
APU_CLKP	O	VDDAN_11_CLK	Positive phase of 100 MHz APU reference clock. Spread capable.
APU_CLKN	O	VDDAN_11_CLK	Negative phase of 100 MHz APU reference clock. Spread capable.
GPP_CLK[8:0]P	O	VDDAN_11_CLK	Positive phase of 100 MHz reference clock for PCIe device(s). Spread capable.
GPP_CLK[8:0]N	O	VDDAN_11_CLK	Negative phase of 100 MHz reference clock for PCIe device(s). Spread capable.
PCIE_RCLKP	I	VDDAN_11_CLK	<b>For external clock generator mode:</b> Positive phase of 100-MHz reference clock for the FCH. Spread capable. <b>For internal clock generator mode:</b> Not used. Left unconnected. The function is selected by the pin strap “CLKGEN” (pin LPCCLK1). Refer to Table 32 on page 81.
PCIE_RCLKN	I	VDDAN_11_CLK	<b>For external clock generator mode:</b> Negative phase of 100-MHz reference clock for the FCH. Spread capable. <b>For internal clock generator mode:</b> Not used. Left unconnected. The function is selected by the pin strap “CLKGEN” (pin LPCCLK1). Refer to Table 32 on page 81.
DISP_CLKP	O	VDDAN_11_CLK	Positive phase of 100-MHz reference clock for APU’s display engine. Not spread capable.
DISP_CLKN	O	VDDAN_11_CLK	Negative phase of 100-MHz reference clock for APU’s display engine. Not spread capable.
DISP2_CLKP	O	VDDAN_11_CLK	Positive phase of 100-MHz LVDS translator reference clock. Not spread capable.
DISP2_CLKN	O	VDDAN_11_CLK	Negative phase of 100-MHz LVDS translator reference clock. Not spread capable.
SLT_GFX_CLKP	O	VDDAN_11_CLK	Positive phase of 100 MHz reference clock for external discrete graphics device. Spread capable.
SLT_GFX_CLKN	O	VDDAN_11_CLK	Negative phase of 100 MHz reference clock for external discrete graphics device. Spread capable.
CLK_REQ0#/ SATA_IS3#/#GPIO60	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe <sup>®</sup> Clock Request 0

**Table 24. Clock Interface Pin Descriptions (Continued)**

Pin Name	Type	Voltage	Functional Description
CLK_REQ1#/ FANOUT4/GPIO61	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 1
CLK_REQ2#/ FANIN4/GPIO62	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 2
CLK_REQ3#/ SATA_IS1#/GPIO63	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 3
CLK_REQ4#/ SATA_IS0#/GPIO64	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 4
REQ3#/ CLK_REQ5#/ GPIO42	I	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 5
LDRQ1#/ CLK_REQ6#/ GPIO49	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 6
GNT3#/ CLK_REQ7#/ GPIO46	I/O	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 7
REQ2#/ CLK_REQ8#/ GPIO41	I	VDDIO_33_PCIG P (5V tolerance)	PCIe Clock Request 8
CLK_REQG#/ GPIO65/OSCIN/ IDLEEXIT#	I	VDDIO_33_PCIG P (5V tolerance)	Clock Request by PCIe Graphics / 14.318 MHz clock input <b>For external clock generator mode:</b> 14.318 MHz OSC clock input pin. <b>For internal clock generator mode:</b> Used as GPIO or left unconnected.
RTCCLK	I/O	VDDIO_33_S	32 kHz output for internal RTC.
CLK_CALRN	I	VDDAN_11_CLK	Pad connection to an external resistor to VDDAN_11_CLK on the motherboard, for impedance calibration



## 4.18 ATE/JTAG Interface

**Table 25. ATE/JTAG Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
TEST0	I	VDDIO_33_S	ATE Test 0
TEST1/TMS	I	VDDIO_33_S	ATE Test 1/ JTAG TMS
TEST2	I	VDDIO_33_S	ATE Test 2
USB_OC0#/ GEVENT12#/TRST	I/O	VDDIO_33_S	JTAG Reset
USB_OC1#/TDI/GEVENT13#	I/O	VDDIO_33_S	JTAG Data In
USB_OC2#/TCK/GEVENT14#	I/O	VDDIO_33_S	JTAG Clock
USB_OC3#/AC_PRES/TDO/ GEVENT15#	I/O	VDDIO_33_S	JTAG Data Out

## 4.19 Integrated Micro-Controller (IMC) Interface

**Table 26. Integrated Micro-Controller Interface Pin Descriptions**

Pin Name	Type	Voltage	Functional Description
EC_PWM0/ EC_TIMER0/ GPIO197	I/O	VDDIO_33_S	IMC PWM 0
EC_PWM1/ EC_TIMER1/ GPIO198	I/O	VDDIO_33_S	IMC PWM 1
EC_PWM2/ EC_TIMER2/ WOL_EN/ GPIO199	I/O	VDDIO_33_S	IMC PWM 2
EC_PWM3/ EC_TIMER3/ GPIO200	I/O	VDDIO_33_S	IMC PWM 3

## 4.20 Consumer Infrared Interface

**Table 27. Consumer Infrared Interface Pin Description**

Pin Name	Type	Voltage	Functional Description
USB_OC4#/IR_RX0/ GEVENT16#	I/O	VDDIO_33_S	Infrared Receive 0. Connection to wideband CIR receiver.
IR_RX1/GEVENT20#	I/O	VDDIO_33_S	Infrared Receive 1. Connection to long-range CIR receiver.
USB_OC5#/IR_TX0/ GEVENT17#	I/O	VDDIO_33_S	Infrared Transmit 0
USB_OC6#/IR_TX1/ GEVENT6#	I/O	VDDIO_33_S	Infrared Transmit 1
IR_LED#/LLB#/ GPIO184	I/O	VDDIO_33_S	Infrared LED

*The following are the possible configurations for CIR*

**No CIR:**

*CIR not used*

**CIR RX with TX0:**

*One RX pin used with TX0*

**CIR RX with TX1:**

*One RX pin used with TX1*

**CIR RX with TX0 and TX1:**

*One RX pin used with TX0 and TX1*

*RX can be RX0 or RX1 except when using wideband CIR, in which case both RX pins need to be used.*

## 4.21 General Purpose I/O and General Event Pins

The GPIO and GEVENT pins of the FCH are multiplexed with other functions. For information on how to configure the GPIO pins for the desired functions, see the *AMD Bolton Fusion Controller Hub Register Reference Guide*.

Table 28 lists all the GPIO and GEVENT pins on the FCH. The Default I/O State column shows the direction and the state of the pin after the core power has become stable ( $VDDCR > \sim 0.8V$ ). The integrated resistor column shows the default status of the internal integrated pull-up/pull-down resistor on the pin after the PCI host bus reset ( $A\_RST\#$ ) is deasserted. The integrated resistor can be enabled/disabled by the system BIOS after boot up.

**Table 28. General Purpose I/O and General Event Pin Descriptions**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
<b>General Events</b>						
GA20IN/ GEVENT0#	I	VDDIO_33_P CIGP (5V tolerance)	null	Input, PU	8.2k PU	General Event 0
KBRST#/ GEVENT1#	I	VDDIO_33_P CIGP (5V tolerance)	KBRST#	Input, PU	8.2k PU	General Event 1 <i>Note: On G3 to S5 transition, the BIOS will not be able to program this pin as Gevent1#. If the pin is used as Gevent1#, the design should ensure that the pin remains in logical high during the G3 → S5 → S0 transition. BIOS can then program this pin as Gevent1# when it is posting.</i>
THRMTRIP#/ SMBALERT#/ GEVENT2#	I/O	VDDIO_33_S	THRM TRIP#	Input	10K PU	General Event 2
PME#/ GEVENT3#	I/O	VDDIO_33_S	null	Input, PU	10K PU	General Event 3

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
PCIE_RST2#/ GEVENT4#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 4
LPC_PD#/ GEVENT5#	I/O	VDDIO_33_S	GEVENT 5#	Input, PU	10k PU	General Event 5
USB_OC6#/ IR_TX1/ GEVENT6#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 6
DDR3_RST#/ GEVENT7#/ VGA_PD	I/O	VDDIO_33_S	DDR3_RST#	Output LOW	10k PU for GEVENT, OD for DDR3_RST#, push-pull and no integrated PU/PD for VGA_PD	General Event 7
WAKE#/ GEVENT8#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 8
SPI_HOLD#/ GBE_LED1/ GEVENT9#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 9
GBE_LED2/ GEVENT10#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 10
GBE_STAT0/ GEVENT11#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 11
USB_OC0#/ GEVENT12#/ TRST	I/O	VDDIO_33_S	GEVENT 12#	Input, PU*	10k PU*	General Event 12 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>
USB_OC1#/ TDI/ GEVENT13#	I/O	VDDIO_33_S	null	Input, PU*	10k PU*	General Event 13 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
USB_OC2#/ TCK/ GEVENT14#	I/O	VDDIO_33_S	null	Input, PU*	10k PU*	General Event 14 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>
USB_OC3#/ AC_PRESEN/ TDO/ GEVENT15#	I/O	VDDIO_33_S	null	Input, PU*	10k PU*	General Event 15 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>
USB_OC4#/ IR_RX0/ GEVENT16#	I/O	VDDIO_33_S	null	Input, PU*	10k PU*	General Event 16 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>
USB_OC5#/ IR_TX0/ GEVENT17#	I/O	VDDIO_33_S	null	Input, PU*	10k PU*	General Event 17 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>
BLINK/ USB_OC7#/ GEVENT18#	I/O	VDDIO_33_S	null	Input, PU*	10k PU*	General Event 18 <i>Note: *Integrated PU is not supported when the pin is configured for USB over current function.</i>
SYS_RESET#/ GEVENT19#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 19
IR_RX1/ GEVENT20#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 20
SPI_CS3#/ GBE_STAT1/ GEVENT21#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 21

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
RI#/GEVENT22#	I/O	VDDIO_33_S	null	Input, PU	10k PU	General Event 22
LPC_SMI#/GEVENT23#	I/O	VDDIO_33_S	null	Input, PU	8.2k PU	General Event 23
S0-domain General Purpose I/O						
AD[31:0]/GPIO[31:0]	I/O	VDDIO_33_P CIGP (5V tolerance)	PCI	Output HIGH	-	GPIO [31:0]
INTE#/GPIO32	I/O	VDDIO_33_P CIGP (5V tolerance)	PCI	Input, PU	8.2k PU	GPIO 32
INTF#/GPIO33	I/O	VDDIO_33_P CIGP (5V tolerance)	PCI	Input, PU	8.2k PU	GPIO 33
INTG#/GPIO34	I/O	VDDIO_33_P CIGP (5V tolerance)	PCI	Input, PU	8.2k PU	GPIO 34
INTH#/GPIO35	I/O	VDDIO_33_P CIGP (5V tolerance)	PCI	Input, PU	8.2k PU	GPIO 35
PCICLK1/ GPO36	O	VDDIO_33_P CIGP (5V tolerance)	PCICLK	Output 33MHz	-	GPO 36
PCICLK2/ GPO37	O	VDDIO_33_P CIGP (5V tolerance)	PCICLK	Output 33MHz	-	GPO 37
PCICLK3/ GPO38	O	VDDIO_33_P CIGP (5V tolerance)	PCICLK	Output 33MHz	-	GPO 38
PCICLK4/ 14M_OSC/ GPO39	O	VDDIO_33_P CIGP (5V tolerance)	PCICLK	Output 14MHz (internal CLKGEN) or 33MHz (external CLKGEN)	-	GPO 39

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
REQ1#/GPIO40	I	VDDIO_33_ PCIGP (5V tolerance)	PCI	Input, PU	15k PU	GPIO 40
REQ2#/ CLK_REQ8#/ GPIO41	I	VDDIO_33_ PCIGP (5V tolerance)	PCI	Input, PU	15k PU	GPIO 41
REQ3#/ CLK_REQ5#/ GPIO42	I	VDDIO_33_ PCIGP (5V tolerance)	PCI	Input, PU	15k PU	GPIO 42
SCL0/GPIO43	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, Tri-State	-	GPIO 43
GNT1#/GPO44	O	VDDIO_33_ PCIGP (5V tolerance)	PCI	Output HIGH	-	GPO 44
GNT2#/ SD_LED/ GPO45	O	VDDIO_33_ PCIGP (5V tolerance)	PCI	Output HIGH	-	GPO 45
GNT3#/ CLK_REQ7#/ GPIO46	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 46
SDA0/GPIO47	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, Tri-State	-	GPIO 47
SERIRQ/ GPIO48	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 48
LDRQ1#/ CLK_REQ6#/ GPIO49	I	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 49
SMARTVOLT1/ SATA_IS2#/ GPIO50	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 50
SMARTVOLT2/ SHUTDOWN#/ GPIO51	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 51

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
FANOUT0/ GPIO52	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 52
FANOUT1/ GPIO53	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 53
FANOUT2/ GPIO54	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 54
SATA_IS4#/ FANOUT3/ GPIO55	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 55
FANIN[2:0]/ GPIO[58:56]	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO [58:56]
SATA_IS5#/ FANIN3/ GPIO59	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 59
CLK_REQ0#/ SATA_IS3#/ GPIO60	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO60
CLK_REQ1#/ FANOUT4/ GPIO61	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 61
CLK_REQ2#/ FANIN4/ GPIO62	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 62
CLK_REQ3#/ SATA_IS1#/ GPIO63	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 63
CLK_REQ4#/ SATA_IS0#/ GPIO64	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 64
CLK_REQG#/ GPIO65/ OSCIN/ IDLEEXIT#	I	VDDIO_33_ PCIGP (5V tolerance)	null	Input, PU	8.2k PU	GPIO 65



**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
SPKR/GPIO66	I/O	VDDIO_33_ PCIGP (5V tolerance)	null	Input, Tri-State	-	GPIO 66
SATA_ACT#/GPIO67	OD	VDDIO_33_ PCIGP (5V tolerance)	null	Input, Tri-State	-	GPIO 67
VGA_HSYNC/GPO68	O	VDDIO_33_ PCIGP	VGA_HS YNC	Tri-State during reset then output low	-	GPO 68
VGA_VSYNC/GPO69	O	VDDIO_33_ PCIGP	VGA_VS YNC	Tri-State during reset then output low	-	GPO 69
VGA_DDC_SDA/GPO70	I/O	VDDIO_33_ PCIGP (5V tolerance)	VGA_DD C_SDA	Tri-State	-	GPO70
VGA_DDC_SCL/GPO71	O	VDDIO_33_ PCIGP (5V tolerance)	VGA_DD C_SCL	Tri-State	-	GPO 71
SD_CLK/SCLK_0/GPIO73	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 73
SD_CMD/SLOAD_0/GPIO74	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 74
SD_CD#/GPIO75	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 75
SD_WP/GPIO76	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 76
SD_DATA0/SDATI_0/GPIO77	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 77
SD_DATA1/SDATO_0/GPIO78	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 78
SD_DATA2/GPIO79	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 79

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
SD_DATA3/ GPIO80	I/O	VDDIO_33_ PCIGP	null	Input, PU	8.2k PU	GPIO 80
<b>S5-Domain General Purpose I/O</b>						
ROM_RST#/ SPI_WP#/ GPIO161	I/O	VDDIO_33_S	ROM_RS T#	Output LOW	-	GPIO 161
SPI_CLK/ GPIO162	I/O	VDDIO_33_S	null or SPI (strap depend- ent)	Input, PD	10k PD	GPIO 162
SPI_DO/ GPIO163	I/O	VDDIO_33_S	null or SPI (strap depend- ent)	Input, PD	10k PD	GPIO 163
SPI_DI/ GPIO164	I/O	VDDIO_33_S	null or SPI (strap depend- ent)	Input, PD	10k PD	GPIO 164
SPI_CS1#/ GPIO165	I/O	VDDIO_33_S	null or SPI (strap depend- ent)	Input, PU	10k PU	GPIO 165
SPI_CS2#/ GBE_STAT2/ GPIO166	I/O	VDDIO_33_S	null or SPI (strap depend- ent)	Input, PU	10k PU	GPIO 166
AZ_SDIN[3:0]/ GPIO[170:167]	I/O	VDDIO_33_S /1.5V_S5	AZ	Input, PD	50k PD	GPIO [17:167]
TEMPIN[2:0]/ GPIO[173:171]	I/O	VDDIO_33_S	null	Input	-	GPIO [173:171]
TEMPIN3/ TALERT#/ GPIO174	I/O	VDDIO_33_S	null	Input	-	GPIO 174
VIN[5:0]/ GPIO[180:175]	I/O	VDDIO_33_S	null	Input	10k PU/PD (disabled by default)	GPIO [180:175]

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
VIN6/ GBE_STAT3/ GPIO181	I/O	VDDIO_33_S	null	Input	-	GPIO 181
VIN7/ GBE_LED3/ GPIO182	I/O	VDDIO_33_S	null	Input	-	GPIO 182
GBE_LED0/ GPIO183	I/O	VDDIO_33_S	null	Input	10k PU	GPIO 183
IR_LED#/ LLB#/GPIO184	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 184
USB_FSD0P/ GPIO185	I/O	VDDIO_33_S	USB	Input, PD	15k PD	GPIO 185
USB_FSD1P/ GPIO186	I/O	VDDIO_33_S	USB	Input, PD	15k PD	GPIO 186
PS2_DAT/ SDA4/GPIO187	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 187
PS2_CLK/ SCL4/GPIO188	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 188
PS2KB_DAT/ GPIO189	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 189
PS2KB_CLK/ GPIO190	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 190
PS2M_DAT/ GPIO191	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 191
PS2M_CLK/ GPIO192	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 192
SCL2/GPIO193	I/O	VDDIO_33_S (5V tolerance)	null	Input, Tri-State	-	GPIO 193
SDA2/GPIO194	I/O	VDDIO_33_S (5V tolerance)	null	Input, Tri-State	-	GPIO 194
SCL3_LV/ GPIO195	I/O	0.8V threshold, VDDIO_33_S domain	null	Input, Tri-State	-	GPIO 195

**Table 28. General Purpose I/O and General Event Pin Descriptions (Continued)**

Pin Name	Type	Level	Default Muxed Function	Default I/O State	Integrated Resistor	Functional Descriptions
SDA3_LV/ GPIO196	I/O	0.8V threshold, VDDIO_33_S domain	null	Input, Tri-State	-	GPIO 196
EC_PWM0/ EC_TIMER0/ GPIO197	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 197
EC_PWM1/ EC_TIMER1/ GPIO198	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 198
EC_PWM2/ EC_TIMER2/ GPIO199	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 199
EC_PWM3/ EC_TIMER3/ GPIO200	I/O	VDDIO_33_S (5V tolerance)	null	Input, PU	10k PU	GPIO 200
KSL_[7:0]/ GPIO[208:201]	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO [208:201]
KSO_[13:0]/ GPIO[222:209]	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO [222:209]
KSO_14/XDB0/ GPIO223	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 223
KSO_15/XDB1/ GPIO224	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 224
KSO_16/XDB2/ GPIO225	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 225
KSO_17/XDB3/ GPIO226	I/O	VDDIO_33_S	null	Input, PU	10k PU	GPIO 226
SCL1/GPIO227	I/O	VDDIO_33_S (5V tolerance)	null	Input, Tri-State	-	GPIO 227
SDA1/GPIO228	I/O	VDDIO_33_S (5V tolerance)	null	Input, Tri-State	-	GPIO 228
ML_VGA_HPD /GPIO229	I/O	VDDIO_33_S	HPD	Output high	-	GPIO 229

## 4.22 Power and Ground Pins

For more information on the power domain, grouping, and power-up sequencing for the power rails, please refer to Section 5.2 “Power Rail Power-up/down Sequence” on page 90.

**Table 29. Power and Ground Pin Descriptions**

Signal Name	Voltage /GND	GND Reference	Note	Description
VDDCR_11_[9:1]	1.1V	VSS	-	Core power
VDDCR_11_S_[2:1]	1.1V	VSS	-	S5 core power
VDDIO_33_S_[8:1]	3.3V	VSS	-	S5 IO power
VDDIO_33_PCIGP[10:1]	3.3V	VSS	-	IO power
VDDIO_AZ_S	1.5V/ 3.3V	VSS	-	HD Audio Interface IO power
VDDXL_33_S	3.3V	VSSXL	1	25MHz XTAL IO power
VDDPL_33_SYS	3.3V	VSSPL_ SYS	2	System clock generator PLLs analog power
VDDPL_11_SYS_S	1.1V	VSSPL_ SYS	2	System clock generator PLLs analog power
VDDAN_11_CLK_[8:1]	1.1V	VSS	2	System clock generator analog/output power
VDDAN_11_ML_[4:1]	1.1V	VSS	-	VGA translator input 1.1V analog power
VDDPL_33_ML	3.3V	VSSPL_ SYS	-	VGA translator input 3.3V analog power
VDDPL_33_PCIE	3.3V	VSS	2	SCL /PCI Express PLL power
VDDAN_11_PCIE_[8:1]	1.1V	VSS	2	SCL / PCI Express analog power
VDDPL_33_SATA	3.3V	VSS	2	SATA PHY PLL power
VDDAN_11_SATA_[10:1]	1.1V	VSS	2	SATA PHY analog/IO power

**Table 29. Power and Ground Pin Descriptions (Continued)**

Signal Name	Voltage /GND	GND Reference	Note	Description
VDDBT_RTC_G	2.5 – 3.6V BAT	VSS	-	RTC/CMOS backup power. Must be present at all time. <i>Notes:</i> <ol style="list-style-type: none"> <li>If the VBAT voltage falls below 1.65V, the CMOS CLR status bit will be set.</li> <li>To force CMOS clear status bit to be set and still maintain the contents of the CMOS the voltage cannot be lowered past 1.55V.</li> <li>If the voltage falls below 1.3V, then all of the contents of the RAM and Real Time Clock is invalid.</li> <li>If the contents of CMOS are not required to be maintained, then the VBAT input of the SOC can be grounded momentarily after the rest of the SOC power rail (S5 and S0) are turned off.</li> </ol>
VDDPL_33_USB_S	3.3V	VSS	2, 3, 4	USB PHY PLL analog power
VDDAN_33_USB_S_[12:1]	3.3V	VSS	2, 3, 4	USB PHY analog/IO power
VDDAN_11_USB_S_[2:1]	1.1V	VSS	2, 3, 5	USB PHY DLL analog power
VDDCR_11_USB_S_[2:1]	1.1V	VSS	3, 5	USB PHY core power
VDDPL_33_SSUSB_S	3.3V	VSS	2, 3, 4	PLL power for super speed USB
VDDAN_11_SSUSB_S_[5:1]	1.1V	VSS	2, 3, 5	Super speed USB analog power
VDDCR_11_SSUSB_S_[4:1]	1.1V	VSS	3, 5	Super speed USB core power
VDDAN_33_HWM_S	3.3V	VSSAN_H WM	-	Hardware monitor interface analog/IO power
VDDAN_33_DAC	3.3V	VSSPL_ DAC	-	DAC 3.3V analog power
VDDPL_33_DAC	3.3V	VSSPL_ DAC	-	DAC 3.3V PLL power
VDDPL_11_DAC	1.1V	VSSPL_ DAC	-	DAC 1.1V PLL power
LDO_CAP	1.8V	VSSPL_ DAC	-	Internally generated 1.8V supply for the RGB outputs
VSS	GND	-	-	Digital ground (plane)
VSSXL	GND	-	-	25MHz XTAL ground
VSSPL_SYS	GND	-	-	System clock generator PLLs common ground

**Table 29. Power and Ground Pin Descriptions (Continued)**

Signal Name	Voltage /GND	GND Reference	Note	Description
VSSAN_HWM	GND	-	-	Hardware monitor interface analog ground
VSSIO_DAC	GND	-	-	DAC IO ground
VSSAN_DAC	GND	-	-	DAC analog ground
VSSANQ_DAC	GND	-	-	DAC analog bias ground
VSSPL_DAC	GND	-	-	DAC PLL ground

**Notes:**

1. These power rails can be tied to S0-S5 or S0-S3, depending on whether WakeOnLan, USB 3.0 Wakemode is supported. See Table 37.
2. These power rails should be filtered.
3. These power rails can be tied to S0-S5 or S0-S3 power depending on whether wake from S4/S5 is supported or not.
4. VDDPL\_33\_USB\_S and VDDAN\_33\_USB\_S\_[12:1] should be sourced from the same voltage regulator and have traces routed close together to minimize voltage droop difference.
5. VDDAN\_11\_USB\_S\_[2:1] and VDDCR\_11\_USB\_S\_[2:1] should be sourced from the same voltage regulator and have traces routed close together to minimize voltage drop difference.

## 4.23 Miscellaneous Pins

**Table 30. Miscellaneous Pin Descriptions**

Pin Name	Functional Description
NC[x]	No Connect
<i>Note: GbE is not supported. The greyed out pins below are not used and must be connected or not connected as described.</i>	
GBE_COL	No Connect
GBE_CRG	No Connect
GBE_MDCK	No Connect
GBE_MDIO	No Connect
GBE_RXCLK	No Connect
GBE_RXD[3:0]	No Connect
GBE_RXCTL/RXDV	No Connect
GBE_RXERR	No Connect
GBE_TXCLK	No Connect
GBE_TXD[3:0]	No Connect

**Table 30. Miscellaneous Pin Descriptions (Continued)**

GBE_TXCTL/TXEN	No Connect
GBE_PHY_PD	No Connect
GBE_PHY_RST#	No Connect
GBE_PHY_INTR	Not used. Terminate as per the <i>AMD Bolton Fusion Controller Hub Motherboard Design Guide</i> , order# 51206
VDDIO_GBE_S[2:1]	Not used. Terminate as per the <i>AMD Bolton Fusion Controller Hub Motherboard Design Guide</i> , order# 51206
VDDIO_33_GBE_S	Not used. Terminate as per the <i>AMD Bolton Fusion Controller Hub Motherboard Design Guide</i> , order# 51206
VDDCR_11_GBE_S[2:1]	Not used. Terminate as per the <i>AMD Bolton Fusion Controller Hub Motherboard Design Guide</i> , order# 51206

## 4.24 Integrated Resistors

Table 31 shows the pins that have an integrated resistor on their pad and the resistor's nature (pull-up or pull-down) and value. In general, the integrated resistors are enabled by default, but can be changed by programming. The table does NOT include information for any GPIO or GEVENT pins, for which one should refer to Table 28 in Section 4.21 "General Purpose I/O and General Event Pins" on page 67.

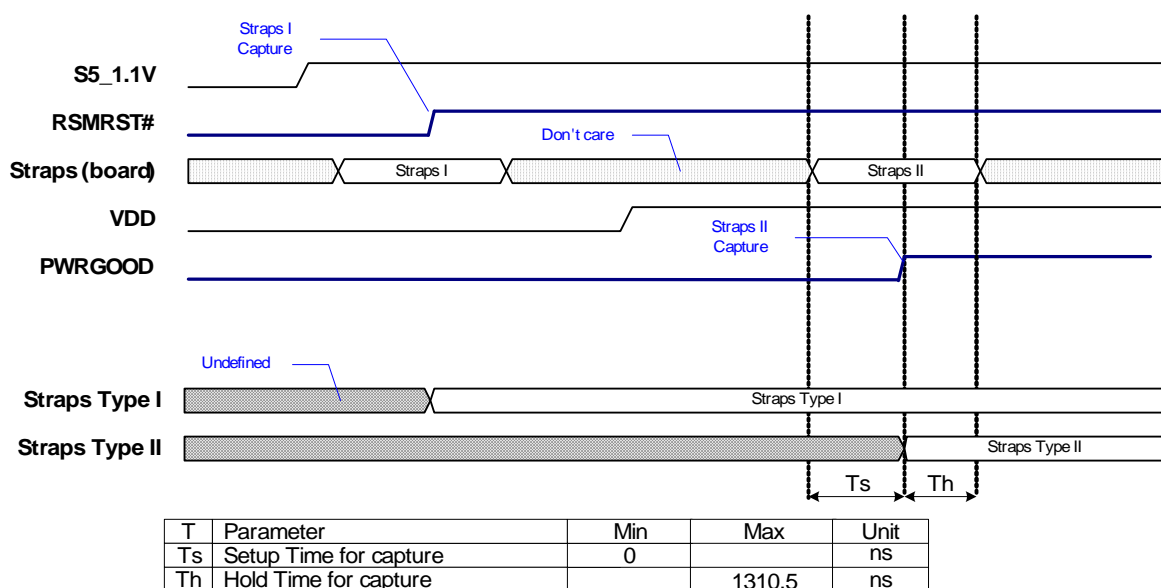
**Table 31. Pins with Integrated Resistors (Excluding GPIO/GEVENT Pins)**

Interface	Pin	Resistor Type/Requirement
LPC	LAD[3:0]	10k pull up
	LDRQ0#	10k pull up
	CLKRUN#	7.5k pull up
	DEVSEL#	7.5k pull up
	FRAME#	7.5k pull up
	IRDY#	7.5k pull up
	LOCK#	7.5k pull up
	PERR#	7.5k pull up
	REQ[3:0]#	15k pull up
	SERR#	7.5k pull up
	STOP#	7.5k pull up
TRDY#	7.5k pull up	
RTC	RTCCLK	10k pull up
	RSMRST#	10k pull up (cannot be disabled)



## 4.25 Strap Information

Two types of straps are captured on the rising edge of RSMRST# and PWR\_GOOD—Type I and Type II. Type I straps become valid immediately after capture on the rising edge of RSMRST#. Modules in the S5 power well use this type of straps, which are captured only once when power is first applied to the chip. All other straps (type II) become valid after PWR\_GOOD is asserted in order to prevent the strap logic that resides in the standby power well from being driven by un-powered logic. Type II straps are captured every time the system powers up from the S5 state. A transition from S3 to S0 does not trigger capture.



**Figure 13. Straps Capture Timing**

Straps are also classified into two groups—standard and debug. Standard straps are required for selecting different chip options at power-up. Debug straps are used for debugging purposes only and do not require population for production boards. However, provisions for connecting pull-ups or pull-downs on the debug strap signals should be made if they are not used for normal system operation.

Table 32 and Table 33 show the function of every strap signal in the design. All straps are defined such that in the most likely scenario of operation, they will be set to the recommended (or safest) values by default. The values shown in the Description column are the external board strap values, with 3.3V being a pull up and 0V a pull down.

Table 32. Standard Straps

Ball Name*	Strap Name	Type	Default Value	Description
LPCCLK0	ECEnableStrap	I	-	Enable Integrated Micro-Controller 0V – Disable 3.3V – Enable This strap has to be enabled to support enhanced hardware monitor features.
EC_PWM2	{ROMTYPE_0 }	I	-	ROMTYPE_0ROM Type 0VSPI ROM 3.3VLPC ROM
RTCCLK	S5 Plus Mode	I	-	Set S5 Plus Mode 0V – Enable 3.3V – Disable
LPCCLK1	CLKGEN	II	-	Defines clock generator. 0V – External clock mode: Use 100 MHz PCIe® clock as reference clock and generate internal clocks only. 3.3V – Integrated clock mode: Use 25MHz crystal clock and generate both internal and external clocks.
PCICLK1	BIF_GEN2_COMPLIANCE_Strap	II	-	Set PCIe to Gen II mode. 0V – Force PCIe interface at Gen I mode. 3.3V – PCIe interface is at Gen II mode.
PCICLK3	DefaultStrapMode	II	-	Default Debug Straps 0V – Disable Debug Straps. 3.3V – Select external Debug Straps (see Table 33).
PCICLK4	CPUClkSel	II	-	APU_CLKP/N and DISP_CLKP/N Clock Selection 0V – Required setting for integrated clock mode. 3.3V – Reserved. This strap is not used if the strap CLKGEN is configured for external clock generator mode.
<b>Note:</b> * For clarity's sake, ball names for strap pins given in this table are truncated to show only the beginning parts. Refer to the pins lists in Appendix A for the complete ball names.				

**Table 33. Debug Straps**

Ball Name	Strap Name	Type	Default Value	Description
AD27	PciPllByp	II	3.3V (Internal PU of 15kΩ)	Bypass PCI PLL (used in functional test at tester) 0V – Bypass internal PLL clock. Use xSPciReqB_1_ as SPCI33 bypass clock. Use xSPciReqB_2_ as A-Link bypass clock. Use xSPciGntB_1_ as B-Link bypass clock. Use xSPciGntB_0_ as B-Link266 bypass clock. 3.3V – Use internal PLL-generated PLL CLK.
AD24	I2CRomEn	II	3.3V (Internal PU of 15kΩ)	I2C ROM enable. Load the settings for SCL/PLL/ misc control from I2C ROM. 0V – Getting the value from I2C EPROM. I2C EPROM ADDRESS set to all zeroes. Use REQ3# as SDA. Use GNT3# as SCL. 3.3V – Disable I2C ROM
AD23	PCI_ROM_ BOOT	II	3.3V (Internal PU of 15kΩ)	Booting from PCI memory 0V – Route ROM fetch to PCI bus on the very first boot. Use ROMTYPE to determine the ROM type on subsequent boots. 3.3V – Use ROMTYPE straps to determine the ROM type.



# Chapter 5 Power Sequence and Timing

This chapter describes the power-on sequences and other timing data for the Bolton-E4 FCH.

## 5.1 Power-up/down Sequence

Figure 14 on page 85 and Figure 15 on page 86 illustrate respectively the power-up/down sequences for ACPI S5-to- S0 -to- S5 and S3-to- S0-to-S3 transitions.

Table 34, Table 35, and Table 36 give the timing values.

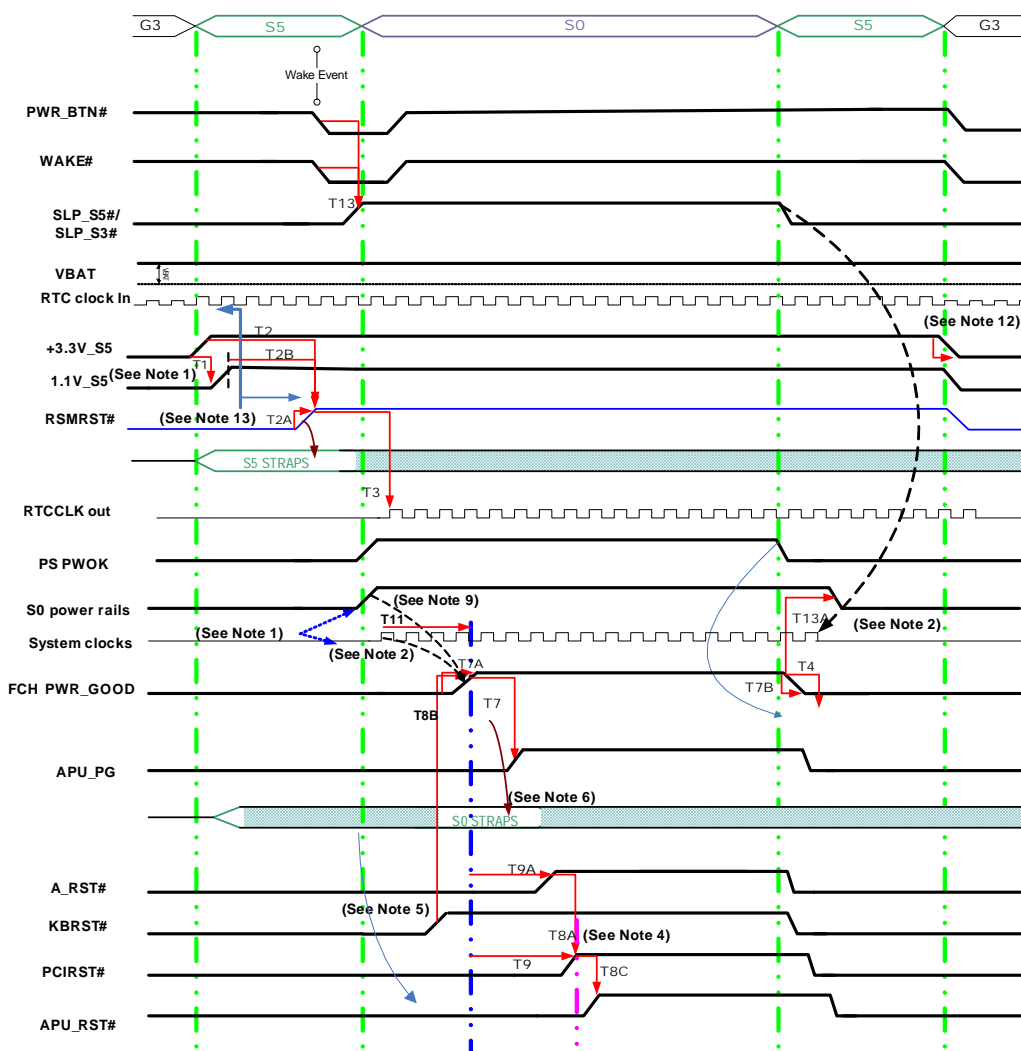


Figure 14. FCH Power Sequence (S5-to-S0-to-S5)

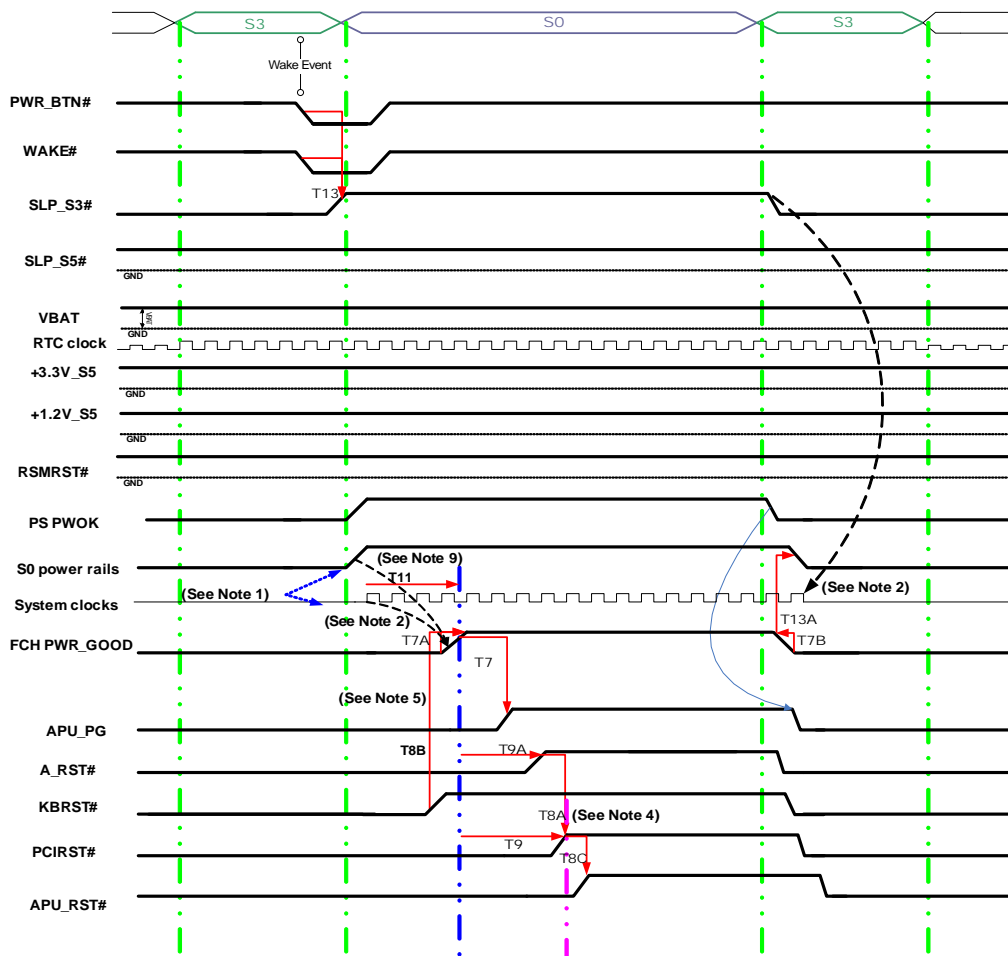


Figure 15. FCH Power Sequence (S3 to S0 to S3)

Table 34. Power Sequence Timing

Symbol	Minimum	Maximum	Description
T1	Note 1 of Section 5.1.1		+3.3V_S5 to +1.1V_S5
T2	10 ms	–	+3.3V_S5 to resume reset (RSMRST#)
T2B	(See Description)		+1.1V_S5 should ramp up to nominal voltage before resume reset (RSMRST#) is de-asserted.
T2A	–	50 ms	Resume reset (RSMRST#) rise time (10% to 90%). See Note 11 of Section 5.1.1.
T3	16 ms	–	RSMRST# de-asserted to start of RTCCLK output from the FCH.

**Table 34. Power Sequence Timing (Continued)**

Symbol	Minimum	Maximum	Description
T7			See Table 35 and Table 36 on page 88 .
T7A	–	50 ms	FCH PWR_GOOD rise time (10% to 90 %). See Note 3 of Section 5.1.1 “Power up Sequence Timing Notes” on page 88.
T7B	–	1 ms	FCH PWR_GOOD fall time.
T8A	0 ns Note 4 of Section 5.1.1	100 ns	A_RST# (PCI host bus reset) to PCIRST#.
T8B	–	Note 5 of Section 5.1.1	KBRST# to FCH PWR_GOOD.
T8C	1.0 ms	2.3 ms	PCIRST# to APU_RST#.
T9	101 ms	113 ms	FCH PWR_GOOD to PCIRST#.
T9A	101 ms	113 ms	FCH PWR_GOOD to A_RST# (T9-T8A).
T13	–	15 ns	Wake Event (except PwrButton) to SLP_S3# / SLP_S5# de-assertion. See Note 14 of Section 5.1.1 “Power up Sequence Timing Notes” on page 88.
		16 ms	Wake Event (PwrButton) to SLP_S3# / SLP_S5# de-assertion.
T13A	80 ns	–	FCH PWR_GOOD must be de-asserted before VDD (PS PWOK) drops more than 5% off the nominal value. See Note 9 of Section 5.1.1 “Power up Sequence Timing Notes” on page 88.
T14	1 ns	–	FCH PWR_GOOD de-assertion to Resume Reset (RSMRST#) assertion. See Note 10 of Section 5.1.1 “Power up Sequence Timing Notes” on page 88.
T15	5 s	–	[Not illustrated] VBAT to +3.3V_S5 to +1.1V_S5. Must be greater than 5 seconds to allow start time for the internal RTC.
T16A	40 μs	–	[Not illustrated] APU_STP# assertion to APU_RST# assertion.
T16B	4 μs	–	[Not illustrated] APU_RST# assertion to SLP_S3# assertion.

**Table 35. FCH PWR\_GOOD and System Clock Timing (Internal Clock Mode Only)**

Symbol	Minimum	Maximum	Description
T7	98 ms	150 ms	FCH PWR_GOOD assertion to APU_PG assertion delay.
T11B	–	39 ms	[Not illustrated] FCH PWR_GOOD to clock out stable.

**Table 36. FCH PWR\_GOOD and System Clock Timing (External Clock Mode Only)**

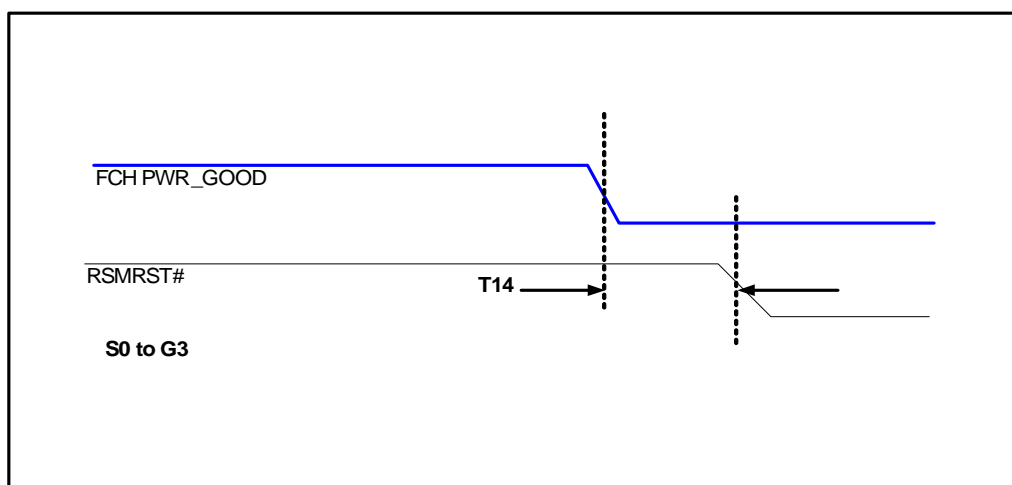
Symbol	Min.	Max.	Description
T7	77 ms	108 ms	FCH PWR_GOOD assertion to APU_PWRGD assertion delay when using the FCH APU_PG output.
T11	–	Note 2 of Section 5.1.1	[Not illustrated] Stable system clocks (25MHz, SRC (PCIe), OSC, 48MHz) to FCH PWR_GOOD when using external clock generator.

### 5.1.1 Power up Sequence Timing Notes

#### Notes:

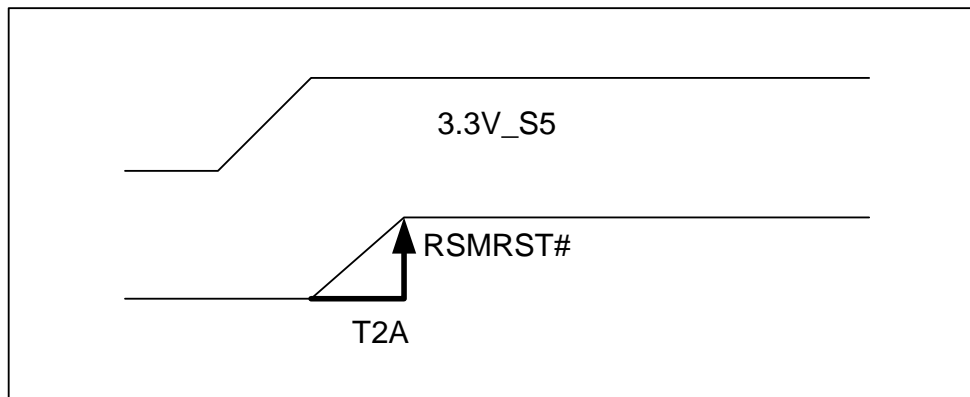
1. Refer to Section 5.2 “Power Rail Power-up/down Sequence” on page 90 for the power rail power-up/down requirements.
2. All system clocks should be stable before the assertion of FCH PWR\_GOOD. Refer to the external clock specification for the timing  $T_{STAB}$ , the time it takes for the external clock chip to provide stable clocks after valid power is applied. If the FCH and the external clock chip share power rails, this parameter needs to be taken into account when considering the FCH PWR\_GOOD assertion timing. Typical value for  $T_{STAB}$  is 1.8 ms. All system clocks should be stopped after SLP\_S3# is asserted when transitioning to sleep states; clock generator power-down sequencing should be adjusted accordingly to meet this requirement.
3. The FCH will latch the straps after rising edge of FCH PWR\_GOOD only once. With de-bouncing of FCH PWR\_GOOD, the latching of strap will occur at approximately ~10ms after the rising edge of FCH PWR\_GOOD.
4. Typical time between A\_RST# and PCIRST# is 75 ns. The measurement should be performed at 10% of both signals. Loading on the motherboard may cause the measurement at 90% to be more than the specified value.
5. The KBRST# should be de-asserted before FCH PWR\_GOOD is de-asserted.
6. Type II Standard and Debug straps will be latched after FCH PWR\_GOOD is asserted. Type I straps are latched on resume reset rising edge.
7. FCH PWR\_GOOD Assertion: The FCH PWR\_GOOD should be asserted after all S0 power rails have ramped up to 90% of their nominal value. FCH PWR\_GOOD de-assertion: The FCH will monitor internally the power down events and protect the internal circuit during the power down event. This includes power down during the S3, S4, and S5 states. During an unexpected power failure or G3 state, the relationship between the +1.1 V (VDDCR) and FCH PWR\_GOOD should be maintained to protect the internal logic of the FCH.
8. The following figure shows the timing of FCH PWR\_GOOD de-asserted to RSMRST# de-asserted during a power down sequence. However, this timing only applies to S0-to-G3 state transition, because G3 state is where both signals are inactivated.





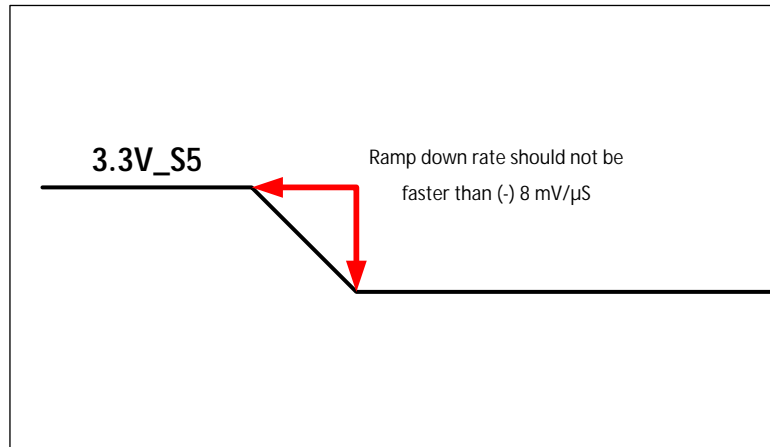
**Figure 16. Timing for FCH PWR\_GOOD De-asserted to RSMRST# De-asserted**

9. When measuring the RSMRST# timing T2A, the loading of the motherboard PCB trace may cause a slow rise time, which should be taken in account. See Figure 17 below.



**Figure 17. Measurement for RSMRST# Timing (T2A)**

10. The ramp down rate of the 3.3V\_S5 rail should not be faster than (-) 8 mV/ $\mu$ S. See Figure 18 on page 90.



**Figure 18. 3.3V\_S5 Power-down Sequence Requirement**

11. VBAT powers the RTC clock input to the FCH. The RTC clock must be functional before de-assertion of RSMRST#; therefore, the VBAT power ramp up time relative to RSMRST# may need to be controlled. Typical start time is 5 seconds, but the value varies with different crystals.
12. The maximum time represents the time FCH's internal logic will take to start driving SLP\_S3# / SLP\_S5#. The net delay time may be dominated by onboard loading which can be far greater than the silicon intrinsic delay.

## 5.2 Power Rail Power-up/down Sequence

The Bolton-E4 FCH power rails can be broadly divided into the following two groups:

- +3.3V and +1.1 V voltage rails that are ON in S0 to S5 states. Rails in this group have the suffix “\_S” at the end of their names.
- +3.3V and +1.1V voltage rails that are ON in S0 state but turned OFF in S3 to S5 states. Rails in this group do not have the suffix “\_S” at the end of their names.

Table 37 shows how the FCH voltage rails are divided into these two groups. Some of the “\_S” domain voltage rails can be connected to “non-\_S” domain voltage rails depending on the feature set supported, as explained in the “Note” column.

**Table 37. FCH Voltage Rail Grouping**

Voltage Rail	+3.3/1.1V_S5	+3.3/1.1V_S0	Note
VDDIO_33_S	x		-
VDDAN_33_USB_S	x		-
VDDAN_33_HWM_S	x		-
VDDPL_33_USB_S	x		-.

**Table 37. FCH Voltage Rail Grouping**

Voltage Rail	+3.3/1.1V_S5	+3.3/1.1V_S0	Note
VDDPL_33_SSUSB_S	x	x	VDDPL_33_SSUSB_S should be tied to +3.3V_S5 rail if USB 3.0 Wake is supported; otherwise, it can be tied to +3.3V_S0 rail. If USB 3.0 is not used at all, it can be tied to GND.
VDDXL_33_S	x	x	VDDXL_33_S should be tied to +3.3V_S5 rail if USB 3.0 Wake is supported; otherwise, it can be tied to +3.3V_S0 rail.
VDDIO_33_PCIGP		x	-
VDDPL_33_SYS		x	-
VDDPL_33_PCIE		x	-
VDDPL_33_SATA		x	-
VDDPL_33_DAC		x	VDDPL_33_DAC, VDDPL_33_ML, VDDAN_33_DAC should be tied to +3.3V_S0 rail if the VGA translator function is supported. If the VGA translator is not used at all, these power rails can be tied to GND.
VDDPL_33_ML		x	
VDDAN_33_DAC		x	
VDDCR_11_S	x		-
VDDCR_11_USB_S	x		-
VDDPL_11_SYS_S	x	x	VDDPL_11_SYS_S should be tied to +1.1V_S5 rail if USB 3.0 Wake is supported; otherwise, it can be tied to +1.1V_S0 rail.
VDDCR_11_SSUSB_S	x	x	VDDCR_11_SSUSB_S should be tied to +1.1V_S5 rail if USB 3.0 Wake is supported; otherwise, it can be tied to +1.1V_S0 rail. If USB 3.0 is not used at all, it can be tied to GND.
VDDCR_11		x	-
VDDAN_11_SATA		x	-
VDDAN_11_PCIE		x	-
VDDAN_11_CLK		x	-

**Table 37. FCH Voltage Rail Grouping**

Voltage Rail	+3.3/1.1V_S5	+3.3/1.1V_S0	Note
VDDAN_11_ML		x	Tie to GND if VGA interface is not enabled.
VDDAN_11_SSUSB_S	x	x	VDDAN_11_SSUSB_S should be tied to +1.1V_S5 rail if USB 3.0 Wake is supported; otherwise, it can be tied to +1.1V_S0 rail. If USB 3.0 is not used at all, it can be tied to GND.
VDDPL_11_DAC		x	Tie to GND if VGA interface is not enabled.
VDDIO_AZ_S	x	x	Though the rail's voltage is 3.3V/1.5V, it follows the same power-rail power-up/down requirements for the 3.3V/1.1V rails as described in this section. It is thus classified here as belonging to either the 3.3V/1.1V_S5 or the 3.3V/1.1V_S0 rail group with respect to the power-up/down requirements, according to the following conditions: <b>Wake on Ring supported:</b> Tie to +3.3/1.5V_S5 rail, and treat like a 3.3/1.1V_S5 rail. <b>Wake on Ring not supported:</b> Tie to +3.3/1.5V_S0 rail, and treat like a 3.3/1.1V_S0 rail.

Within each of the +3.3 /1.1 V\_S5 or +3.3 /1.1 V\_S0 power rail groups, rails of the same voltage (3.3 V or 1.1 V) should be powered up at the same time. However, there are no required sequencing relationships between the 3.3-V rails and the 1.1-V rails.

Although there are no power rail sequencing requirements between any specific power rail groups (except for VBAT—see explanations below), customers can use the power rail power-up sequence shown in Figure 19 and Table 38 below as a reference. All of the AMD Bolton-E4 reference platforms are designed to follow that reference power-up sequence.

For power-down sequence, power rails on reference platforms should either be powered-down at the same time or in the reverse order of the power-up sequence shown below.

The only mandatory requirement for power rail sequencing is that VBAT (VDDBT\_RTC\_G) must ramp at least 5 seconds before the S5 rails to allow start time for the external RTC crystal.

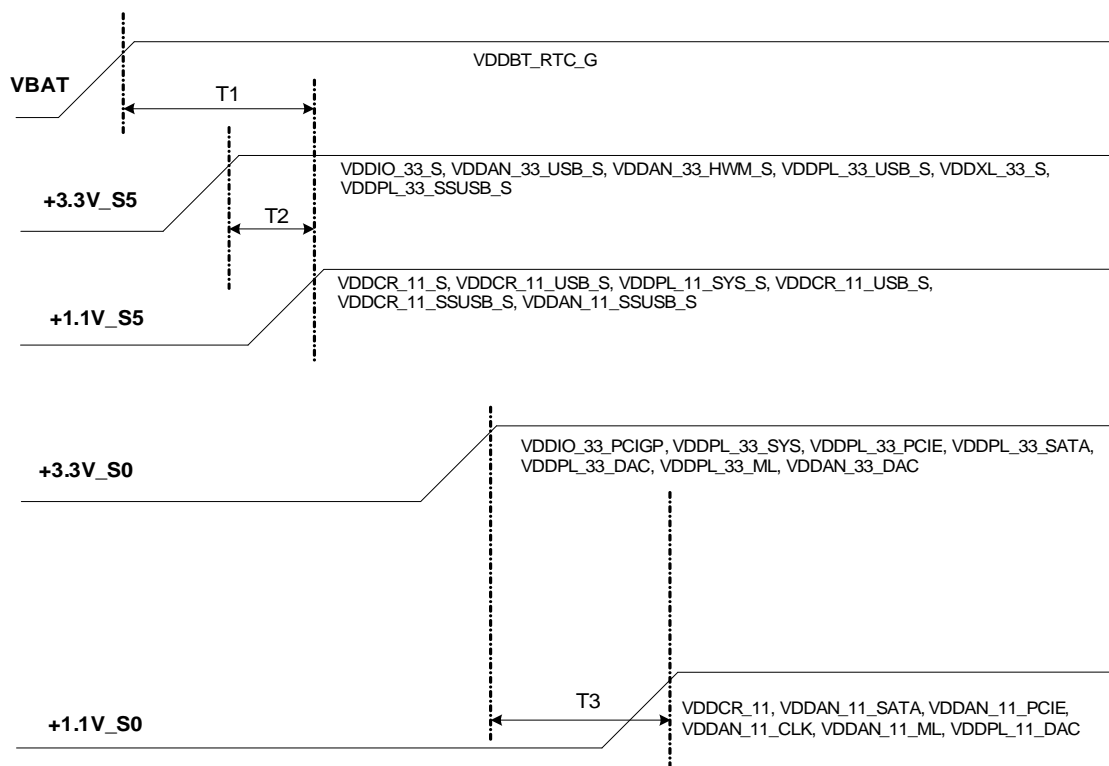


Figure 19. Power Rail Power-up Sequence Requirements

Table 38. Power Rail Power-up Sequence Requirements

Symbol	Parameter	Voltage Difference during Ramping	
		Minimum (V)	Maximum (V)
T1	VBAT to the S5 rails	VDDBT_RTC_G must ramp at least 5 seconds before the S5 rails.	No restrictions
T2	+3.3V_S5 rails ramp high relative to +1.1V_S5 rails	0	No restrictions*
T3	+3.3V_S0 rails ramp high relative to +1.1V_S0 rails	0	No restrictions*

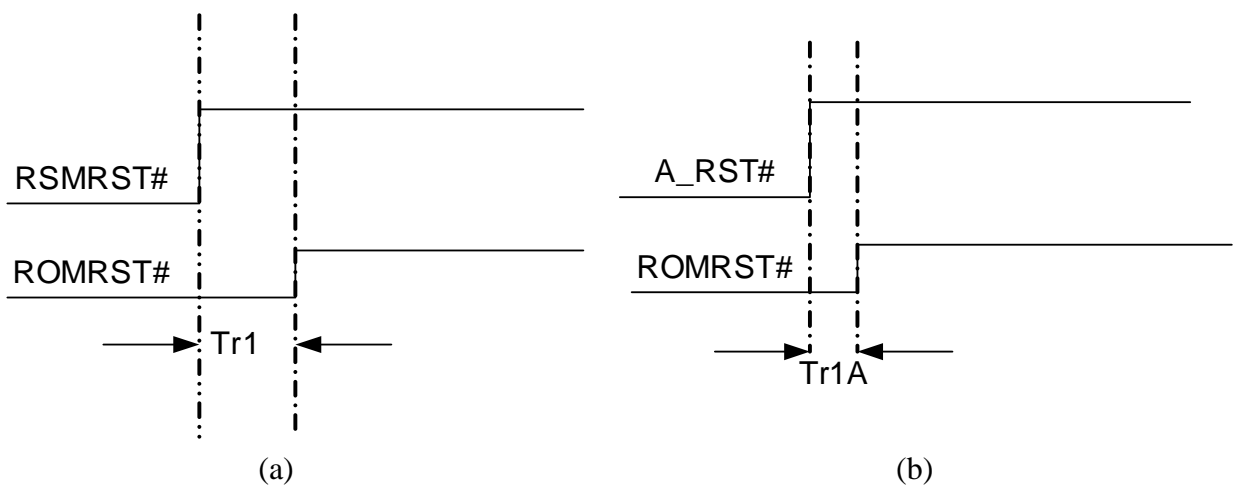
*\*Note: Power rails from the same group are assumed to be generated from the same regulator; however, they can be generated from different regulators as long as they come up at the same time.*

### 5.3 Reset Timings

The FCH controls the system reset signal timings, which are provided in this section. ROMRST# timing is shown with respect to RSMRST# and A\_RST# signals in Figure 20 (a) and (b). ROM\_RST can be generated on the system board using either the RSMRST# or A\_RST# signal depending on the platform configurations, and Table 40 on page 95, indicates the timing figure and label that apply in each situation.

**Table 39. ROM Reset Timing Figure for Various Platform Configurations**

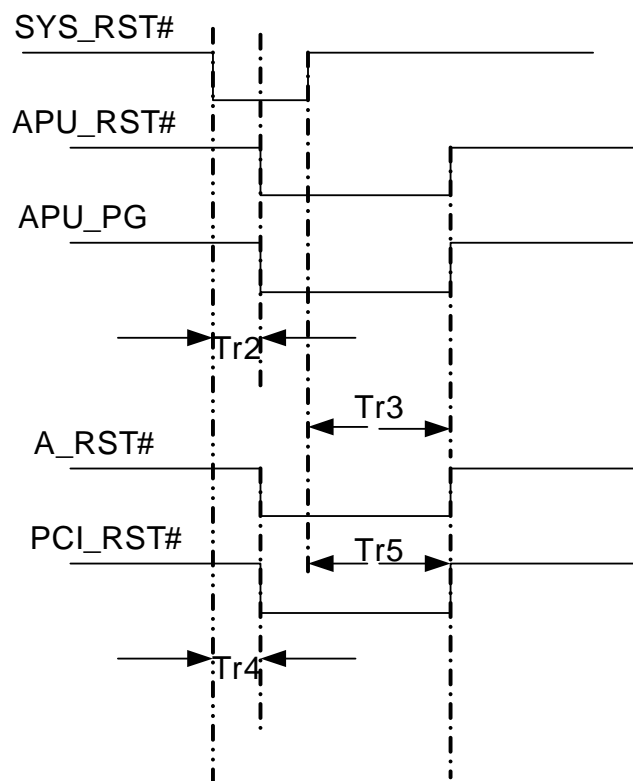
IMC Enabled	ROM Reset Timing Figure
Y	Figure 20 (a)
N	Figure 20 (b)



**Figure 20. ROM Reset Timing**

Figure 21 on page 95 shows the timing of APU\_RST#, APU\_PG, A\_RST#, and PCI\_RST# with respect to the SYS\_RST# signal when SYS\_RST# is used to force a system reset. SYS\_RST# and RSMRST# signals are input to the FCH and are generated on the system board.

Table 40 on page 95 shows the values of all the timing labels.



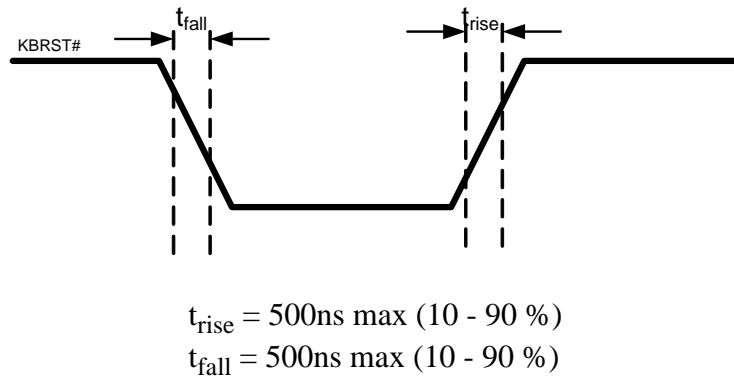
**Figure 21. Reset Timing Requirements**

**Table 40. Reset Timing Requirements**

Symbol	Parameter	Min	Typical	Max
Tr1	RSMRST# to ROMRST# (ROMRST# is generated from RSMRST#.)	48 ms	-	58 ms
Tr1A	A_RST# to ROMRST# (ROMRST# is generated from A_RST#)	-	-	100 ns
Tr2	SYS_RESET# assertion to APU_RST# assertion	-	8 ms	-
	SYS_RESET# assertion to APU_PG de-assertion	-	8 ms	-
Tr3	SYS_RESET# de-assertion to A_RST# de-assertion	-	230 ms	-
Tr4	SYS_RESET# assertion to A_RST# assertion	-	8.05 ms	-
	SYS_RESET# assertion to PCI_RST# assertion	-	8.1 ms	-
Tr5	SYS_RESET# de-assertion to PCI_RST# de-assertion	-	231 ms	

### 5.3.1 KBRST# Timing Requirements

KBRST# rise and fall time requirements are shown in Figure 22 .

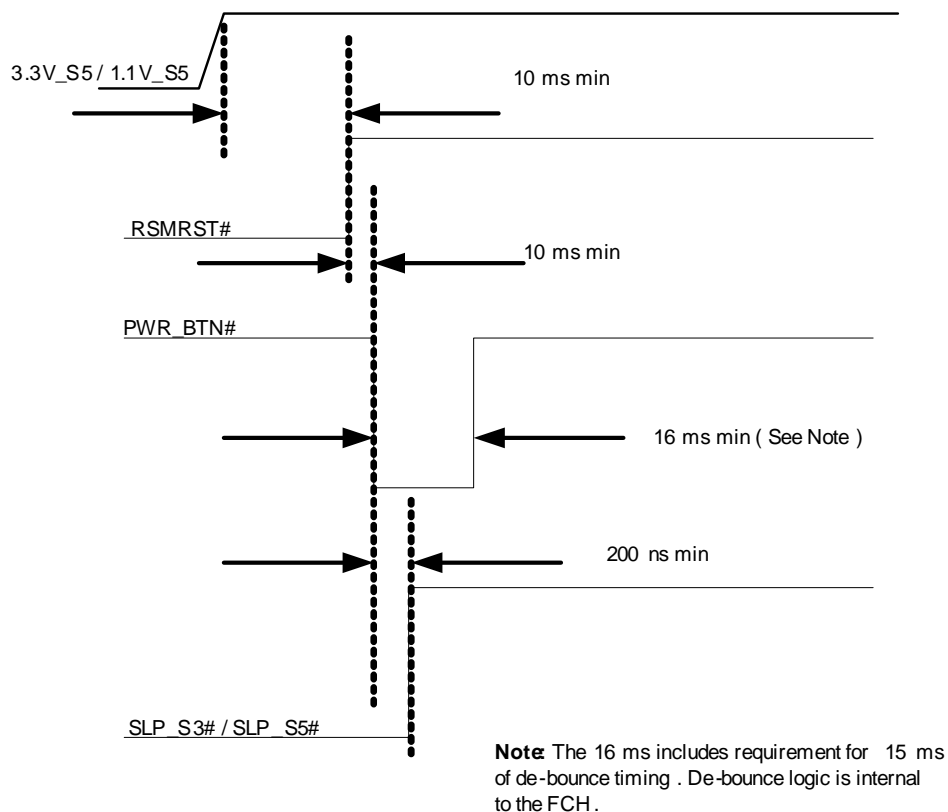


**Figure 22. Timing Requirements for KBRST#**



## 5.4 Power Button Timing

Figure 23 illustrates various timing values related to the assertion and de-assertion of the power button.



**Figure 23. Power Button Timing**



## Chapter 6 Electrical Characteristics

*Note:* Values quoted in this section are preliminary and require further verification.

### 6.1 Power Rail Specifications

#### 6.1.1 Absolute Ratings

To prevent damage to the ASIC, the voltage applied to each power rail should not exceed 10% of its nominal voltage, nor should it fall below -0.5V with respect to VSS.

#### 6.1.2 Operating Range

For proper operation of the ASIC, voltages of all power rails should stay within +/- 5% of their nominal values. Voltages, measured at the ball of the ASIC, must stay within the range of tolerance in spite of any DC transients or AC noises of frequencies less than 2 MHz.

### 6.2 DC Characteristics

**Table 41. DC Characteristics of the GPIO Pins**

Symbol	Parameter	Minimum	Maximum	Unit	Condition
VDDQ	I/O power	3.0	3.46	V	
VIL	Input Low Voltage	-	1.5	V	
VIH	Input High Voltage	1.5	-	V	
VOL	Output Low Voltage	-	0.4	V	IOL = 8.0 mA (Note 1)
VOH	Output High Voltage	2.4	-	V	IOH = 8.0 mA (Note 1, 2)
ILI	Input Leakage Current	-	10	μA	Only applicable when the integrated resistors are not enabled.
CIN	Input Capacitance	-	10	pF	Only applicable when the integrated resistors are not enabled.

**Notes:**

1. For the GEVENT9# and GEVENT10# pads, the IOL and IOH are programmable to values between 4 and 8 mA.
2. VOH specifications are not applicable to I/OD or OD signals.

**Table 42. DC Characteristics of the PCI Interface**

Symbol	Parameter	Minimum	Maximum	Unit	Condition
VDDQ	I/O power	3.0	3.46	V	
VIL	Input Low Threshold	-	0.3VDD	V	
VIH	Input High Threshold	0.3VDD	-	V	
VOL	Output Low Voltage	-	0.4	V	IOL = 4.0 mA to 12.0 mA
VOH*	Output High Voltage	2.4	-	V	IOH = -4.0 mA to 12 mA
ILI	Input Leakage Current	-	10	μA	Only applicable when the integrated resistors are not enabled.
CIN	Input Capacitance	-	10	pF	Only applicable when the integrated resistors are not enabled.

**Note:** \*VOH specifications are not applicable to I/OD or OD signals.

**Table 43. DC Characteristics of the APU Interface**

Symbol	Parameter	Minimum	Maximum	Unit	Condition
<b>DMA_ACTIVE#</b>					
VCPU_IO	CPU IO Voltage	-	-	V	OD signal
VOL	Output Low Voltage	-	0.4	V	IOL = 8.0 mA
<b>APU_PG, APU_RST#</b>					
VDDQ	I/O power			V	OD signal
VOL	Output Low Voltage	-	0.4	V	IOL = 8.0 mA

**Table 44. DC Characteristics of RSMRST#**

Symbol	Parameter	Minimum	Maximum	Unit	Condition
3.3V_S5	Core standby power	3.0	3.46	V	
VIL	Input Low Voltage	-	1.5	V	
VIH	Input High Voltage	1.5	-	V	
ILI	Input Leakage Current	-	10	μA	
CIN	Input Capacitance	-	10	pf	

**Table 45. DC Characteristics of PWR\_GOOD**

Symbol	Parameter	Minimum	Maximum	Unit	Condition
VDDQ	I/O power	3.0	3.46	V	
VIL	Input Low Voltage	-	1.5	V	
VIH	Input High Voltage	1.5	-	V	
ILI	Input Leakage Current	-	10	$\mu$ A	
CIN	Input Capacitance	-	10	pf	

**Table 46. DC Characteristics of the LPC Interface**

Symbol	Parameter	Minimum	Maximum	Unit	Condition
VDDQ	I/O power	3.0	3.46	V	
VIL	Input Low Threshold	-	0.3VDD	V	
VIH	Input High Threshold	0.3VDD	-	V	
VOL	Output Low Voltage	-	0.4	V	IOL = 4.0 mA to 12 .0 mA
VOH	Output High Voltage	2.4	-	V	IOH = -4.0 mA to 12 mA
ILI	Input Leakage Current	-	10	$\mu$ A	Only applicable when the integrated resistors are not enabled. Not applicable to LDRQ[1:0]#.
CIN	Input Capacitance	-	10	pF	Only applicable when the integrated resistors are not enabled. Not applicable to LDRQ[1:0]#.

## 6.3 RTC Battery Current Consumption

The RTC battery current consumption is estimated as follows:

**Table 47. RTC Battery Current Consumption (Preliminary Estimates)**

Power State	RTC Battery Current	
	Typical	Maximum
G3 (Off)	< 3 $\mu$ A	< 4.5 $\mu$ A
S0-S5	< 0.2 $\mu$ A	-

The RTC battery life is calculated using the rated capacity of the battery and the typical current numbers. The typical batteries used for the RTC are normally rated for 170 mAh, and the worst case current consumption for the FCH is 4.5  $\mu$ A, according to Table 47 on page 101. Thus, the minimum life of the battery can be calculated as follows:

$$170,000 \mu\text{Ah} / 4.5 \mu\text{A} = 38,000 \text{ h} \cong 4.3 \text{ years}$$

## 6.4 States of Power Rails during ACPI S3 to S5 States

Please refer to Section 5.2 “Power Rail Power-up/down Sequence” on page 90.

## 6.5 System Clock Specifications

### 6.5.1 System Clock Descriptions

**Table 48. System Clock Input Source Descriptions**

Clock Domain	Frequency	Source	Usage
25M_X1, 25M_X2	25 MHz	25-MHz Crystal	Master reference clock for the FCH for internal clock mode
PCIE_RCLKP, PCIE_RCLKN	100 MHz	Main clock generator	Reference clock for the FCH for external clock mode.
SATA_X1, SATA_X2	25 MHz	25-MHz Crystal	For SATA Controllers
32K_X1, 32K_X2	32 KHz	32-KHz Crystal	For RTC
USBCLK	48 MHz	48-MHz OSC or internal USB 48-MHz PLL	For USB Controllers and HD Audio

### 6.5.2 System Clock Input Frequency Specifications

**Table 49. System Clock Input Frequency Specifications**

Clock	Frequency
25M_X1, 25M_X2	25.000 MHz $\pm$ 50 ppm
USBCLK	48.000 MHz $\pm$ 100 ppm
SATA_X1, SATA_X2	25.000 MHz $\pm$ 50 ppm

## 6.5.3 AC Specifications

### 6.5.3.1 System Clock Output AC Specifications

**GPP\_CLKP/N, SLT\_GFX\_CLKP/N, and DISP2\_CLKP/N:** These clocks are compliant with the PCI Express® Specification 2.0. Please refer to the *PCI Express CEM 2.0 Specification* for the clocks' AC and DC specifications for the clocks.

**Table 50. DISP\_CLKP/N AC Specifications: (Non-Spread Clock)**

Symbol	Parameter	100 MHz Input		Unit
		Minimum	Maximum	
V <sub>IH</sub>	Differential Input High Voltage	+150	-	mV
V <sub>IL</sub>	Differential Input Low Voltage	-	-150	mV
V <sub>CROSS</sub>	Absolute crossing point voltage	+250	+550	mV
T <sub>PERIOD AVG</sub>	Average Clock Period Accuracy	-300	+300	ppm
T <sub>CCJITTER</sub>	Cycle to Cycle Jitter	-	150	ps
T <sub>dc</sub>	Reference Duty Cycle	40	60	%
Rising Edge Rate	Rising Edge Rate	0.6	4.0	V/ns
Falling Edge Rate	Falling Edge Rate	-4.0	-0.6	V/ns

**Table 51. APU\_CLKP/N AC Specifications**

Symbol	Parameter	200/100 MHz Output		Unit
		Minimum	Maximum	
V <sub>OH</sub>	Differential Output High Voltage	+150	-	mV
V <sub>OL</sub>	Differential Output Low Voltage	-	-150	mV
V <sub>CROSS</sub>	Absolute crossing point voltage	+250	+550	mV
V <sub>CROSS DELTA</sub>	Variation of V <sub>CROSS</sub> over all rising clock edges	-	+140	mV
T <sub>PERIOD AVG</sub>	Average Clock Period Accuracy	-300	+300	ppm
Rising Edge Rate	Rising Edge Rate	0.6	4.0	V/ns
Falling Edge Rate	Falling Edge Rate	-4.0	-0.6	V/ns
T <sub>CCJITTER</sub>	Cycle to Cycle jitter	-	150	ps
Duty Cycle	Duty Cycle	40	60	%

Table 52. 14MHz/25MHz/48MHz Auxiliary Clock AC Specifications

Symbol	Parameter	Value			Unit	Note
		Minimum	Typical	Maximum		
14M	14 MHz Clock Frequency	14.2146	14.31818	14.8920	MHz	-
24M	24 MHz Clock Frequency	TBA	24	TBA	MHz	
25M	25 MHz Clock Frequency	24.875	25	25.125	MHz	-
48M	48 MHz Clock Frequency	47.55	48	48.47	MHz	-
50M	50 MHz Clock Frequency	TBA	50	TBA	MHz	-
VOL	Output low voltage	-	-	0.4	V	IOL=4.0 mA when highdrive = 0 IOL = 8.0 mA when highdrive = 1
VOH	Output high voltage	2.4	-	-	V	IOH = -4.0 mA when highdrive = 0 IOH = 8.0 mA when highdrive = 1
Rising Slew Rate	Rising Slew Rate	1.0	-	4.0	V/ns	50pf load
Falling Slew Rate	Falling Slew Rate	1.0	-	4.0	V/ns	50pf load
Tdc	Duty Cycle	40	-	60	%	

**Note:** In integrated clock mode this pin will output 14.318 MHz clock. The output frequency varies from cycle to cycle, with an average frequency of 14.318MHz. This clock is available for customers to use on the system board if it meets the requirements of target device. **AMD has not validated this clock on any specific applications.** Since this clock is averaged at 14.318 MHz, AMD does not recommend this clock to be used for devices that use an Internal PLL. The output will generate 12 MHz on power up until after the FCH PWR\_GOOD is asserted. After the FCH PWR\_GOOD assertion, the clock output will be 14MHz. After power up, this pin can be configured to output a 24-MHz, 25-MHz, 48-MHz, or 50-MHz clock.



**Table 53. PCI Clock AC Specifications**

Symbol	Parameter	Value			Unit	Note
		Minimum	Typical	Maximum		
Tperiod	Clock period	30	-	33.3	MHz	
VOL	Output low voltage	-	-	0.4	V	IOL = 4.0 mA
VOH	Output high voltage	2.4	-	-	V	IOH = -4.0 mA
Rising Slew Rate	Rising Slew Rate	1.0	-	4.0	V/ns	50pf load
Falling Slew Rate	Falling Slew Rate	1.0	-	4.0	V/ns	50pf load

**6.5.3.2 AC Specification of External Reference Clock for 25M\_X1**

**Note:** The specification below applies at the input of the 25M\_X1 pad only, it does not apply to the output of the external clock chip.

**Table 54. AC Specification of External Reference Clock for 25M\_X1**

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
VIH	Input High Level	2.97	--	--	V	1
Vin Max	Maximum Voltage IN		--	3.3	V	2
VIL	Input Low Voltage	0	--	0.33	V	
TIP	25MHZ Clock Period	--	40	--	ns	3
FTOL	Frequency Tolerance	-25	--	25	ppm	
DC	Duty Cycle	45	50	55	%	
TIR	25MHz Slew Rate (Rise)	1	--	--	V/ns	4, 5
TIF	25MHz Slew Rate (Fall)	1	--	--	V/ns	4, 5
TSHORT	Short Term Peak-to-Peak Jitter	--	--	200	ps	3
TIJLT	25MHz Long Term Jitter Requirement (10 $\mu$ s after scope trigger)	--	--	250	ps	

**Table 54. AC Specification of External Reference Clock for 25M\_X1****Notes:**

1. *Minimum voltage required to guarantee a High level detection.*
2. *25M\_X1 input should not exceed Vin Max during normal operation.*
3. *Time intervals measured at 50% threshold point.*
4. *Rise Time and Fall Time measurements should be measured at 10%-90% thresholds.*
5. *For acceptable duty-cycle performance, TIR and TIF should be kept to within 10% of each other.*

### 6.5.3.3 SPI AC Specifications

Figure 24 and Figure 25 show the timing requirements for the SPI ROM controller setup.

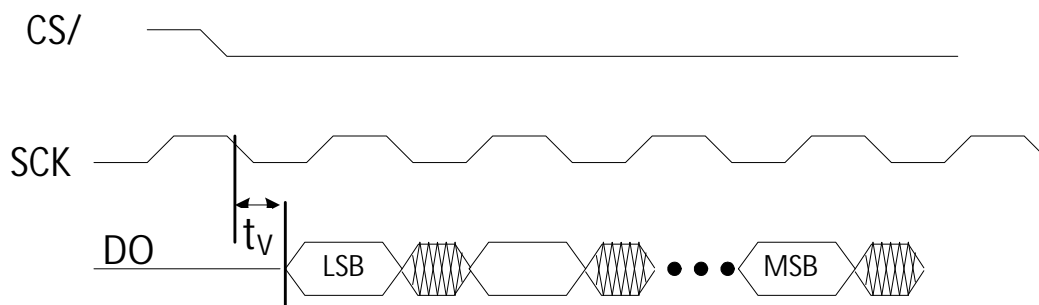


Figure 24. SPI Output Timing Diagram

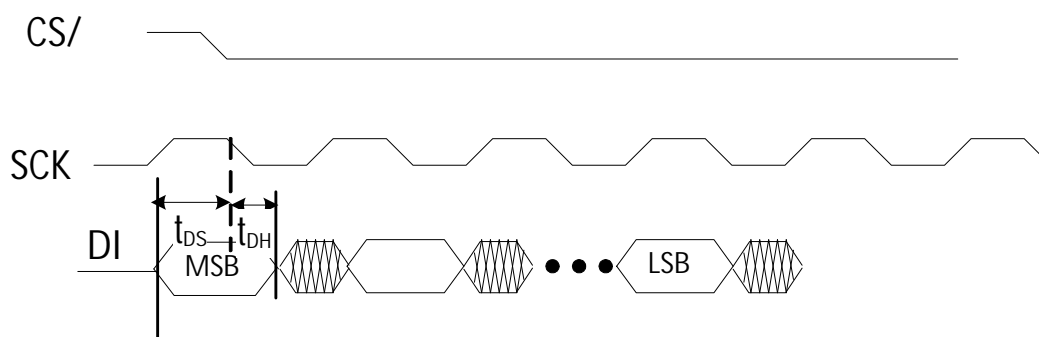


Figure 25. SPI Input Timing Diagram

Table 55. SPI Timing Parameters

Symbol	Parameter	Min	Max	Unit	Note
$t_v$	Output valid time		4	ns	@ output load of 10 pf and timing measured from the falling edge of the clock
$t_{DS}$	Data in setup	5.5		ns	Timing measured from the falling edge of the clock
$t_{DH}$	Data in hold	0		ns	
$t_v$ (quad mode)	Output valid time		6	ns	@ output load of 10 pf and timing measured from the falling edge of the clock
$t_{DS}$ (quad mode)	Data in setup	6		ns	Timing measured from the falling edge of the clock
$t_{DH}$ (quad mode)	Data in hold	0		ns	

**Table 56. SPI Serial Clock Timing (Supported frequencies: 16.5, 22, 33 and 66 MHz)**

	Minimum	Typical	Maximum
Clock Frequency for READ instructions (fR)	16.34 MHz	16.50 MHz	16.67 MHz
Clock High Time (tCLH)	26.1 ns	30.3 ns	34.5 ns
Clock Low Time (tCLL)	26.1 ns	30.3 ns	34.5 ns
Clock Rise Time (tCLCH)	0.10 V/ns		
Clock Fall Time (tCHCL)	0.10 V/ns		
	Minimum	Typical	Maximum
Clock Frequency for READ instructions (fR)	21.78 MHz	22.00 MHz	22.22 MHz
Clock High Time (tCLH)	12.9 ns	15.0 ns	17.1 ns
Clock Low Time (tCLL)	25.8 ns	30.0 ns	34.2 ns
Clock Rise Time (tCLCH)	0.10 V/ns		
Clock Fall Time (tCHCL)	0.10 V/ns		
	Minimum	Typical	Maximum
Clock Frequency for READ instructions (fR)	32.67 MHz	33.00 MHz	33.33 MHz
Clock High Time (tCLH)	13.0 ns	15.2 ns	17.3 ns
Clock Low Time (tCLL)	13.0 ns	15.2 ns	17.3 ns
Clock Rise Time (tCLCH)	0.10 V/ns		
Clock Fall Time (tCHCL)	0.10 V/ns		
	Min	Typical	Max
Clock Frequency for READ instructions (fR)	65.34 MHz	66.00 MHz	66.66 MHz
Clock High Time (tCLH)	6.5 ns	7.6 ns	8.6 ns
Clock Low Time (tCLL)	6.5 ns	7.6 ns	8.6 ns
Clock Rise Time (tCLCH)	0.10 V/ns		
Clock Fall Time (tCHCL)	0.10 V/ns		

# Chapter 7 Package Information

## 7.1 Physical Dimensions

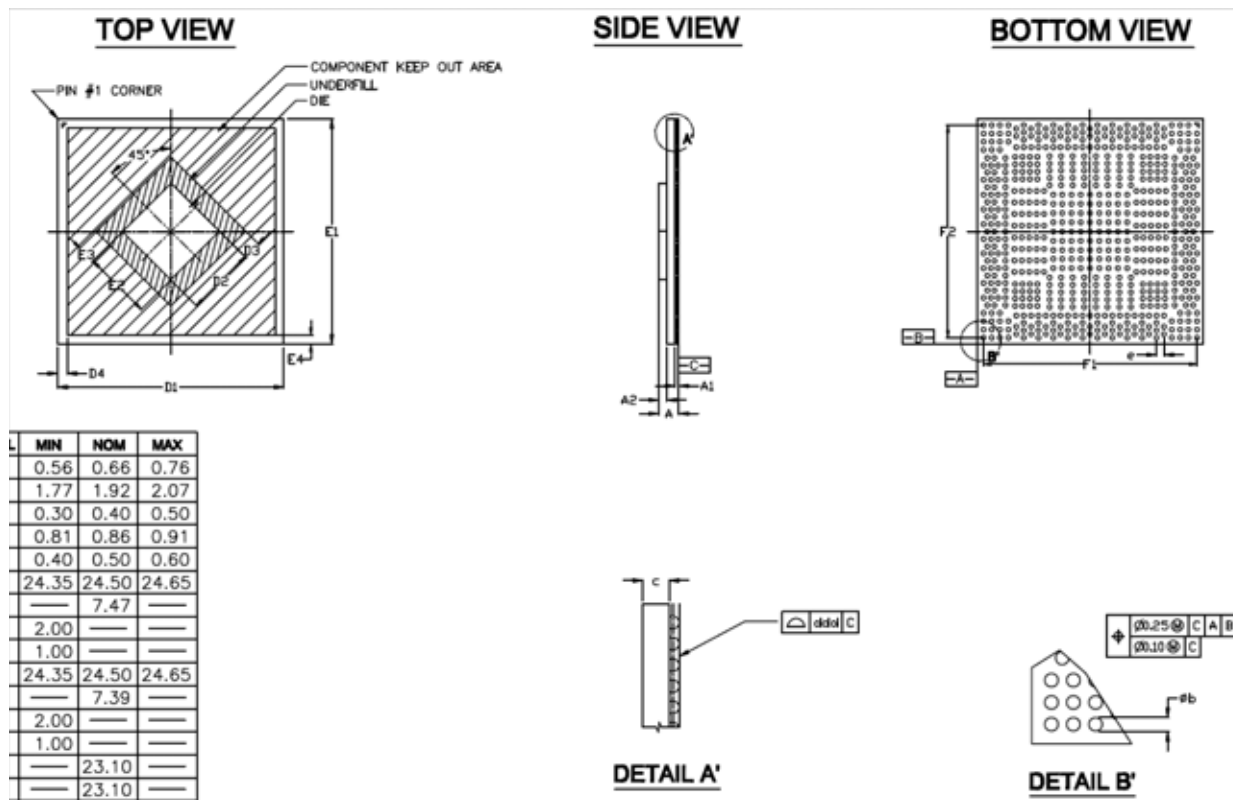


Figure 26. Bolton-E4 24.5 mm x 24.5 mm 0.8 mm Pitch 656-FCBGA Package Outline

Table 57. Bolton-E4 24.5 mm x 24.5 mm 0.8 mm Pitch 656-FCBGA Physical Dimensions

Reference	Minimum (mm)	Nominal (mm)	Maximum (mm)
c	0.56	0.66	0.76
A	1.77	1.92	2.07
A1	0.30	0.40	0.50
A2	0.81	0.86	0.91
$\phi b$	0.40	0.50	0.60
D1	24.35	24.50	24.65

**Table 57. Bolton-E4 24.5 mm x 24.5 mm 0.8 mm Pitch 656-FCBGA Physical Dimensions**

Reference	Minimum (mm)	Nominal (mm)	Maximum (mm)
D2	-	6.84	-
D3	2.00	-	-
D4	1.00	-	-
E1	24.35	24.50	24.65
E2	-	7.20	-
E3	2.00	-	-
E4	1.00	-	-
F1	-	23.10	-
F2	-	23.10	-
e (min. pitch)	-	0.80	-
ddd	-	-	0.20

## 7.2 Pressure Specification

To avoid damages to the ASIC (die or solder ball joint cracks) caused by improper mechanical assembly of the cooling device, follow the recommendations below:

- It is recommended that the maximum load that is evenly applied across the contact area between the thermal management device and the die do not exceed 6 lbf. Note that a total load of 4-6 lbf is adequate to secure the thermal management device and achieve the lowest thermal contact resistance with a temperature drop across the thermal interface material of no more than 3°C. Also, the surface flatness of the metal spreader should be 0.001 inch/1 inch or better.
- Pre-test the assembly fixture with a strain gauge to make sure that the flexing of the final assembled board and the pressure applied around the ASIC package will not exceed 600 micro-strains under any circumstances.
- Ensure that any distortion (bow or twist) of the board after SMT and cooling device assembly is within industry guidelines (IPC/EIA J-STD-001). For measurement method, refer to the industry approved technique described in the manual *IPC-TM-650, section 2.4.22*.

## 7.3 Thermal Information

This section describes some key thermal parameters of Bolton-E4. For a detailed discussion on these parameters and other thermal design descriptions including package level thermal data and analysis, please consult the *Thermal Design and Analysis Guidelines for the Bolton Fusion Controller Hub, order# 51209*.

**Table 58. Bolton-E4 Thermal Limits**

Parameter	Minimum	Nominal	Maximum	Unit	Note
Operating Case Temperature	0	—	105	°C	1
Absolute Rated Junction Temperature	—	—	125	°C	2
Storage Temperature	–40	—	60	°C	
Ambient Temperature	0	—	45	°C	3
Thermal Design Power	—	See Table 59	—	W	4

**Notes:**

1. The maximum operating case temperature is the die geometric top-center temperature measured through proper thermal contact to the back side of the die based on the methodology given in the document *Thermal Design and Analysis Guidelines for the Bolton Fusion Controller Hub, order# 51209*(Chapter 1). This is the temperature at which the functionality of the chip is qualified.
2. The maximum absolute rated junction temperature is the junction temperature at which the device can operate without causing damage to the ASIC.
3. The ambient temperature is defined as the temperature of the local intake air to the thermal management device. The maximum ambient temperature is dependent on the heat sink's local ambient conditions as well as the chassis' external ambient, and the value given here is based on the AMD reference Desktop heat sink solution for the FCH. Refer to Chapter 5 in the *Thermal Design and Analysis Guidelines for the Bolton Fusion Controller Hub, order# 51209*, for heat sink and thermal design guidelines. Refer to Chapter 6 of the above mentioned document for details of ambient conditions.
4. Thermal Design Power (TDP) is defined as the highest power dissipated while running currently available worst case applications at nominal voltages. The core voltage was raised to 5% above its nominal value for measuring the ASIC power. Since the core power of modern ASICs using 65nm and smaller process technology can vary significantly, parts specifically screened for higher core power were used for TDP measurement. The TDP is intended only as a design reference, and the value given here is preliminary.

**Table 59. Bolton-E4 TDP Values and Configurations**

	<b>Bolton-E4</b>
Clock Gen	Y
SATA	8 x 6Gb/s
RAID	not supported
FIS-Based Switching	Y
HD Audio	Y
x1 PCIe GPP	4 Gen 2
Unified Media Interface	X4 Gen 2
USB 3.0 + 2.0 + 1.1 Ports	4 + 10 + 2
APU Fan Control	Y
Consumer IR	Y
SD Controller	Y
VGA DAC	Y
TDP (105 °C)	7.8W



## 7.4 Reflow Profile

A reference reflow profile is given below. Please note the following when using RoHS/lead-free solder (SAC105/305/405 Tin-Silver-Cu):

- The final reflow temperature profile will depend on the type of solder paste and chemistry of flux used in the SMT process. Modifications to the reference reflow profile may be required in order to accommodate the requirements of the other components in the application.
- An oven with 10 heating zones or above is recommended.
- To ensure that the reflow profile meets the target specification on both sides of the board, a different profile and oven recipe for the first and second reflow may be required.
- Mechanical stiffening can be used to minimize board warpage during reflow.
- It is suggested to decrease temperature cooling rate to minimize board warpage.
- This reflow profile applies only to RoHS/lead-free (high temperature) soldering process and it should not be used for eutectic solder packages. Damage may result if this condition is violated.
- Maximum 3 reflows are allowed on the same part.

**Table 60. Recommended Board Solder Reflow Profile - RoHS/Lead-Free Solder**

Profiling Stage	Temperature	Process Range
Overall Preheat	Room temp to 220°C	2 mins to 4 mins
Soaking Time	130°C to 170°C	Typical 60 – 80 seconds
Liquidus	220°C	Typical 60 – 80 seconds
Ramp Rate	Ramp up and Cooling	<2°C / second
Peak	Max. 245°C	235°C ±5 °C
Temperature at peak within 5°C	240°C to 245°C	10 – 30 seconds

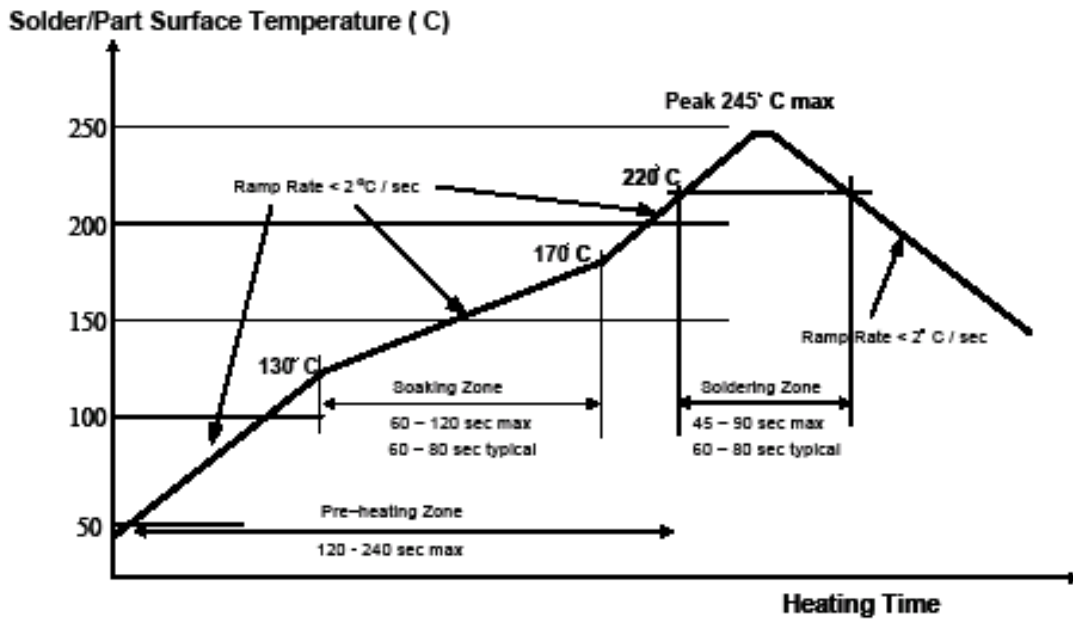


Figure 27. RoHS/Lead-Free Solder (SAC305/405 Tin-Silver-Copper) Reflow Profile

## Chapter 8 Testability

### 8.1 XOR Chain Test Mode

#### 8.1.1 Test Control Signals

Table 61 shows the signals used for the integrated test controller of Bolton-E4.

**Table 61. Signals for the Test Controller of Bolton-E4**

Signal Name	Description
25M_X1, 25M_X2	25-MHz Reference Clock
TEST0	Test0 input
TEST1	Test1 input
TEST2	Test2 input

Table 62 shows how Test[2:0] are used to select the normal operation, ASIC debug, or test mode.

**Table 62. Test Mode Signals**

TEST2	TEST1	TEST0	Test Mode	Description
0	0	0	None	Normal operation
0	0	1	Reserved	Reserved for ASIC debug
0	1	X	Test Mode	EnableTest Mode
1	X	X	Reserved	Reserved for ASIC debug

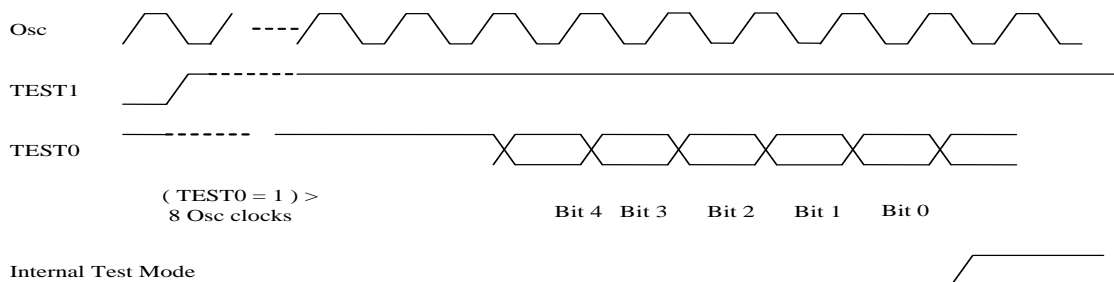
When TEST2 is low, a low on TEST1 will reset all test logic and allow TEST0 to choose between normal operation and the reserved debug mode. A high on TEST1 should be followed by a bit sequence on TEST0 to define the test mode into which Bolton-E4 will enter. A new test mode can be entered when a new bit sequence is transmitted. In addition to resetting the test controller asynchronously with TEST1, a bit sequence can also be used to synchronously change the test mode. Table 63 on page 116 shows the legal bit sequences for TEST0.

**Note:** Once the Test mode or Test mode and sub test mode is entered, Test2 and Test1 should be kept at 0 and 1 respectively until the requirement for the Test Mode is completed.

**Table 63. TEST0 Bit Sequence**

TEST0 bit sequence	Test Mode
11111	Look for first 0 to define a new test mode
00000	Reserved
00001	Alt Pull High Test
00010	Pull Outputs High
00011	Pull Outputs Low
00100	Pull Outputs to Z
00101	XOR Test Mode

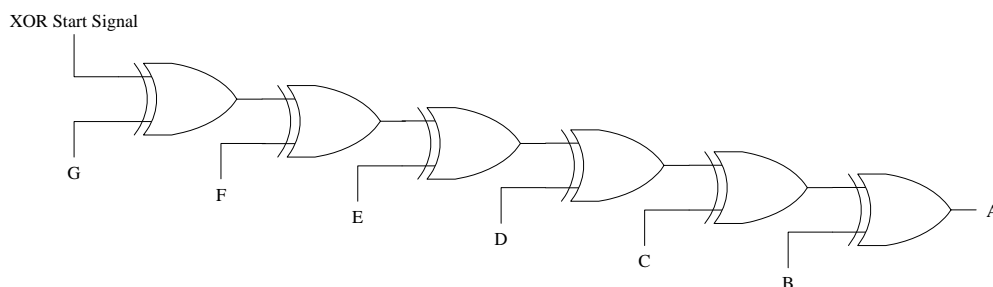
Figure 28 illustrates the data timing for the test signals with respect to the OSC clock. Any timing reference referred in this section is assumed to be based on OSC clock running at 25 MHz. The OSC clock can be slowed down to 1 MHz as long as the bit stream applied on TEST0 pin is also in sync with this clock. The 25-MHz OSC clock should be disconnected first. For setting any Test 0 bit sequence, the OSC clock is required only up-to the time the mode set is completed. After this the clock can be stopped and as long as TEST1 and Test2 pins are set to {1, 0} respectively to maintain the selected mode to be active. Note that once TEST1 is set to one, TEST0 needs to be asserted to one for at least 8 clocks before transmitting the test mode bit sequence. The rising of “Internal Test Mode” in the diagram indicates the time when Huhdson-2 enters into test mode.



**Figure 28. Test Mode Capturing Sequence Timing**

### 8.1.2 Brief Description of an XOR Chain

A sample of a generic XOR chain is shown in the figure below.



**Figure 29. A Generic XOR Chain**

Pin A is assigned to the output direction, and pins B through F are assigned to the input direction. After all pins from B to F are assigned to logic 0 or 1, a logic change in any one of these pins will toggle the output pin A.

Table 64 is the truth table for the XOR tree shown in Figure 29. The XOR start signal is assumed to be logic 1. The start signal is an internal signal to the ASIC and is not part of the XOR tree pins listed in Table 64.

Once the inputs are set to their respective values, the output pin will reflect the correct value within 200ns. Note: OSC clock is not required to be running after the mode is set and the pads are exercised in XOR tree function.

**Table 64. Truth Table for an XOR Chain**

Test Vector Number	Input Pin G	Input Pin F	Input Pin E	Input Pin D	Input Pin C	Input Pin B	Output Pin A
1	0	0	0	0	0	0	1
2	1	0	0	0	0	0	0
3	1	1	0	0	0	0	1
4	1	1	1	0	0	0	0
5	1	1	1	1	0	0	1
6	1	1	1	1	1	0	0
7	1	1	1	1	1	1	1

## 8.2 Description of the Bolton-E4 XOR Chain

During XOR chain test mode, most of the chip pads on Bolton-E4 are connected together using XOR gates as shown in Figure 30. The first input of the chain is connected to a logic level high (internal connection), and all pads (listed in Table 65) are configured as inputs except for the last pad in the chain, which is configured as an output. Table 65 lists all pads that are on the Bolton-E4 XOR chain, as well as and their order of connection. Pads are chained together in the shown order, i.e., pad number 1 is the first pad on the XOR chain, pad number 2 the second, and so on.

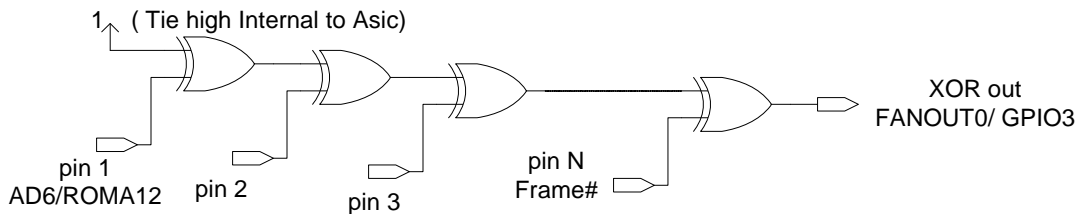


Figure 30. On-chip XOR Chain Connectivity

Table 65. Connection Order of Bolton-E4 XOR Chain Pins

XOR#	Ball Ref	Pin Name
1	A31	LFRAME#
2	C29	ML_VGA_HPD/GPIO229
3	A29	LAD3
4	E28	PROCHOT#
5	C28	LAD1
6	D27	LAD0
7	B27	LDRQ0#
8	G26	LDT_STP#
9	F26	LDT_RST#
10	E26	LDT_PG
11	C26	LPC_SMI#/GEVENT23#
12	A26	LAD2
13	G25	DMA_ACTIVE#
14	D25	LPCCLK1

XOR#	Ball Ref	Pin Name
15	B25	LPCCLK0
16	F24	KSI_3/GPIO204
17	E24	KSI_4/GPIO205
18	C24	KSI_6/GPIO207
19	A24	KSO_16/XDB2/GPIO225
20	D23	PS2M_DAT/GPIO191
21	B23	KSI_5/GPIO206
22	K22	KSI_1/GPIO202
23	J22	EC_PWM2/EC_TIMER2/ WOL_EN/GPIO199
24	H22	EC_PWM1/EC_TIMER1/ GPIO198
25	G22	SCL3_LV/GPIO195
26	F22	KSI_2/GPIO203
27	E22	EC_PWM0/EC_TIMER0/ GPIO197
28	C22	PS2M_CLK/GPIO192

XOR#	Ball Ref	Pin Name
29	A22	KSO_3/GPIO212
30	K21	KSI_0/GPIO201
31	J21	SPI_CS2#/GBE_STAT2/ GPIO166
32	H21	EC_PWM3/EC_TIMER3/ GPIO200
33	G21	SDA3_LV/GPIO196
34	F21	KSO_0/GPIO209
35	D21	PS2KB_DAT/GPIO189
36	B21	KSO_9/GPIO218
37	F20	KSO_2/GPIO211
38	E20	KSO_1/GPIO210
39	C20	PS2KB_CLK/GPIO190
40	A20	KSO_5/GPIO214
41	K19	PS2_DAT/SDA4/GPIO187
42	J19	PS2_CLK/SCL4/GPIO188
43	H19	SCL2/GPIO193
44	G19	SDA2/GPIO194
45	D19	KSO_11/GPIO220
46	B19	KSO_14/XDB0/GPIO223
47	K18	KSO_10/GPIO219
48	J18	KSO_6/GPIO215
49	H18	KSO_7/GPIO216
50	G18	KSO_8/GPIO217
51	F18	KSI_7/GPIO208
52	E18	KSO_4/GPIO213
53	C18	KSO_13/GPIO222
54	A18	KSO_12/GPIO221
55	B17	KSO_15/XDB1/GPIO224
56	D17	KSO_17/XDB3/GPIO226
57	H5	USB_FSD0N
58	H3	USB_FSD1N
59	J4	PWR_BTN#

XOR#	Ball Ref	Pin Name
60	F5	USB_OC3#/AC_PRES/TDO/ GEVENT15#
61	K1	WAKE#/GEVENT8#
62	J2	IR_LED#/LLB#/GPIO184
63	M5	VIN7/GBE_LED3/ GPIO182
64	P3	VIN5/SCLK_1/GPIO180
65	M1	VIN6/GBE_STAT3/GPIO181
66	P1	VIN4/SLOAD_1/GPIO179
67	K6	TEMPIN0/GPIO171
68	K5	TEMPIN1/GPIO172
69	K3	TEMPIN2/GPIO173
70	M6	TEMPIN3/TALERT#/ GPIO174
71	J7	USB_OC1#/TDI/GEVENT13#
72	L2	VIN2/SDATI_1/GPIO177
73	N2	VIN0/GPIO175
74	M3	VIN1/GPIO176
75	N4	VIN3/SDATO_1/GPIO178
76	M7	BLINK/USB_OC7#/ GEVENT18#
77	P5	USB_OC2#/TCK/ GEVENT14#
78	P6	USB_OC4#/IR_RX0/ GEVENT16#
79	R2	RI#/GEVENT22#
80	R7	SDA1/GPIO228
81	R8	USB_OC6#/IR_TX1/ GEVENT6#
82	R9	PME#/GEVENT3#
83	R10	THRMTRIP#/SMBALERT#/ GEVENT2#
84	T1	USB_OC5#/IR_TX0/ GEVENT17#
85	T5	LPC_PD#/GEVENT5#

XOR#	Ball Ref	Pin Name
86	T7	SCL1/GPIO227
87	T8	USB_OC0#/ GEVENT12#/ TRST/SPI_TPM_CS#
88	T6	SPI_CS1#/GPIO165
89	V1	ROM_RST#/SPI_WP#/ GPIO161
90	U4	SYS_RESET#/GEVENT19#
91	V3	SPI_CLK/GPIO162
92	V5	SPI_DO/GPIO163
93	V8	DDR3_RST#/GEVENT7#/ VGA_PD
94	V7	IR_RX1/GEVENT20#
95	V10	GBE_LED2/ GEVENT10#
96	V6	SPI_DI/GPIO164
97	Y6	SPI_HOLD#/ GBE_LED1/GEVENT9#
98	W8	GBE_LED0/GPIO183
99	W9	GBE_PHY_INTR
100	AC2	GBE_PHY_PD
101	W7	SPI_CS3#/GBE_STAT1/ GEVENT21#
102	AA7	GBE_PHY_RST#
103	AA8	GBE_STAT0/GEVENT11#
104	W10	GBE_MDIO
105	AC4	GBE_COL
106	AD1	GBE_RXERR
107	AD3	GBE_CRS
108	AD9	GBE_MDCK
109	AE2	PCIE_RST#
110	AD5	A_RST#
111	AB5	PCIRST#
112	AB6	PCIE_RST2#/GEVENT4#
113	Y1	AZ_SDIN3/GPIO170

XOR#	Ball Ref	Pin Name
114	Y3	AZ_SDIN2/GPIO169
115	Y5	AZ_SDIN1/GPIO168
116	AA2	AZ_SDIN0/GPIO167
117	AB3	AZ_BITCLK
118	AB1	AZ_SDOOUT
119	AE4	AZ_RST#
120	AD6	AZ_SYNC
121	AB7	GBE_TXCLK
122	AB8	GBE_RXCLK
123	AB9	GBE_TXCTL/TXEN
124	AD7	GBE_RXD0
125	AD8	GBE_TXD0
126	AE7	GBE_RXD1
127	AE8	GBE_TXD1
128	AF7	GBE_RXD2
129	AF9	GBE_TXD3
130	AG6	GBE_TXD2
131	AG8	GBE_RXCTL/RXDV
132	AH7	GBE_RXD3
133	AF1	PCICLK1/GPO36
134	AF3	PCICLK0
135	AF5	PCICLK2/GPO37
136	AF6	PCICLK4/14M_OSC/GPO39
137	AG2	PCICLK3/GPO38
138	AL1	AD6/GPIO6
139	AJ1	AD9/GPIO9
140	AH1	STOP#
141	AN3	CBE0#
142	AL3	AD11/GPIO11
143	AJ3	AD0/GPIO0
144	AH3	AD4/GPIO4
145	AG4	AD2/GPIO2
146	AN5	AD7/GPIO7



XOR#	Ball Ref	Pin Name
147	AL5	AD1/GPIO1
148	AJ5	AD5/GPIO5
149	AN6	AD8/GPIO8
150	AL6	AD3/GPIO3
151	AJ6	AD13/GPIO13
152	AM7	AD12/GPIO12
153	AK7	AD14/GPIO14
154	AN8	AD15/GPIO15
155	AL8	AD10/GPIO10
156	AJ8	CBE1#
157	AH8	SERR#
158	AM9	PERR#
159	AK9	DEVSEL#
160	AH9	LOCK#
161	AG9	AD16/GPIO16
162	AN10	CBE2#
163	AL10	IRDY#
164	AJ10	AD18/GPIO18
165	AG10	FRAME#
166	AF10	TRDY#
167	AE10	PAR
168	AM11	AD17/GPIO17
169	AK11	AD20/GPIO20
170	AN12	AD21/GPIO21
171	AL12	AD19/GPIO19
172	AG12	AD22/GPIO22
173	AE12	AD23/GPIO23
174	AE16	AD31/GPIO31
175	AG15	REQ0#
176	AD13	GNT1#/GPO44
177	AD12	CBE3#
178	AC12	AD24/GPIO24
179	AD18	INTH#/GPIO35

XOR#	Ball Ref	Pin Name
180	AD21	GNT2#/SD_LED/GPO45
181	AD16	GNT0#
182	AC16	INTG#/GPIO34
183	AG13	REQ1#/GPIO40
184	AE13	AD25/GPIO25
185	AF13	AD26/GPIO26
186	AH13	AD27/GPIO27
187	AH14	AD28/GPIO28
188	AD15	AD29/GPIO29
189	AC15	AD30/GPIO30
190	AD19	CLKRUN#
191	AF15	REQ2#/CLK_REQ8#/GPIO41
192	AE18	INTF#/GPIO33
193	AF18	INTE#/GPIO32
194	AK17	GNT3#/CLK_REQ7#/ SATA_IS7#/GPIO46
195	AM17	REQ3#/CLK_REQ5#/ SATA_IS6#/GPIO42
196	AL16	FANIN2/GPIO58
197	AN16	FANIN1/GPIO57
198	AJ16	FANOUT2/GPIO54
199	AM15	FANOUT1/GPIO53
200	AH16	FANOUT0/GPIO52
201	AK15	FANIN0/GPIO56
202	AE19	SERIRQ/GPIO48
203	AD22	SATA_ACT#/GPIO67
204	AH17	SATA_IS4#/FANOUT3/ GPIO55
205	AG18	SATA_IS5#/FANIN3/ GPIO59
206	AF25	CLK_REQG#/GPIO65/ OSCIN/IDLEEXIT#
207	AF19	NB_PWRGD
208	AG19	KBRST#/GEVENT1#

XOR#	Ball Ref	Pin Name
209	AE22	GA20IN/GEVENT0#
210	AE24	CLK_REQ3#/SATA_IS1#/ GPIO63
211	AG26	SMARTVOLT2/ SHUTDOWN#/GPIO51
212	AG24	CLK_REQ4#/SATA_IS0#/ GPIO64
213	AD25	SDA0/GPIO47
214	AG25	CLK_REQ2#/FANIN4/ GPIO62
215	AG22	CLK_REQ1#/FANOUT4/ GPIO61
216	AF24	SPKR/GPIO66
217	AD26	SCL0/GPIO43
218	AE26	SMARTVOLT1/SATA_IS2#/ GPIO50
219	AF22	CLK_REQ0#/SATA_IS3#/ GPIO60
220	AE27	LDRQ1#/CLK_REQ6#/ GPIO49
221	AH12	SD_WP/GPIO76
222	AN14	SD_CMD/SLOAD_0/ GPIO74
223	AL14	SD_CLK/SCLK_0/ GPIO73
224	AJ12	SD_CD#/GPIO75
225	AJ14	SD_DATA3/GPIO80
226	AK13	SD_DATA0/SDATI_0/ GPIO77
227	AM13	SD_DATA1/SDATO_0/ GPIO78
228	AH15	SD_DATA2/GPIO79
229	N32	VGA_DDC_SCL/GPO71
230	M33	VGA_DDC_SDA/GPO70
231	M28	VGA_HSYNC/GPO68
232	N30	VGA_VSYNC/GPO69

## 8.2.1 Unused Pins

The pins that are part of the XOR chain (see Table 65 on page 118) but are not used for testing must be pulled up or down before the XOR chain is activated. No pins in the XOR chain should be left floating. All digital or analog pins not included in Table 65 on page 118 are not part of the XOR chain and can be left floating during an XOR test.



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## Appendix A Pin Listing

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This appendix contains pin listings for the Bolton-E4 sorted in two different ways. To go to the listing of interest, click on the linked cross-references below:

- “Pin List by Pin Name” on page 126
- “Pin List by Ball Number” on page 143

## A.1 Pin List by Pin Name

Table A-1 Pin Listing by Pin Name

Pin Name	Ball #
14M_25M_48M_OSC	J26
25M_X1	C31
25M_X2	C33
32K_X1	G2
32K_X2	G4
A_RST#	AD5
AD0/GPIO0	AJ3
AD1/GPIO1	AL5
AD10/GPIO10	AL8
AD11/GPIO11	AL3
AD12/GPIO12	AM7
AD13/GPIO13	AJ6
AD14/GPIO14	AK7
AD15/GPIO15	AN8
AD16/GPIO16	AG9
AD17/GPIO17	AM11
AD18/GPIO18	AJ10
AD19/GPIO19	AL12
AD2/GPIO2	AG4
AD20/GPIO20	AK11
AD21/GPIO21	AN12
AD22/GPIO22	AG12
AD23/GPIO23	AE12
AD24/GPIO24	AC12
AD25/GPIO25	AE13
AD26/GPIO26	AF13
AD27/GPIO27	AH13
AD28/GPIO28	AH14
AD29/GPIO29	AD15
AD3/GPIO3	AL6
AD30/GPIO30	AC15
AD31/GPIO31	AE16
AD4/GPIO4	AH3
AD5/GPIO5	AJ5
AD6/GPIO6	AL1
AD7/GPIO7	AN5
AD8/GPIO8	AN6
AD9/GPIO9	AJ1
APU_CLKN	T23
APU_CLKP	T24
APU_PG	E26

Pin Name	Ball #
APU_RST#	F26
AUX_VGA_CH_N	V29
AUX_VGA_CH_P	V28
AUXCAL	U28
AZ_BITCLK	AB3
AZ_RST#	AE4
AZ_SDIN0/GPIO167	AA2
AZ_SDIN1/GPIO168	Y5
AZ_SDIN2/GPIO169	Y3
AZ_SDIN3/GPIO170	Y1
AZ_SDOUT	AB1
AZ_SYNC	AD6
BLINK/USB_OC7#/ GEVENT18#	M7
CBE0#	AN3
CBE1#	AJ8
CBE2#	AN10
CBE3#	AD12
CLK_CALRN	F27
CLK_REQ0#/ SATA_IS3#/GPIO60	AF22
CLK_REQ1#/ FANOUT4/GPIO61	AG22
CLK_REQ2#/ FANIN4/ GPIO62	AG25
CLK_REQ3#/ SATA_IS1#/GPIO63	AE24
CLK_REQ4#/ SATA_IS0#/GPIO64	AG24
CLK_REQG#/GPIO65/ OSCIN/IDLEEXIT#	AF25
CLKRUN#	AD19
DDR3_RST#/ GEVENT7#/VGA_PD	V8
DEVSEL#	AK9
DISP_CLKN	T26
DISP_CLKP	R26
DISP2_CLKN	H31
DISP2_CLKP	H33
DMA_ACTIVE#	G25
EC_PWM0/ EC_TIMER0/GPIO197	E22
EC_PWM1/ EC_TIMER1/GPIO198	H22
EC_PWM2/ EC_TIMER2/WOL_EN/ GPIO199	J22

Pin Name	Ball #
EC_PWM3/ EC_TIMER3/GPIO200	H21
FANIN0/GPIO56	AK15
FANIN1/GPIO57	AN16
FANIN2/GPIO58	AL16
FANOUT0/GPIO52	AH16
FANOUT1/GPIO53	AM15
FANOUT2/GPIO54	AJ16
FRAME#	AG10
GA20IN/GEVENT0#	AE22
GBE_COL	AC4
GBE_CRS	AD3
GBE_LED0/GPIO183	W8
GBE_LED2/ GEVENT10#	V10
GBE_MDCK	AD9
GBE_MDIO	W10
GBE_PHY_INTR	W9
GBE_PHY_PD	AC2
GBE_PHY_RST#	AA7
GBE_RXCLK	AB8
GBE_RXCTL/RXDV	AG8
GBE_RXD0	AD7
GBE_RXD1	AE7
GBE_RXD2	AF7
GBE_RXD3	AH7
GBE_RXERR	AD1
GBE_STAT0/ GEVENT11#	AA8
GBE_TXCLK	AB7
GBE_TXCTL/TXEN	AB9
GBE_TXD0	AD8
GBE_TXD1	AE8
GBE_TXD2	AG6
GBE_TXD3	AF9
GNT0#	AD16
GNT1#/GPO44	AD13
GNT2#/SD_LED/ GPO45	AD21
GNT3#/CLK_REQ7#/ SATA_IS7#/GPIO46 (Note: SATA_IS7# applies to	AK17
GPP_CLK0N	H28
GPP_CLK0P	H27
GPP_CLK1N	K26
GPP_CLK1P	J27



Pin Name	Ball #
GPP_CLK2N	F31
GPP_CLK2P	F33
GPP_CLK3N	E31
GPP_CLK3P	E33
GPP_CLK4N	M24
GPP_CLK4P	M23
GPP_CLK5N	M26
GPP_CLK5P	M27
GPP_CLK6N	N26
GPP_CLK6P	N25
GPP_CLK7N	R24
GPP_CLK7P	R23
GPP_CLK8N	R27
GPP_CLK8P	N27
GPP_RX0N	AA26
GPP_RX0P	AA27
GPP_RX1N	V27
GPP_RX1P	W27
GPP_RX2N	W26
GPP_RX2P	V26
GPP_RX3N	W23
GPP_RX3P	W24
GPP_TX0N	V31
GPP_TX0P	V33
GPP_TX1N	W32
GPP_TX1P	W30
GPP_TX2N	AB27
GPP_TX2P	AB26
GPP_TX3N	AA23
GPP_TX3P	AA24
INTE#/GPIO32	AF18
INTF#/GPIO33	AE18
INTG#/GPIO34	AC16
INTH#/GPIO35	AD18
INTRUDER_ALERT#	F3
IR_LED#/LLB#/ GPIO184	J2
IR_RX1/GEVENT20#	V7
IRDY#	AL10
KBRST#/GEVENT1#	AG19
KSI_0/GPIO201	K21
KSI_1/GPIO202	K22
KSI_2/GPIO203	F22
KSI_3/GPIO204	F24
KSI_4/GPIO205	E24
KSI_5/GPIO206	B23

Pin Name	Ball #
KSI_6/GPIO207	C24
KSI_7/GPIO208	F18
KSO_0/GPIO209	F21
KSO_1/GPIO210	E20
KSO_10/GPIO219	K18
KSO_11/GPIO220	D19
KSO_12/GPIO221	A18
KSO_13/GPIO222	C18
KSO_14/XDB0/ GPIO223	B19
KSO_15/XDB1/ GPIO224	B17
KSO_16/XDB2/ GPIO225	A24
KSO_17/XDB3/ GPIO226	D17
KSO_2/GPIO211	F20
KSO_3/GPIO212	A22
KSO_4/GPIO213	E18
KSO_5/GPIO214	A20
KSO_6/GPIO215	J18
KSO_7/GPIO216	H18
KSO_8/GPIO217	G18
KSO_9/GPIO218	B21
LAD0	D27
LAD1	C28
LAD2	A26
LAD3	A29
LDO_CAP	M31
LDRQ0#	B27
LDRQ1#/CLK_REQ6#/ GPIO49	AE27
LDT_STP#	G26
LFRAME#	A31
LOCK#	AH9
LPC_PD#/GEVENT5#	T5
LPC_SMI#/ GEVENT23#	C26
LPCCLK0	B25
LPCCLK1	D25
ML_VGA_HPD/ GPIO229	C29
ML_VGA_L0N	T33
ML_VGA_L0P	T31
ML_VGA_L1N	T28
ML_VGA_L1P	T29
ML_VGA_L2N	R30

Pin Name	Ball #
ML_VGA_L2P	R32
ML_VGA_L3N	P28
ML_VGA_L3P	P29
NC1	AG16
NC10	AH33
NC11	AH31
NC12	AJ33
NC13	AJ31
NC2	AH10
NC3	A28
NC4	G27
NC5	L4
NC6	AL29
NC7	AN31
NC8	AL31
NC9	AL33
PAR	AE10
PCICLK0	AF3
PCICLK1/GPO36	AF1
PCICLK2/GPO37	AF5
PCICLK3/GPO38	AG2
PCICLK4/14M_OSC/ GPO39	AF6
PCIE_CALRN	AF31
PCIE_CALRP	AF29
PCIE_RCLKN	G28
PCIE_RCLKP	G30
PCIE_RST#	AE2
PCIE_RST2#/ GEVENT4#	AB6
PCIRST#	AB5
PERR#	AM9
PME#/GEVENT3#	R9
PROCHOT#	E28
PS2_CLK/SCL4/ GPIO188	J19
PS2_DAT/SDA4/ GPIO187	K19
PS2KB_CLK/GPIO190	C20
PS2KB_DAT/GPIO189	D21
PS2M_CLK/GPIO192	C22
PS2M_DAT/GPIO191	D23
PWR_BTN#	J4
PWR_GOOD	N7
REQ0#	AG15
REQ1#/GPIO40	AG13

Pin Name	Ball #
REQ2#/CLK_REQ8#/ GPIO41	AF15
REQ3#/CLK_REQ5#/ SATA_IS6#/GPIO42	AM17
RI#/GEVENT22#	R2
ROM_RST#/SPI_WP#/ GPIO161	V1
RSMRST#	U2
RTCCLK	F1
S5_CORE_EN	H7
SATA_ACT#/GPIO67	AD22
SATA_CALRN	AF27
SATA_CALRP	AF28
SATA_IS4#/FANOUT3/ GPIO55	AH17
SATA_IS5#/FANIN3/ GPIO59	AG18
SATA_RX0N	AL20
SATA_RX0P	AN20
SATA_RX1N	AH20
SATA_RX1P	AJ20
SATA_RX2N	AM23
SATA_RX2P	AK23
SATA_RX3N	AN24
SATA_RX3P	AL24
SATA_RX4N	AJ26
SATA_RX4P	AH26
SATA_RX5N	AK27
SATA_RX5P	AM27
SATA_RX6N	AL31
SATA_RX6P	AL33
SATA_RX7N	AJ33
SATA_RX7P	AJ31
SATA_TX0N	AM19
SATA_TX0P	AK19
SATA_TX1N	AL22
SATA_TX1P	AN22
SATA_TX2N	AH22
SATA_TX2P	AJ22
SATA_TX3N	AJ24
SATA_TX3P	AH24
SATA_TX4N	AN26
SATA_TX4P	AL26
SATA_TX5N	AL28
SATA_TX5P	AN29
SATA_TX6N	AN31
SATA_TX6P	AL29

Pin Name	Ball #
SATA_TX7N	AH31
SATA_TX7P	AH33
SATA_X1	AF21
SATA_X2	AG21
SCL0/GPIO43	AD26
SCL1/GPIO227	T7
SCL2/GPIO193	H19
SCL3_LV/GPIO195	G22
SD_CD#/GPIO75	AJ12
SD_CLK/SCLK_0/ GPIO73	AL14
SD_CMD/SLOAD_0/ GPIO74	AN14
SD_DATA0/SDATI_0/ GPIO77	AK13
SD_DATA1/SDATO_0/ GPIO78	AM13
SD_DATA2/GPIO79	AH15
SD_DATA3/GPIO80	AJ14
SD_WP/GPIO76	AH12
SDA0/GPIO47	AD25
SDA1/GPIO228	R7
SDA2/GPIO194	G19
SDA3_LV/GPIO196	G21
SERIRQ/GPIO48	AE19
SERR#	AH8
SLP_S3#	T3
SLP_S5#	W2
SLT_GFX_CLKN	K29
SLT_GFX_CLKP	J30
SMARTVOLT1/ SATA_IS2#/GPIO50	AE26
SMARTVOLT2/ SHUTDOWN#/GPIO51	AG26
SPI_CLK/GPIO162	V3
SPI_CS1#/GPIO165	T6
SPI_CS2#/ GBE_STAT2/GPIO166	J21
SPI_CS3#/ GBE_STAT1/ GEVENT21#	W7
SPI_DI/GPIO164	V6
SPI_DO/GPIO163	V5
SPI_HOLD#/ GBE_LED1/GEVENT9#	Y6
SPKR/GPIO66	AF24
STOP#	AH1

Pin Name	Ball #
SYS_RESET#/ GEVENT19#	U4
TEMPIN0/GPIO171	K6
TEMPIN1/GPIO172	K5
TEMPIN2/GPIO173	K3
TEMPIN3/TALERT#/ GPIO174	M6
TEST0	T9
TEST1/TMS	T10
TEST2	V9
THRMTRIP#/ SMBALERT#/ GEVENT2#	R10
TRDY#	AF10
UMI_RX0N	AB31
UMI_RX0P	AB33
UMI_RX1N	AB29
UMI_RX1P	AB28
UMI_RX2N	Y31
UMI_RX2P	Y33
UMI_RX3N	Y29
UMI_RX3P	Y28
UMI_TX0N	AE32
UMI_TX0P	AE30
UMI_TX1N	AD31
UMI_TX1P	AD33
UMI_TX2N	AD29
UMI_TX2P	AD28
UMI_TX3N	AC32
UMI_TX3P	AC30
USB_FSD0N	H5
USB_FSD0P/GPIO185	H6
USB_FSD1N	H3
USB_FSD1P/GPIO186	H1
USB_HSD0N	E3
USB_HSD0P	E1
USB_HSD10N	K13
USB_HSD10P	K12
USB_HSD11N	F12
USB_HSD11P	G12
USB_HSD12N	J12
USB_HSD12P	K10
USB_HSD13N	G10
USB_HSD13P	H10
USB_HSD1N	C3
USB_HSD1P	C1

Pin Name	Ball #
USB_HSD2N	A5
USB_HSD2P	C5
USB_HSD3N	A6
USB_HSD3P	C6
USB_HSD4N	E8
USB_HSD4P	F8
USB_HSD5N	C8
USB_HSD5P	A8
USB_HSD6N	G9
USB_HSD6P	H9
USB_HSD7N	A10
USB_HSD7P	C10
USB_HSD8N	F10
USB_HSD8P	E10
USB_HSD9N	D11
USB_HSD9P	B11
USB_OC0#/GEVENT12#/TRST	T8
USB_OC1#/TDI/GEVENT13#	J7
USB_OC2#/TCK/GEVENT14#	P5
USB_OC3#/AC_PRES/TDO/GEVENT15#	F5
USB_OC4#/IR_RX0/GEVENT16#	P6
USB_OC5#/IR_TX0/GEVENT17#	T1
USB_OC6#/IR_TX1/GEVENT6#	R8
USB_RCOMP	B9
USB_SS_RX0N	K15
USB_SS_RX0P	J15
USB_SS_RX1N	G13
USB_SS_RX1P	H13
USB_SS_RX2N	F14
USB_SS_RX2P	E14
USB_SS_RX3N	A12
USB_SS_RX3P	C12
USB_SS_TX0N	H16
USB_SS_TX0P	J16
USB_SS_TX1N	G15
USB_SS_TX1P	F15
USB_SS_TX2N	B15
USB_SS_TX2P	D15
USB_SS_TX3N	C14
USB_SS_TX3P	A14

Pin Name	Ball #
USBCLK/ 14M_25M_48M_OSC	G8
USBSS_CALRN	A16
USBSS_CALRP	C16
VDDAN_11_CLK_1	H26
VDDAN_11_CLK_2	J25
VDDAN_11_CLK_3	K24
VDDAN_11_CLK_4	L22
VDDAN_11_CLK_5	M22
VDDAN_11_CLK_6	N21
VDDAN_11_CLK_7	N22
VDDAN_11_CLK_8	P22
VDDAN_11_ML_1	Y22
VDDAN_11_ML_2	V23
VDDAN_11_ML_3	V24
VDDAN_11_ML_4	V25
VDDAN_11_PCIE_1	AB24
VDDAN_11_PCIE_2	Y21
VDDAN_11_PCIE_3	AE25
VDDAN_11_PCIE_4	AD24
VDDAN_11_PCIE_5	AB23
VDDAN_11_PCIE_6	AA22
VDDAN_11_PCIE_7	AF26
VDDAN_11_PCIE_8	AG27
VDDAN_11_SATA_1	AA21
VDDAN_11_SATA_10	AC19
VDDAN_11_SATA_2	AB21
VDDAN_11_SATA_3	AB22
VDDAN_11_SATA_4	Y20
VDDAN_11_SATA_5	AC22
VDDAN_11_SATA_6	AC21
VDDAN_11_SATA_7	AA20
VDDAN_11_SATA_8	AA18
VDDAN_11_SATA_9	AB20
VDDAN_11_SSUSB_S _1	P16
VDDAN_11_SSUSB_S _2	M14
VDDAN_11_SSUSB_S _3	N14
VDDAN_11_SSUSB_S _4	P13
VDDAN_11_SSUSB_S _5	P14
VDDAN_11_USB_S_1	U12
VDDAN_11_USB_S_2	U13
VDDAN_33_DAC	T22



Pin Name	Ball #
VDDAN_33_HWM_S	M8
VDDAN_33_USB_S_1	G7
VDDAN_33_USB_S_10	M12
VDDAN_33_USB_S_11	N12
VDDAN_33_USB_S_12	M11
VDDAN_33_USB_S_2	H8
VDDAN_33_USB_S_3	J8
VDDAN_33_USB_S_4	K8
VDDAN_33_USB_S_5	K9
VDDAN_33_USB_S_6	M9
VDDAN_33_USB_S_7	M10
VDDAN_33_USB_S_8	N9
VDDAN_33_USB_S_9	N10
VDDBT_RTC_G	E6
VDDCR_11_1	T14
VDDCR_11_2	T17
VDDCR_11_3	T20
VDDCR_11_4	U16
VDDCR_11_5	U18
VDDCR_11_6	V14
VDDCR_11_7	V17
VDDCR_11_8	V20
VDDCR_11_9	Y17
VDDCR_11_GBE_S_1	AB11
VDDCR_11_GBE_S_2	AA11
VDDCR_11_S_1	N20
VDDCR_11_S_2	M20
VDDCR_11_SSUSB_S_1	N16
VDDCR_11_SSUSB_S_2	N17
VDDCR_11_SSUSB_S_3	P17
VDDCR_11_SSUSB_S_4	M17
VDDCR_11_USB_S_1	T12
VDDCR_11_USB_S_2	T13
VDDIO_33_GBE_S	AB10
VDDIO_33_PCIGP_1	AB17
VDDIO_33_PCIGP_10	AB16
VDDIO_33_PCIGP_2	AB18
VDDIO_33_PCIGP_3	AE9
VDDIO_33_PCIGP_4	AD10
VDDIO_33_PCIGP_5	AG7
VDDIO_33_PCIGP_6	AC13
VDDIO_33_PCIGP_7	AB12

Pin Name	Ball #
VDDIO_33_PCIGP_8	AB13
VDDIO_33_PCIGP_9	AB14
VDDIO_33_S_1	N18
VDDIO_33_S_2	L19
VDDIO_33_S_3	M18
VDDIO_33_S_4	V12
VDDIO_33_S_5	V13
VDDIO_33_S_6	Y12
VDDIO_33_S_7	Y13
VDDIO_33_S_8	W11
VDDIO_AZ_S	AA4
VDDIO_GBE_S_1	AA9
VDDIO_GBE_S_2	AA10
VDDPL_11_DAC	V21
VDDPL_11_SYS_S	J24
VDDPL_33_DAC	V22
VDDPL_33_ML	U22
VDDPL_33_PCIE	AH29
VDDPL_33_SATA	AG28
VDDPL_33_SSUSB_S	L18
VDDPL_33_SYS	H24
VDDPL_33_USB_S	D7
VDDXL_33_S	G24
VGA_BLUE	M29
VGA_DAC_RSET	K31
VGA_DDC_SCL/ GPO71	N32
VGA_DDC_SDA/ GPO70	M33
VGA_GREEN	L32
VGA_HSYNC/GPO68	M28
VGA_RED	L30
VGA_VSYNC/GPO69	N30
VIN0/GPIO175	N2
VIN1/GPIO176	M3
VIN2/SDAT1_1/ GPIO177	L2
VIN3/SDATO_1/ GPIO178	N4
VIN4/SLOAD_1/ GPIO179	P1
VIN5/SCLK_1/GPIO180	P3
VIN6/GBE_STAT3/ GPIO181	M1
VIN7/GBE_LED3/ GPIO182	M5
VSS	A3

Pin Name	Ball #
VSS	A33
VSS	AA12
VSS	AA13
VSS	AA14
VSS	AA16
VSS	AA17
VSS	AA25
VSS	AA28
VSS	AA30
VSS	AA32
VSS	AA6
VSS	AB25
VSS	AC18
VSS	AC28
VSS	AC6
VSS	AD27
VSS	AE15
VSS	AE21
VSS	AE28
VSS	AE6
VSS	AF12
VSS	AF16
VSS	AF33
VSS	AF8
VSS	AG30
VSS	AG32
VSS	AH11
VSS	AH18
VSS	AH19
VSS	AH21
VSS	AH23
VSS	AH25
VSS	AH27
VSS	AH5
VSS	AJ18
VSS	AJ28
VSS	AJ29
VSS	AK21
VSS	AK25
VSS	AL18
VSS	AM21
VSS	AM25
VSS	AN1
VSS	AN18
VSS	AN28
VSS	AN33

Pin Name	Ball #
VSS	B13
VSS	B7
VSS	D13
VSS	D9
VSS	E12
VSS	E16
VSS	E29
VSS	E5
VSS	F11
VSS	F13
VSS	F16
VSS	F17
VSS	F19
VSS	F23
VSS	F25
VSS	F29
VSS	F7
VSS	F9
VSS	G16
VSS	G32
VSS	G6
VSS	H12
VSS	H15
VSS	H29
VSS	J10
VSS	J13
VSS	J28
VSS	J32
VSS	J6
VSS	J9
VSS	K16
VSS	K27
VSS	K28
VSS	K7
VSS	L12
VSS	L13
VSS	L15
VSS	L16
VSS	L21
VSS	L6
VSS	M13
VSS	M16
VSS	M21
VSS	M25
VSS	N11
VSS	N13

Pin Name	Ball #
VSS	N23
VSS	N24
VSS	N6
VSS	P12
VSS	P18
VSS	P20
VSS	P21
VSS	P31
VSS	P33
VSS	R11
VSS	R25
VSS	R28
VSS	R4
VSS	R6
VSS	T11
VSS	T16
VSS	T18
VSS	T25
VSS	T27
VSS	U14
VSS	U17
VSS	U20
VSS	U21
VSS	U30
VSS	U32
VSS	U6
VSS	V11
VSS	V16
VSS	V18
VSS	W25
VSS	W28
VSS	W4
VSS	W6
VSS	Y14
VSS	Y16
VSS	Y18
VSSAN_DAC	L28
VSSAN_HWM	N8
VSSANQ_DAC	K33
VSSIO_DAC	N28
VSSPL_DAC	T21
VSSPL_SYS	H25
VSSXL	K25
WAKE#/GEVENT8#	K1
WD_PWRGD	AF19



## A.2 Pin List by Ball Number

Table A-2 Pin List by Ball Number

Ball #	Pin Name
A10	USB_HSD7N
A12	USB_SS_RX3N
A14	USB_SS_TX3P
A16	USBSS_CALRN
A18	KSO_12/GPIO221
A20	KSO_5/GPIO214
A22	KSO_3/GPIO212
A24	KSO_16/XDB2/ GPIO225
A26	LAD2
A28	NC3
A29	LAD3
A3	VSS
A31	LFRAME#
A33	VSS
A5	USB_HSD2N
A6	USB_HSD3N
A8	USB_HSD5P
AA10	VDDIO_GBE_S_2
AA11	VDDCR_11_GBE_S_2
AA12	VSS
AA13	VSS
AA14	VSS
AA16	VSS
AA17	VSS
AA18	VDDAN_11_SATA_8
AA2	AZ_SDIN0/GPIO167
AA20	VDDAN_11_SATA_7
AA21	VDDAN_11_SATA_1
AA22	VDDAN_11_PCIE_6
AA23	GPP_TX3N
AA24	GPP_TX3P
AA25	VSS
AA26	GPP_RX0N
AA27	GPP_RX0P
AA28	VSS
AA30	VSS
AA32	VSS
AA4	VDDIO_AZ_S
AA6	VSS
AA7	GBE_PHY_RST#

Ball #	Pin Name
AA8	GBE_STAT0/ GEVENT11#
AA9	VDDIO_GBE_S_1
AB1	AZ_SDOOUT
AB10	VDDIO_33_GBE_S
AB11	VDDCR_11_GBE_S_1
AB12	VDDIO_33_PCIGP_7
AB13	VDDIO_33_PCIGP_8
AB14	VDDIO_33_PCIGP_9
AB16	VDDIO_33_PCIGP_10
AB17	VDDIO_33_PCIGP_1
AB18	VDDIO_33_PCIGP_2
AB20	VDDAN_11_SATA_9
AB21	VDDAN_11_SATA_2
AB22	VDDAN_11_SATA_3
AB23	VDDAN_11_PCIE_5
AB24	VDDAN_11_PCIE_1
AB25	VSS
AB26	GPP_TX2P
AB27	GPP_TX2N
AB28	UMI_RX1P
AB29	UMI_RX1N
AB3	AZ_BITCLK
AB31	UMI_RX0N
AB33	UMI_RX0P
AB5	PCIRST#
AB6	PCIE_RST2#/ GEVENT4#
AB7	GBE_TXCLK
AB8	GBE_RXCLK
AB9	GBE_TXCTL/TXEN
AC12	AD24/GPIO24
AC13	VDDIO_33_PCIGP_6
AC15	AD30/GPIO30
AC16	INTG#/GPIO34
AC18	VSS
AC19	VDDAN_11_SATA_10
AC2	GBE_PHY_PD
AC21	VDDAN_11_SATA_6
AC22	VDDAN_11_SATA_5
AC28	VSS
AC30	UMI_TX3P
AC32	UMI_TX3N
AC4	GBE_COL
AC6	VSS
AD1	GBE_RXERR



Ball #	Pin Name
AD10	VDDIO_33_PCIGP_4
AD12	CBE3#
AD13	GNT1#/GPO44
AD15	AD29/GPIO29
AD16	GNT0#
AD18	INTH#/GPIO35
AD19	CLKRUN#
AD21	GNT2#/SD_LED/ GPO45
AD22	SATA_ACT#/GPIO67
AD24	VDDAN_11_PCIE_4
AD25	SDA0/GPIO47
AD26	SCL0/GPIO43
AD27	VSS
AD28	UMI_TX2P
AD29	UMI_TX2N
AD3	GBE_CRS
AD31	UMI_TX1N
AD33	UMI_TX1P
AD5	A_RST#
AD6	AZ_SYNC
AD7	GBE_RXD0
AD8	GBE_TXD0
AD9	GBE_MDCK
AE10	PAR
AE12	AD23/GPIO23
AE13	AD25/GPIO25
AE15	VSS
AE16	AD31/GPIO31
AE18	INTF#/GPIO33
AE19	SERIRQ/GPIO48
AE2	PCIE_RST#
AE21	VSS
AE22	GA20IN/GEVENT0#
AE24	CLK_REQ3#/ SATA_IS1#/GPIO63
AE25	VDDAN_11_PCIE_3
AE26	SMARTVOLT1/ SATA_IS2#/GPIO50
AE27	LDRQ1#/CLK_REQ6#/ GPIO49
AE28	VSS
AE30	UMI_TX0P
AE32	UMI_TX0N
AE4	AZ_RST#
AE6	VSS

Ball #	Pin Name
AE7	GBE_RXD1
AE8	GBE_TXD1
AE9	VDDIO_33_PCIGP_3
AF1	PCICLK1/GPO36
AF10	TRDY#
AF12	VSS
AF13	AD26/GPIO26
AF15	REQ2#/CLK_REQ8#/ GPIO41
AF16	VSS
AF18	INTE#/GPIO32
AF19	WD_PWRGD
AF21	SATA_X1
AF22	CLK_REQ0#/ SATA_IS3#/GPIO60
AF24	SPKR/GPIO66
AF25	CLK_REQG#/GPIO65/ OSCIN/IDLEEXIT#
AF26	VDDAN_11_PCIE_7
AF27	SATA_CALRN
AF28	SATA_CALRP
AF29	PCIE_CALRP
AF3	PCICLK0
AF31	PCIE_CALRN
AF33	VSS
AF5	PCICLK2/GPO37
AF6	PCICLK4/14M_OSC/ GPO39
AF7	GBE_RXD2
AF8	VSS
AF9	GBE_TXD3
AG10	FRAME#
AG12	AD22/GPIO22
AG13	REQ1#/GPIO40
AG15	REQ0#
AG16	NC1
AG18	SATA_IS5#/FANIN3/ GPIO59
AG19	KBRST#/GEVENT1#
AG2	PCICLK3/GPO38
AG21	SATA_X2
AG22	CLK_REQ1#/ FANOUT4/GPIO61
AG24	CLK_REQ4#/ SATA_IS0#/GPIO64
AG25	CLK_REQ2#/FANIN4/ GPIO62

Ball #	Pin Name
AG26	SMARTVOLT2/ SHUTDOWN#/GPIO51
AG27	VDDAN_11_PCIE_8
AG28	VDDPL_33_SATA
AG30	VSS
AG32	VSS
AG4	AD2/GPIO2
AG6	GBE_TXD2
AG7	VDDIO_33_PCIGP_5
AG8	GBE_RXCTL/RXDV
AG9	AD16/GPIO16
AH1	STOP#
AH10	NC2
AH11	VSS
AH12	SD_WP/GPIO76
AH13	AD27/GPIO27
AH14	AD28/GPIO28
AH15	SD_DATA2/GPIO79
AH16	FANOUT0/GPIO52
AH17	SATA_IS4#/FANOUT3/ GPIO55
AH18	VSS
AH19	VSS
AH20	SATA_RX1N
AH21	VSS
AH22	SATA_TX2N
AH23	VSS
AH24	SATA_TX3P
AH25	VSS
AH26	SATA_RX4P
AH27	VSS
AH29	VDDPL_33_PCIE
AH3	AD4/GPIO4
AH31	NC11 (D3 only)
AH31	SATA_TX7N
AH33	NC10 (D3 only)
AH33	SATA_TX7P
AH5	VSS
AH7	GBE_RXD3
AH8	SERR#
AH9	LOCK#
AJ1	AD9/GPIO9
AJ10	AD18/GPIO18
AJ12	SD_CD#/GPIO75
AJ14	SD_DATA3/GPIO80
AJ16	FANOUT2/GPIO54

Ball #	Pin Name
AJ18	VSS
AJ20	SATA_RX1P
AJ22	SATA_TX2P
AJ24	SATA_TX3N
AJ26	SATA_RX4N
AJ28	VSS
AJ29	VSS
AJ3	AD0/GPIO0
AJ31	NC13 (D3 only)
AJ31	SATA_RX7P
AJ33	NC12 (D3 only)
AJ33	SATA_RX7N
AJ5	AD5/GPIO5
AJ6	AD13/GPIO13
AJ8	CBE1#
AK11	AD20/GPIO20
AK13	SD_DATA0/SDATI_0/ GPIO77
AK15	FANIN0/GPIO56
AK17	GNT3#/CLK_REQ7#/ SATA_IS7#/GPIO46 (Note: SATA_IS7# applies to
AK19	SATA_TX0P
AK21	VSS
AK23	SATA_RX2P
AK25	VSS
AK27	SATA_RX5N
AK7	AD14/GPIO14
AK9	DEVSEL#
AL1	AD6/GPIO6
AL10	IRDY#
AL12	AD19/GPIO19
AL14	SD_CLK/SCLK_0/ GPIO73
AL16	FANIN2/GPIO58
AL18	VSS
AL20	SATA_RX0N
AL22	SATA_TX1N
AL24	SATA_RX3P
AL26	SATA_TX4P
AL28	SATA_TX5N
AL29	NC6 (D3 only)
AL29	SATA_TX6P
AL3	AD11/GPIO11
AL31	NC8 (D3 only)
AL31	SATA_RX6N

Ball #	Pin Name
AL33	NC9 (D3 only)
AL33	SATA_RX6P (
AL5	AD1/GPIO1
AL6	AD3/GPIO3
AL8	AD10/GPIO10
AM11	AD17/GPIO17
AM13	SD_DATA1/SDATO_0/ GPIO78
AM15	FANOUT1/GPIO53
AM17	REQ3#/CLK_REQ5#/ SATA_IS6#/GPIO42
AM19	SATA_TX0N
AM21	VSS
AM23	SATA_RX2N
AM25	VSS
AM27	SATA_RX5P
AM7	AD12/GPIO12
AM9	PERR#
AN1	VSS
AN10	CBE2#
AN12	AD21/GPIO21
AN14	SD_CMD/SLOAD_0/ GPIO74
AN16	FANIN1/GPIO57
AN18	VSS
AN20	SATA_RX0P
AN22	SATA_TX1P
AN24	SATA_RX3N
AN26	SATA_TX4N
AN28	VSS
AN29	SATA_TX5P
AN3	CBE0#
AN31	NC7 (D3 only)
AN31	SATA_TX6N
AN33	VSS
AN5	AD7/GPIO7
AN6	AD8/GPIO8
AN8	AD15/GPIO15
B11	USB_HSD9P
B13	VSS
B15	USB_SS_TX2N
B17	KSO_15/XDB1/ GPIO224
B19	KSO_14/XDB0/ GPIO223
B21	KSO_9/GPIO218

Ball #	Pin Name
B23	KSI_5/GPIO206
B25	LPCCLK0
B27	LDRQ0#
B7	VSS
B9	USB_RCOMP
C1	USB_HSD1P
C10	USB_HSD7P
C12	USB_SS_RX3P
C14	USB_SS_TX3N
C16	USBSS_CALRP
C18	KSO_13/GPIO222
C20	PS2KB_CLK/GPIO190
C22	PS2M_CLK/GPIO192
C24	KSI_6/GPIO207
C26	LPC_SMI#/ GEVENT23#
C28	LAD1
C29	ML_VGA_HPD/ GPIO229
C3	USB_HSD1N
C31	25M_X1
C33	25M_X2
C5	USB_HSD2P
C6	USB_HSD3P
C8	USB_HSD5N
D11	USB_HSD9N
D13	VSS
D15	USB_SS_TX2P
D17	KSO_17/XDB3/ GPIO226
D19	KSO_11/GPIO220
D21	PS2KB_DAT/GPIO189
D23	PS2M_DAT/GPIO191
D25	LPCCLK1
D27	LAD0
D7	VDDPL_33_USB_S
D9	VSS
E1	USB_HSD0P
E10	USB_HSD8P
E12	VSS
E14	USB_SS_RX2P
E16	VSS
E18	KSO_4/GPIO213
E20	KSO_1/GPIO210
E22	EC_PWM0/ EC_TIMER0/GPIO197

Ball #	Pin Name
E24	KSI_4/GPIO205
E26	APU_PG
E28	PROCHOT#
E29	VSS
E3	USB_HSD0N
E31	GPP_CLK3N
E33	GPP_CLK3P
E5	VSS
E6	VDDBT_RTC_G
E8	USB_HSD4N
F1	RTCCLK
F10	USB_HSD8N
F11	VSS
F12	USB_HSD11N
F13	VSS
F14	USB_SS_RX2N
F15	USB_SS_TX1P
F16	VSS
F17	VSS
F18	KSI_7/GPIO208
F19	VSS
F20	KSO_2/GPIO211
F21	KSO_0/GPIO209
F22	KSI_2/GPIO203
F23	VSS
F24	KSI_3/GPIO204
F25	VSS
F26	APU_RST#
F27	CLK_CALRN
F29	VSS
F3	INTRUDER_ALERT#
F31	GPP_CLK2N
F33	GPP_CLK2P
F5	USB_OC3#/AC Pres/ TDO/GEVENT15#
F7	VSS
F8	USB_HSD4P
F9	VSS
G10	USB_HSD13N
G12	USB_HSD11P
G13	USB_SS_RX1N
G15	USB_SS_TX1N
G16	VSS
G18	KSO_8/GPIO217
G19	SDA2/GPIO194
G2	32K_X1

Ball #	Pin Name
G21	SDA3_LV/GPIO196
G22	SCL3_LV/GPIO195
G24	VDDXL_33_S
G25	DMA_ACTIVE#
G26	LDT_STP#
G27	NC4
G28	PCIE_RCLKN
G30	PCIE_RCLKP
G32	VSS
G4	32K_X2
G6	VSS
G7	VDDAN_33_USB_S_1
G8	USBCLK/ 14M_25M_48M_OSC
G9	USB_HSD6N
H1	USB_FSD1P/GPIO186
H10	USB_HSD13P
H12	VSS
H13	USB_SS_RX1P
H15	VSS
H16	USB_SS_TX0N
H18	KSO_7/GPIO216
H19	SCL2/GPIO193
H21	EC_PWM3/ EC_TIMER3/GPIO200
H22	EC_PWM1/ EC_TIMER1/GPIO198
H24	VDDPL_33_SYS
H25	VSSPL_SYS
H26	VDDAN_11_CLK_1
H27	GPP_CLK0P
H28	GPP_CLK0N
H29	VSS
H3	USB_FSD1N
H31	DISP2_CLKN
H33	DISP2_CLKP
H5	USB_FSD0N
H6	USB_FSD0P/GPIO185
H7	S5_CORE_EN
H8	VDDAN_33_USB_S_2
H9	USB_HSD6P
J10	VSS
J12	USB_HSD12N
J13	VSS
J15	USB_SS_RX0P
J16	USB_SS_TX0P



Ball #	Pin Name
J18	KSO_6/GPIO215
J19	PS2_CLK/SCL4/ GPIO188
J2	IR_LED#/LLB#/ GPIO184
J21	SPI_CS2#/ GBE_STAT2/GPIO166
J22	EC_PWM2/ EC_TIMER2/WOL_EN/ GPIO199
J24	VDDPL_11_SYS_S
J25	VDDAN_11_CLK_2
J26	14M_25M_48M_OSC
J27	GPP_CLK1P
J28	VSS
J30	SLT_GFX_CLKP
J32	VSS
J4	PWR_BTN#
J6	VSS
J7	USB_OC1#/TDI/ GEVENT13#
J8	VDDAN_33_USB_S_3
J9	VSS
K1	WAKE#/GEVENT8#
K10	USB_HSD12P
K12	USB_HSD10P
K13	USB_HSD10N
K15	USB_SS_RX0N
K16	VSS
K18	KSO_10/GPIO219
K19	PS2_DAT/SDA4/ GPIO187
K21	KSI_0/GPIO201
K22	KSI_1/GPIO202
K24	VDDAN_11_CLK_3
K25	VSSXL
K26	GPP_CLK1N
K27	VSS
K28	VSS
K29	SLT_GFX_CLKN
K3	TEMPIN2/GPIO173
K31	VGA_DAC_RSET
K33	VSSANQ_DAC
K5	TEMPIN1/GPIO172
K6	TEMPIN0/GPIO171
K7	VSS
K8	VDDAN_33_USB_S_4

Ball #	Pin Name
K9	VDDAN_33_USB_S_5
L12	VSS
L13	VSS
L15	VSS
L16	VSS
L18	VDDPL_33_SSUSB_S
L19	VDDIO_33_S_2
L2	VIN2/SDATI_1/ GPIO177
L21	VSS
L22	VDDAN_11_CLK_4
L28	VSSAN_DAC
L30	VGA_RED
L32	VGA_GREEN
L4	NC5
L6	VSS
M1	VIN6/GBE_STAT3/ GPIO181
M10	VDDAN_33_USB_S_7
M11	VDDAN_33_USB_S_12
M12	VDDAN_33_USB_S_10
M13	VSS
M14	VDDAN_11_SSUSB_S _2
M16	VSS
M17	VDDCR_11_SSUSB_S _4
M18	VDDIO_33_S_3
M20	VDDCR_11_S_2
M21	VSS
M22	VDDAN_11_CLK_5
M23	GPP_CLK4P
M24	GPP_CLK4N
M25	VSS
M26	GPP_CLK5N
M27	GPP_CLK5P
M28	VGA_HSYNC/GPO68
M29	VGA_BLUE
M3	VIN1/GPIO176
M31	LDO_CAP
M33	VGA_DDC_SDA/ GPO70
M5	VIN7/GBE_LED3/ GPIO182
M6	TEMPIN3/TALERT#/ GPIO174

Ball #	Pin Name
M7	BLINK/USB_OC7#/ GEVENT18#
M8	VDDAN_33_HWM_S
M9	VDDAN_33_USB_S_6
N10	VDDAN_33_USB_S_9
N11	VSS
N12	VDDAN_33_USB_S_11
N13	VSS
N14	VDDAN_11_SSUSB_S _3
N16	VDDCR_11_SSUSB_S _1
N17	VDDCR_11_SSUSB_S _2
N18	VDDIO_33_S_1
N2	VIN0/GPIO175
N20	VDDCR_11_S_1
N21	VDDAN_11_CLK_6
N22	VDDAN_11_CLK_7
N23	VSS
N24	VSS
N25	GPP_CLK6P
N26	GPP_CLK6N
N27	GPP_CLK8P
N28	VSSIO_DAC
N30	VGA_VSYNC/GPO69
N32	VGA_DDC_SCL/ GPO71
N4	VIN3/SDATO_1/ GPIO178
N6	VSS
N7	PWR_GOOD
N8	VSSAN_HWM
N9	VDDAN_33_USB_S_8
P1	VIN4/SLOAD_1/ GPIO179
P12	VSS
P13	VDDAN_11_SSUSB_S _4
P14	VDDAN_11_SSUSB_S _5
P16	VDDAN_11_SSUSB_S _1
P17	VDDCR_11_SSUSB_S _3
P18	VSS
P20	VSS

Ball #	Pin Name
P21	VSS
P22	VDDAN_11_CLK_8
P28	ML_VGA_L3N
P29	ML_VGA_L3P
P3	VIN5/SCLK_1/GPIO180
P31	VSS
P33	VSS
P5	USB_OC2#/TCK/ GEVENT14#
P6	USB_OC4#/IR_RX0/ GEVENT16#
R10	THRMTRIP#/ SMBALERT#/ GEVENT2#
R11	VSS
R2	RI#/GEVENT22#
R23	GPP_CLK7P
R24	GPP_CLK7N
R25	VSS
R26	DISP_CLKP
R27	GPP_CLK8N
R28	VSS
R30	ML_VGA_L2N
R32	ML_VGA_L2P
R4	VSS
R6	VSS
R7	SDA1/GPIO228
R8	USB_OC6#/IR_TX1/ GEVENT6#
R9	PME#/GEVENT3#
T1	USB_OC5#/IR_TX0/ GEVENT17#
T10	TEST1/TMS
T11	VSS
T12	VDDCR_11_USB_S_1
T13	VDDCR_11_USB_S_2
T14	VDDCR_11_1
T16	VSS
T17	VDDCR_11_2
T18	VSS
T20	VDDCR_11_3
T21	VSSPL_DAC
T22	VDDAN_33_DAC
T23	APU_CLKN
T24	APU_CLKP
T25	VSS
T26	DISP_CLKN

Ball #	Pin Name
T27	VSS
T28	ML_VGA_L1N
T29	ML_VGA_L1P
T3	SLP_S3#
T31	ML_VGA_L0P
T33	ML_VGA_L0N
T5	LPC_PD#/GEVENT5#
T6	SPI_CS1#/GPIO165
T7	SCL1/GPIO227
T8	USB_OC0#/ GEVENT12#/TRST
T9	TEST0
U12	VDDAN_11_USB_S_1
U13	VDDAN_11_USB_S_2
U14	VSS
U16	VDDCR_11_4
U17	VSS
U18	VDDCR_11_5
U2	RSMRST#
U20	VSS
U21	VSS
U22	VDDPL_33_ML
U28	AUXCAL
U30	VSS
U32	VSS
U4	SYS_RESET#/ GEVENT19#
U6	VSS
V1	ROM_RST#/SPI_WP#/ GPIO161
V10	GBE_LED2/ GEVENT10#
V11	VSS
V12	VDDIO_33_S_4
V13	VDDIO_33_S_5
V14	VDDCR_11_6
V16	VSS
V17	VDDCR_11_7
V18	VSS
V20	VDDCR_11_8
V21	VDDPL_11_DAC
V22	VDDPL_33_DAC
V23	VDDAN_11_ML_2
V24	VDDAN_11_ML_3
V25	VDDAN_11_ML_4
V26	GPP_RX2P

Ball #	Pin Name
V27	GPP_RX1N
V28	AUX_VGA_CH_P
V29	AUX_VGA_CH_N
V3	SPI_CLK/GPIO162
V31	GPP_TX0N
V33	GPP_TX0P
V5	SPI_DO/GPIO163
V6	SPI_DI/GPIO164
V7	IR_RX1/GEVENT20#
V8	DDR3_RST#/ GEVENT7#/VGA_PD
V9	TEST2
W10	GBE_MDIO
W11	VDDIO_33_S_8
W2	SLP_S5#
W23	GPP_RX3N
W24	GPP_RX3P
W25	VSS
W26	GPP_RX2N
W27	GPP_RX1P
W28	VSS
W30	GPP_TX1P
W32	GPP_TX1N
W4	VSS
W6	VSS
W7	SPI_CS3#/ GBE_STAT1/ GEVENT21#
W8	GBE_LED0/GPIO183
W9	GBE_PHY_INTR
Y1	AZ_SDIN3/GPIO170
Y12	VDDIO_33_S_6
Y13	VDDIO_33_S_7
Y14	VSS
Y16	VSS
Y17	VDDCR_11_9
Y18	VSS
Y20	VDDAN_11_SATA_4
Y21	VDDAN_11_PCIE_2
Y22	VDDAN_11_ML_1
Y28	UMI_RX3P
Y29	UMI_RX3N
Y3	AZ_SDIN2/GPIO169
Y31	UMI_RX2N
Y33	UMI_RX2P
Y5	AZ_SDIN1/GPIO168

Ball #	Pin Name
Y6	SPI_HOLD#/ GBE_LED1/GEVENT9#

